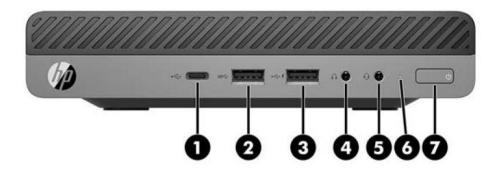
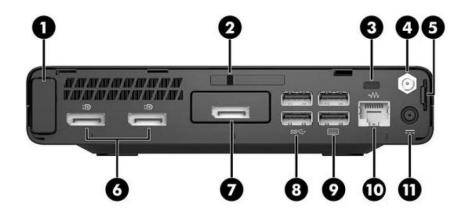
HP ProDesk 600 G3 Desktop Mini Business PC



- 1. USB Type-C[™] charging port
- 2. USB 3.1 Gen 1 port
- 3. USB 3.1 Gen 1 charging port
- 4. Universal Audio Jack with CTIA headset support

- 5. Headset Connector
- 6. Hard drive activity light
- 7. Dual-state power button

HP ProDesk 600 G3 Desktop Mini Business PC



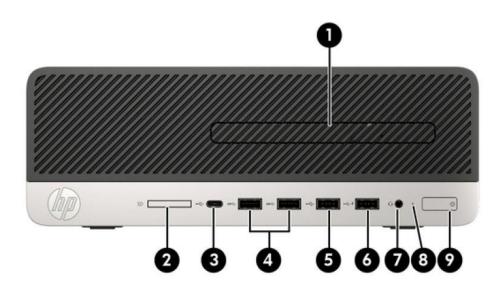
- 1. Antenna cover
- 2. Cover lock switch
- 3. Cable lock slot
- 4. External antenna connector
- 5. Padlock loop
- 6. (2) Dual-Mode DisplayPort™ (DP++)

- 7. Choice of port (DisplayPort™, HDMI, VGA, Serial or USB-CTM) (USB-CTM option has alt mode DisplayPort™ or 15W output)
- 8. (2) USB 3.1 Gen 1 (black)
- (2) USB 3.1 Gen 1 (black), allows for wake from S4/S5 with keyboard/mouse when connected and enabled in BIOS
- 10. RJ-45 Network connector
- 11. Power connector

Not Shown

- Slots (1) internal M.2 PCIe 2230 connector for optional wireless NIC
 - (1) internal M.2 SSD storage (2230 or 2280 connector)
- Bays (1) 2.5" internal storage drive bay
- VESA Support for VESA 100 mounting system on bottom of PC chassis

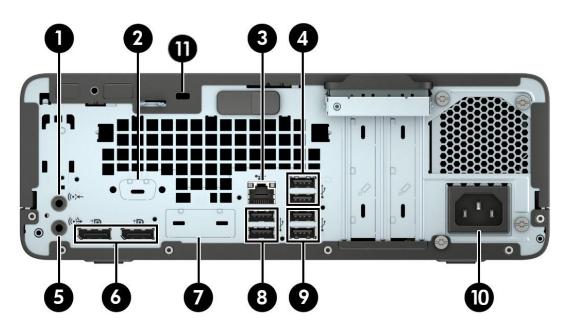
HP ProDesk 600 G3 Small Form Factor Business PC



- 1. Slim Optical Drive (optional)
- 2. SD card 4.0 reader (optional)
- 3. USB Type-C[™] charging port
- 4. (2) USB 3.1 Gen1 x ports
- 5. USB 2.0 port

- 6. USB 2.0 (fast charging port)
- 7. Universal Audio Jack with CTIA headset support
- 8. Hard drive activity light
- 9. Power button

HP ProDesk 600 G3 Small Form Factor Business PC



- 1. Audio-in connector
- 2. Optional serial port available
- 3. RJ-45 (network) jack
- 4. (2) USB 2.0 ports on non-vPro™ SKUs
 (2) USB 3.1 Gen1 x ports on vPro™ SKUs
- 5. Audio-out connector for powered audio devices
- 6. (2) Dual-Mode DisplayPort™ (DP++)

- 7. Optional port (DisplayPort™, HDMI, VGA, or USB-C™) (USB-C™ option has alt mode DisplayPort™ or 15W output)
- 8. (2) USB 2.0 ports with wake from S4/S5 feature
- 9. (2) USB 3.1 Gen1 x ports
- 10. Power cord connector
- 11. Cable lock slot

NOTE: The serial port is no longer standard to the chassis but is available as an option. A second serial port and PS/2 port PCIe combination are available.

Not Shown

Slots (2) PCI Express x16 graphics connectors; one wired as an x4

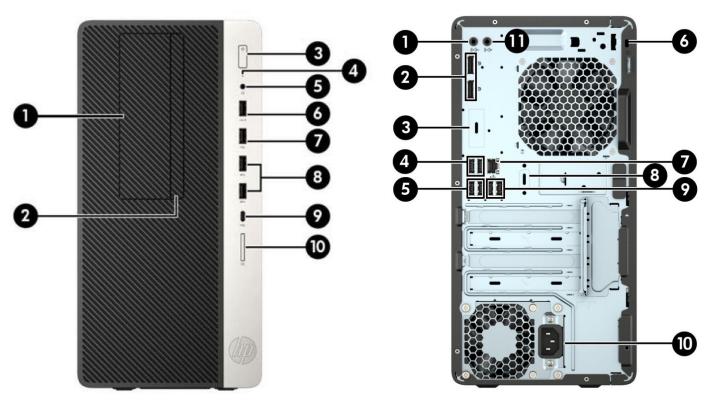
- (1) internal M.2 PCIe x1 connector for optional wireless NIC
- (1) internal M.2 PCIe x4 connector for optional Turbo Drive SSD

Bays (1) 3.5" internal storage drive bay or 2.5" internal storage drive bay (2.5" drive needs adapter)

(1) 9.5mm slim optical drive bay

Overview

HP ProDesk 600 G3 and 680 G3 Microtower Business PC



- 1. 5.25-inch drive bay (behind bezel)
- 2. Slim optical drive (optional)
- 3. Dual-state power button
- 4. Hard drive activity light
- 5. Universal Audio Jack with CTIA headset support
- 6. USB 2.0 (fast charging port*)
- 7. USB 2.0 port
- 8. (2) USB 3.1 Gen1 x ports
- 9. USB Type-C charging port
- 10. SD card 4.0 reader (optional)

- 1. Audio-in connector
- 2. Dual-Mode DisplayPort™ (DP++) (2)
- 3. Optional port (DisplayPort™, HDMI, VGA, or USB-CTM) (USB-CTM option has alt mode DisplayPort™ or 15W output)
- 4. (2) USB 2.0 Ports with Wake from S4/S5 feature
- 5. (2) USB 3.1 Gen1 x ports
- 6. Cable lock slot
- 7. RJ-45 (network) jack
- 8. Optional serial port available
- 9. (2) USB 2.0 ports on non-vPro[™] SKUs
 (2) USB 3.1 Gen1 x ports on vPro[™] SKUs
- 10. Power cord connector
- 11. Audio-out connector for powered audio devices

NOTE: When a device is plugged into the headset jack, a dialog box will open asking if you want to use the connector for a microphone line-in device or a headphone. You can reconfigure the connector at any time by double-clicking the Audio Manager icon in the Windows® taskbar.

The serial port is no longer standard to the chassis but is available as an option. A second serial port and PS/2 port PCIe combination are available.



^{*}This port connects a USB device, provides high-speed data transfer, and even when the computer is off, charges products such as a cell phone, camera, activity tracker, or smartwatch.

Overview

Not Shown

Slots (2) PCI Express x16 graphics connectors; one wired as an x4

- (1) PCI Express x1 accessory connector
- (1) PCI Express x1 accessory connector or PCI x1 accessory connector
- (1) internal M.2 PCIe x1 connector for optional wireless NIC
- (1) internal M.2 PCIe x4 connector for optional Turbo Drive SSD

NOTE: Select models will offer (1) PCI Express x1 accessory connector and (1) PCI connector instead of (2) PCI Express x1 accessory connectors

NOTE: Maximum total of 4 PCI slots supported on MT.

Bays (1) 5.25" internal half-height drive bay or (2) 2.5" internal storage drive bays

- (1) 3.5" internal storage drive bays
- (1) 9.5mm internal optical drive bay



Overview

AT A GLANCE

- Choice of four form factors: Desktop Mini, Small Form Factor, Microtower and All-in-One Non-Touch only (AiO available 2H 2017)
- New commercial design on Desktop Mini, Small Form Factor, Microtower
- HP developed- and engineered UEFI BIOS supporting security, manageability and software image stability
- Intel® Q270 chipset supporting both Intel® 7 Generation and Intel® 6th generation Core™ processors, featuring integrated Intel® HD Graphics and optional Intel® vPro™ Technology (available with Core i5 and Core i7 processors)
- Processor support up to 65W (MT/SFF), 35W (DM)
- Support for Windows 10 to Windows 7 Downgrade with Intel® 6th Generation processors
- Intel® Ethernet Connection I219LM GbE LOM integrated network connection
- DDR4 Synchronous Dynamic Random Access Memory (SDRAM)
- Support for up to three monitors via two standard DisplayPort™ connectors and an optional third video port connector which provides the following choices: HDMI, VGA (except AiO models), DisplayPort™, or USB Type-C™ with DisplayPort™ (see Ports section or pages 1-8 for port availability by platform).
- Configurable 3rd rear I/O video port (HDMI, DisplayPort™, VGA, Type-C with DisplayPort™)
- HP BIOSphere Gen3
- HP Manageability Integration Kit
- HP WorkWise
- Standard and high efficiency energy saving power supply options
- ENERGY STAR® certified. EPEAT® Gold registered where applicable/supported. Registration may vary by country. See www.epeat.net for registration status by country.
- CCC, CECP & SEPA Certified
- PC chassis and all internal components and modules are manufactured with low halogen content³
- Arsenic-free
- Dust filter available for Desktop Mini, Small Form Factor, Microtower
- Protected by HP Services, including limited warranties up to 3-3-3 (terms and conditions vary by country; certain restrictions
 and exclusions apply); Care Packs available with up to 5 years Next Business Day Onsite Hardware Support
- Lengthy purchase lifecycles and image stability

NOTE: See important legal disclosures for all listed specs in their respective features sections.

- Multi-Core is designed to improve performance of certain software products. Not all customers or software applications will
 necessarily benefit from use of this technology. 64-bit computing system required. Performance and clock frequency will vary
 depending on application workload and your hardware and software configurations. Intel's numbering is not a measurement of
 higher performance.
- 2. DisplayPort™ multi-stream monitors 'daisy-chained' together.
- 3. External power supplies, power cords, cables and peripherals are not low halogen. Service parts obtained after purchase may not be low halogen.



Standard Features and Configurable Components

OPERATING SYSTEMS

Preinstalled

Windows 10 Pro 641

Windows 10 Pro 64 (National Academic License)3

Windows 10 Home 641

Windows 10 Home Single Language 641

Windows 7 Professional 64 (available through downgrade rights from Windows 10 Pro)^{2, 4} Windows 7 Professional 32 (available through downgrade rights from Windows 10 Pro)^{2, 4}

Pre-installed (other)

FreeDOS 2.0 NeoKylin Linux® 64

Web-supported only

Windows 10 Enterprise 64¹ Windows 7 Enterprise 64⁴

- 1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.
- 2. This system is preinstalled with Windows 7 Pro software and also comes with a license and media for Windows 10 Pro software. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version. You must back up all data (files, photos, etc.) before uninstalling and installing operating systems to avoid loss of your data.
- 3. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see https://aka.ms/ProEducation for Windows 10 Pro Education feature information.
- 4. Only available with 6th generation (Intel) processors.

CHIPSET

Intel® Q270

PROCESSORS*, **

*NOTE: Your product does not support Windows 8 or Windows 7, In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows® 8 or Windows 7 drivers on http://www.support.hp.com

**Note: Multi-Core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. 64-bit computing system required. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering is not a measurement of higher performance.

Intel® 7th Generation Core™ i7 Processors	<u>DM</u>	<u>SFF</u>	<u>MT</u>
Intel® Core™ i7-7700 Processor		X	X
65W			
Up to 4.2 GHz Max. Turbo Frequency (3.6 GHz base frequency)			
8 MB cache, 4 cores, 8 threads			
Intel® HD Graphics 630			
Supports DDR4 memory up to 2400 MT/s data rate			
Supports Intel® vPro™ Technology and Intel® Stable Image			
Platform Program (SIPP)			



Intel® Core™ i7-7700T Processor	Х	
35W		
Up to 3.8 GHz Max. Turbo Frequency (2.9 GHz base frequency)		
8 MB cache, 4 cores, 8 threads		
Intel® HD Graphics 630		
Supports DDR4 memory up to 2400 MT/s data rate		
Supports Intel® vPro™Technology and Intel® Stable Image		
Platform Program (SIPP)		

Intel® 7th Generation Core™ i5 Processors	<u>DM</u>	<u>SFF</u>	<u>MT</u>
Intel® Core™ i5-7500 Processor		X	X
65W			
Up to 3.8 GHz Max. Turbo Frequency (3.4 GHz base frequency)			
6 MB cache, 4 cores, 4 threads			
Intel® HD Graphics 630			
Supports DDR4 memory up to 2500 MT/s data rate			
Supports Intel® vPro TM Technology and Intel® Stable Image Platform Program (SIPP)			
3	V		
Intel® Core™ i5-7500T Processor	X		
Up to 3.3 CHz Max. Turbo Fraguency (3.7 CHz bace fraguency)			
Up to 3.3 GHz Max. Turbo Frequency (2.7 GHz base frequency) 6 MB cache, 4 cores, 4 threads			
Intel® HD Graphics 630			
Supports DDR4 memory up to 2400 MT/s data rate			
Supports Intel® vPro™ Technology and Intel® Stable Image			
Platform Program (SIPP)			
Intel® Core™ i5-7600 Processor		Х	Х
65W			
Up to 4.1 GHz Max. Turbo Frequency (3.5 GHz base frequency)			
6 MB cache, 4 cores, 4 threads			
Intel® HD Graphics 630			
Supports DDR4 memory up to 2400 MT/s data rate			
Supports Intel® vPro™ Technology and Intel® Stable Image			
Platform Program (SIPP)			
Intel® Core™ i5-7600T Processor	X		
35W			
Up to 3.7 GHz Max. Turbo Frequency (2.8 GHz base frequency)			
6 MB cache, 4 cores, 4 threads			
Intel® HD Graphics 630			
Supports DDR4 memory up to 2400 MT/s data rate			
Supports Intel® vPro™ Technology and Intel® Stable Image Platform Program (SIPP)			
riativiiii rivyiaiii (Sirr)			

Intel® 7th Generation Core™ i3 Processors	<u>DM</u>	<u>SFF</u>	<u>MT</u>
Intel® Core™ i3-7100 Processor		Х	X
51W			
3.9 GHz base frequency			
3 MB cache, 2 cores, 4 threads			
Intel® HD Graphics 630			
Supports DDR4 memory up to 2400 MT/s data rate			
Intel® Core™ i3-7100T Processor	X		
35W			
3.4 GHz base frequency			



3 MB cache, 2 cores, 4 threads			
Intel® HD Graphics 630			
Supports DDR4 memory up to 2400 MT/s data rate			
Intel® Core™ i3-7300 Processor		X	X
51W			
4.0 GHz base frequency			
4 MB cache, 2 cores, 4 threads			
Intel® HD Graphics 630			
Supports DDR4 memory up to 2400 MT/s data rate			
Intel® Core™ i3-7300T Processor	Х		
35W			
3.5 GHz base frequency			
3 MB cache, 2 cores, 4 threads			
Intel® HD Graphics 630			
Supports DDR4 memory up to 2400 MT/s data rate			
Intel® Core™ i3-7320 Processor		Х	Х
51W			
4.1GHz base frequency			
4 MB cache, 2 cores, 4 threads			
Intel® HD Graphics 630			
Supports DDR4 memory up to 2400 MT/s data rate			

Intel® 7th Generation Pentium® Processors	<u>DM</u>	<u>SFF</u>	<u>MT</u>
Intel® Pentium® G4560 Processor		X	X
54W			
3.5 GHz Base Frequency			
3 MB cache, 2 cores, 4 threads			
Intel® HD Graphics 610			
Supports DDR4 memory up to 2400 MT/s data rate			
Intel® Pentium® G4560T Processor	X		
35W			
2.9 GHz Base Frequency			
3 MB cache, 2 cores, 4 threads			
Intel® HD Graphics 610			
Supports DDR4 memory up to 2400 MT/s data rate			
Intel® Pentium® G4600 Processor		X	X
51W			
3.6 GHz Base Frequency			
3 MB cache, 2 cores, 4 threads			
Intel® HD Graphics 610			
Supports DDR4 memory up to 2400 MT/s data rate			
Intel® Pentium® G4600T Processor	X		
35W			
3.0 GHz Base Frequency			
3 MB cache, 2 cores, 4 threads			
Intel® HD Graphics 610			
Supports DDR4 memory up to 2400 MT/s data rate			
Intel® Pentium® G4620 Processor		X	X
51W			
3.7 GHz Base Frequency			
3 MB cache, 2 cores, 4 threads			
Intel® HD Graphics 610			
Supports DDR4 memory up to 2400 MT/s data rate			



Intel® 7th Generation Celeron® Processors	<u>DM</u>	<u>SFF</u>	<u>MT</u>
Intel® Celeron ® G3930 Processor		Х	Х
51W			
2.9 GHz Base Frequency			
2 MB cache, 2 cores, 2 threads			
Intel® HD Graphics 610			
Supports DDR4 memory up to 2133 MT/s data rate			
Intel® Celeron® G3930T Processor	X		
35W			
2.7 GHz Base Frequency			
2 MB cache, 2 cores, 2 threads			
Intel® HD Graphics 610			
Supports DDR4 memory up to 2133 MT/s data rate			
Intel® Celeron ® G3950 Processor		X	X
51W			
3.0 GHz Base Frequency			
2 MB cache, 2 cores, 2 threads			
Intel® HD Graphics 610			
Supports DDR4 memory up to 2133 MT/s data rate			
Intel® 6th Generation Core™ i7 Processors	<u>DM</u>	<u>SFF</u>	MT

Intel® 6th Generation Core™ i7 Processors	<u>DM</u>	<u>SFF</u>	<u>MT</u>
Intel® Core™ i7-6700 Processor		X	Х
65W			
Up to 4.0 GHz Max. Turbo Frequency (3.4 GHz base frequency)			
8 MB cache, 4 cores, 8 threads			
Intel® HD Graphics 530			
Supports DDR4 memory up to 2133 MT/s data rate			
Supports Intel® vPro™ Technology and Intel® Stable Image			
Platform Program (SIPP)			
Intel® Core™ i7-6700T Processor	X		
35W			
Up to 3.6 GHz Max. Turbo Frequency (2.8 GHz base frequency)			
8 MB cache, 4 cores, 8 threads			
Intel® HD Graphics 530			
Supports DDR4 memory up to 2133 MT/s data rate			
Supports Intel® vPro™ Technology and Intel® Stable Image			
Platform Program (SIPP)			

Intel® 6th Generation Core™ i5 Processors	<u>DM</u>	<u>SFF</u>	<u>MT</u>
Intel® Core™ i5-6500 Processor		X	Х
65W			
Up to 3.6 GHz Max. Turbo Frequency (3.2 GHz base frequency)			
6 MB cache, 4 cores, 4 threads			
Intel® HD Graphics 530			
Supports DDR4 memory up to 2133 MT/s data rate			
Supports Intel® vPro™ Technology and Intel® Stable Image			
Platform Program (SIPP)			
Intel® Core™ i5-6600T Processor	Х		
35W			
Up to 3.5 GHz Max. Turbo Frequency (2.7 GHz base frequency)			
6 MB cache, 4 cores, 4 threads			
Intel® HD Graphics 530			
Supports DDR4 memory up to 2133 MT/s data rate			



Supports Intel® vPro™ Technology and Intel® Stable Image Platform Program (SIPP)			
Intel® Core™ i5-6600 Processor 65W Up to 3.9 GHz Max. Turbo Frequency (3.3 GHz base frequency) 6 MB cache, 4 cores, 4 threads Intel® HD Graphics 530 Supports DDR4 memory up to 2133 MT/s data rate Supports Intel® vPro™ Technology and Intel® Stable Image Platform Program (SIPP)		X	х
Intel® Core™ i5-6500T Processor 35W Up to 3.1 GHz Max. Turbo Frequency (2.5 GHz base frequency) 6 MB cache, 4 cores, 4 threads Intel® HD Graphics 530 Supports DDR4 memory up to 2133 MT/s data rate Supports Intel® vPro™ Technology and Intel® Stable Image Platform Program (SIPP)	X		

Intel® 6th Generation Core™ i3 Processors	<u>DM</u>	<u>SFF</u>	<u>MT</u>
Intel® Core™ i3-6100 Processor		X	X
51W			
3.7 GHz base frequency			
3 MB cache, 2 cores, 4 threads			
Intel® HD Graphics 530			
Supports DDR4 memory up to 2133 MT/s data rate			
<u>Intel® Core™ i3-6100T Processor</u>	X		
35W			
3.2 GHz base frequency			
3 MB cache, 2 cores, 4 threads			
Intel® HD Graphics 530			
Supports DDR4 memory up to 2133 MT/s data rate			

Intel® 6th Generation Celeron® Processors	<u>DM</u>	<u>SFF</u>	<u>MT</u>
Intel® Celeron® G4400 Processor			X
54W			
3.3 GHz Base Frequency			
3 MB cache, 2 cores, 2 threads			
Intel® HD Graphics 510			
Supports DDR4 memory up to 2133 MT/s data rate			

Standard Features and Configurable Components

MEMORY*

Form Factor	Туре	Maximum	Number of Slots
Desktop Mini	DDR4-2400 (Transfer rates up to 2400 MT/s)	32 GB	2 SODIMM
Small Form Factor	DDR4-2400 (Transfer rates up to 2400 MT/s)	64 GB	4 DIMM
Microtower	DDR4-2400 (Transfer rates up to 2400 MT/s)	64 GB	4 DIMM

Memory modules available. Memory options vary by platform. All slots are customer accessible / upgradeable.

- 2,048 MB (2048 MB x 1) (AMO only)
- 4,096 MB (4096 MB x 1)
- 8,192 MB (8192 MB x 1)
- 16,384 MB (16,384 MB x 1)

Memory modules support data transfer rates up to 2400 MT/s; actual data rate is determined by the system's configured processor. See processor specifications for supported memory data rate.

STORAGE*

2.5 inch 7.2k RPM Hard Disk Drives	<u>DM</u>	<u>SFF</u>	<u>MT</u>
1TB SATA	Х	Х	Х
500GB SATA	Х	Х	Х
3.5" SATA 7.2k RPM Hard Disk Drives	<u>DM</u>	<u>SFF</u>	<u>MT</u>
500GB 7200RPM 3.5in		X	Х
1TB 7200RPM 3.5in		Х	Х
2TB 7200RPM 3.5in		Х	Х
2.5 inch Solid State Hybrid Drives (SSHD)	<u>DM</u>	<u>SFF</u>	<u>MT</u>
1TB 5400RPM 2.5in 8GB Hybrid	Х	Х	Х
500GB 5400RPM 2.5in 8GB Hybrid	Х	Х	Х
3.5 inch Solid State Hybrid Drives (SSHD)	<u>DM</u>	<u>SFF</u>	<u>MT</u>
1TB 7200RPM 3.5in SSHD (SSHD)		Х	Х
2.5 inch Self-encrypting Drives (SED HDD)	<u>DM</u>	<u>SFF</u>	<u>MT</u>
500GB 5400RPM 2.5in Federal Information Processing Standard (FIPS) SED	Х	Х	Х
500GB 7200RPM 2.5in SED 0PAL2	Х	Х	Х



^{*} Full availability of 4 GB or more of memory requires a 64-bit operating system. With Windows 32-bit operating systems, the amount of usable memory is dependent upon your configuration, so that above 3 GB all memory may not be available due to system resource requirements.

2.5 inch Self-encrypting Drives (SED SSD)	<u>DM</u>	<u>SFF</u>	<u>MT</u>
256GB TLC SED SSD Opal 2 Drive	X	Х	Х
512GB TLC SED SSD Opal 2 Drive	Х	Х	Х
256GB TLC SED SSD 2.5in Federal Information Processing Standard (FIPS) SED	Х	Х	Х
512GB TLC SED SSD 2.5in Federal Information Processing Standard (FIPS) SED	Х	Х	Х

PCIe NMVe SSD Drives	<u>DM</u>	<u>SFF</u>	<u>MT</u>
HP 256GB Turbo Drive G2 PCIe TLC SSD Drive	Х	Х	Х
HP 512GB Turbo Drive G2 PCIe TLC SSD Drive	Х	Х	Х
HP 1TB Turbo Drive G2 PCIe TLC SSD Drive	Х	Х	Х

2.5 SATA SSD Drives	<u>DM</u>	<u>SFF</u>	<u>MT</u>
HP SATA 128GB SSD Drive	Х	Х	Х
HP SATA 256GB SSD Drive	Х	Х	Х

^{*}For storage drives, GB = 1 billion bytes, TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30GB of system disk is reserved for system recovery software.

Optical Disc Drives	<u>DM</u>	<u>SFF</u>	<u>MT</u>
HP 9.5mm G3 800/600 Tower DVD-Writer*			Х
HP 9.5mm G3 800/600 Tower DVD-ROM			Х
HP 9.5mm G3 800/600/400 SFF G4 400 Microtower DVD-Writer*		Х	
HP 9.5mm G3 800/600/400 SFF G4 400 Microtower DVD-ROM		Х	

^{*}HD-DVD discs cannot be played on this drive. No support for DVD-RAM. Actual speeds may vary. Don't copy copyright-protected materials. Double Layer discs can store more data than single layer discs. Discs burned with this drive may not be compatible with many existing single-layer DVD drives and players.

Removable	<u>DM</u>	<u>SFF</u>	<u>MT</u>
HP 9.5mm Slim Removable SATA 500GB		Х	Х
HP 3.5" Removable SATA HDD Frame/Carrier			Х

Media Card Reader (optional)*	<u>DM</u>	<u>SFF</u>	<u>MT</u>
SD4 with 5-in-1 Interface from SD option to PCA is USB		Х	Х
(Supports SD, SDXC, SDHC, UHS-I, UHS-II)			

^{*}Card sold separately



Standard Features and Configurable Components

GRAPHICS

System Integrated Graphics	<u>DM</u>	<u>SFF</u>	<u>MT</u>
Intel® HD Graphics 530 (integrated on 6th gen Core i7/i5/i3 processors)	Х	Х	Х
Intel® HD Graphics 630 (integrated on 7^{th} gen Core i7/i5/i3 processors and Pentium G4620, 4600, 4600T)	Х	Х	Х
Intel® HD Graphics 610 (integrated on Pentium G4560, G4560T, Celeron G3950, G3930, G3930T)	Х	Х	Х

Optional Discrete Graphics Solutions

(optional and RX 460 devices and GT 730 1GB HDMI card, they must

be configured at purchase)	<u>DM</u>	<u>SFF</u>	<u>MT</u>
AMD Radeon™ R7 450 4GB FH PCIe x16*			Х
AMD Radeon™ RX 460 2GB FH PCIe x16*			Х
NVIDIA® GeForce® GT 730 1GB PCIe x8 HDMI		Х	Х
NVIDIA® GeForce® GT 730 2GB PCIe x8 DP		Х	Х

^{*}Requires 250W chassis

2 nd Graphics Cards	<u>DM</u>	<u>SFF</u>	<u>MT</u>
AMD Radeon™ R7 450 4GB FH PCIe x16 G5 2 ^{nd**}			Х
NVIDIA® GeForce® GT 730 1GB PCIe x8 HDMI 2 ^{nd***}			Х
NVIDIA® GeForce® GT 730 2GB PCIe x8 DP 2nd****			Х

^{**}Available only with AMD Radeon™ R7 450.

AUDIO/MULTIMEDIA

	<u>DM</u>	<u>SFF</u>	<u>MT</u>
Conexant CX20632 Audio Codec	Х	Х	Х
Headset* front connector (3.5mm)	Х	X	Х
Headphone front connector (3.5mm)	Х		
Line-out rear connector* (3.5mm)		X	Х
Line-in rear connector* (3.5mm)		X	Х
Multi-streaming capable*	Х	X	Х
Internal speaker (standard)	Х	Χ	Х

^{*} The DM, SFF, MT front headset connector supports CTIA style headsets. Headset connectors are retaskable to function as a Line-In, Microphone-In, Line-out or Headphone-out port. Rear audio input ports are re-taskable as a Line-in or Microphone-in port. External speakers must be powered externally. Multi-streaming can be enabled in the audio control panel to allow independent audio streams to be sent to/from the front and rear jacks. This allows for different audio applications to use separate audio ports on the system. For example, the front jacks could be used with a headset for a communications application while the rear jacks are being used with external speakers and a multimedia application.



^{***}Available only with NVIDIA® GeForce® GT730 1GB.

^{****}Available only with NVIDIA® GeForce® GT730 2GB.

Standard Features and Configurable Components

NETWORKING/COMMUNICATIONS*

Ethernet (RJ-45) Integrated	<u>DM</u>	<u>SFF</u>	<u>MT</u>
Intel® I219LM Gigabit Network Connection LOM (standard	Х	Х	Х
Ethernet (RJ-45) Optional	<u>DM</u>	<u>SFF</u>	<u>MT</u>
Intel® Ethernet I210-T1 PCIe x1 Gb Network Interface Card (optional)		Х	Х
Wireless LAN (optional and all except for 7265 for SFF/MT must be bought at purchase) Intel® 8265 802.11AC 2x2 Wi-Fi +Bluetooth® M.2 Combo Card vPro™ (802.11AC Wave 2 supported)		SFF X	<u>мт</u> Х
Intel® 8265 802.11AC 2x2 Wi-Fi +Bluetooth® M.2 Combo Card non-vPro™ (802.11AC Wave 2 supported)	Х	Х	Х
Intel® 7265 802.11AC 2x2 Wi-Fi +Bluetooth® M.2 Combo Card non-vPro™	Х	Х	Х
Intel® 7260 802.11 a,b,g,n 2x2 M.2 Bluetooth® Disabled NIC**	Х		
Intel® 3168 802.11AC 2x2 Wi-Fi +Bluetooth® M.2 Combo Card non-vPro™	Х	Х	Х

^{*} Wireless access point and Internet service required and not included. Availability of public wireless access points limited.

SLOTS

	<u>DM</u>	<u>SFF</u>	<u>MT</u>
Turbo Drive (M.2 PCIe)	1 ea. M.2 PCIe x1-2230 (for WLAN) 1 ea. M.2 PCIe x4-2280/2230 (for storage)	1 ea. M.2 PCIe x1-2230 (for WLAN) 1 ea. M.2 PCIe x4-2280 (for storage)	1 ea. M.2 PCIe x1-2230 (for WLAN) 1 ea. M.2 PCIe x4-2280 (for storage)
PCI Express x1 (v3.0)	N/A	N/A	2 ea.* (1 optional)) 4.2" full height 6.6" length 10W max. power
PCI Express x16 (v3.0) (wired as a x4)	N/A	1 ea. 2.5" low profile 6.6" length 35W max. power	1 ea. 4.2" full height 6.6" length 35W max. power
PCI Express x16 (v3.0)	N/A	1 ea. 2.5" low profile 6.6" length 35W max. power	1 ea. 4.2" full height 6.6" length 75W max. power
Optional PCI	N/A	N/A	1 ea. 4.2" full height 6.6" length

^{*}Models configured with optional PCI slot come with 1 PCI Express x16 (v3.0) (wired as a x4) instead of 2. NOTE: Maximum total of 4 PCI slots supported on MT.



^{**}Wake on Lan feature is not available.

Standard Features and Configurable Components

PORTS

vPro™ configs	<u>DM</u>	<u>SFF</u>	<u>MT</u>
USB 2.0			2 (front) including 1 fast charging; 2 (rear)
USB 3.1 Gen1	2 (front) including 1 fast charging; 4 (rear)	2 (front); 4 (rear)	2 (front); 4 (rear)
USB Type-C™3.1 Gen1 port	1 (front); 1 (optional) (rear)	1 (front); 1 (optional) (rear)	1 (front); 1 (optional) (rear)

Non-vPro™ configs	<u>DM</u>	<u>SFF</u>	<u>MT</u>
USB 2.0			2 (front) including 1 fast charging; 4 (rear)
	2 (front) including 1 fast charging; 4 (rear)	2 (front); 2 (rear)	2 (front); 2 (rear)
USB Type-C™3.1 Gen1 port	1 (front); 1 (optional) (rear)	1 (front); 1 (optional) (rear)	1 (front); 1 (optional) (rear)
USB 2.0			2 (front) including 1 fast charging; 4 (rear)

		stream 1 Optional port (DisplayPort™, HDMI, VGA or USB-C™) (USB- C™ option has alt mode	2 DisplayPort™ with multi-stream 1 Optional port (DisplayPort™, HDMI, VGA or USB-C™) (USB- C™ option has alt mode DisplayPort™ or 15W output)
			Front: 1 Headset Rear: 1 Audio-out 1 Audio-in
Network Interface	RJ-45	RJ-45	RJ-45
Serial (RS-232)	1 (optional)*	1 (optional)	1 (optional)
Serial (RS-232) and PS/2 combination	N/A	1 (optional) (rear)	1 (optional) (rear)

BAYS

	<u>DM</u>	<u>SFF</u>	<u>MT</u>
5.25" Half Height **	N/A	N/A	1 ea.
9mm Slim ODD	N/A	1 ea.	1 ea.
Secure Digital (SD) 4 Reader	N/A	1 ea.	1 ea.
2.5" internal storage drive	1 ea.	1 ea.*	2 ea.
3.5" internal storage drive	N/A	1 ea.*	1 ea.

^{*}SFF can be configured with either (1) 3.5" or (1) 2.5" internal storage drive (2.5 inch drive needs adapter)



^{**}The HP G2 5.25 ODD is also compatible with the G3 MT Chassis

Standard Features and Configurable Components

KEYBOARDS AND POINTING DEVICES (optional)

Keyboards	<u>DM</u>	<u>SFF</u>	<u>MT</u>
HP Conferencing Keyboard	X	Х	Х
HP USB PS/2 Washable Keyboard*	Х	Х	Х
HP USB Business Slim CCID SmartCard Keyboard	Х	Х	Х
HP USB Business Slim Keyboard	Х	Х	Х
HP PS/2 Business Slim Keyboard*		Х	Х
HP USB Business Slim Keyboard (China only)	Х	Х	Х
HP USB Business Slim Grey Keyboard	Х	Х	Х
Mice	<u>DM</u>	SFF	MT
HP PS/2 Mouse*		Х	Х
HP USB 1000dpi Laser Mouse	X	Х	Х
HP Grey V2 Mouse	Х	Х	X.
HP USB Mouse	Х	Х	Х
HP USB PS/2 Washable Mouse*	Х	Х	Х
HP USB Mouse (China only)	Х	Х	Х
HP USB Hardened Mouse	Х	Х	Х
Combo	<u>DM</u>	SFF	MT
HP Wireless Business Slim Keyboard and Mouse	X	Х	Х
HP USB Keyboard and Mouse (China only)	Х	Х	Х
Other	<u>DM</u>	<u>SFF</u>	MT
HP Mouse Pad	Х	Х	Х

^{*}Optional HP Internal Serial/PS/2 Ports is required to support this device.

ADAPTERS AND CABLES (optional)

	<u>DM</u>	<u>SFF</u>	<u>MT</u>
HP DisplayPort™ Cable	X	X	X
HP DisplayPort™ to DVI-D Adapter	X	Х	Х
HP DisplayPort™ to HDMI 4K Adapter	X	Х	Х
HP DisplayPort™ to VGA Adapter	Х	Х	Х
HP DVI Cable	X	Х	Х
HP 700mm DisplayPort™ Cable Kit	Х		
HP USB to Serial Port Adapter	Х		

Standard Features and Configurable Components

I/O Devices

Optional Ports (only one can be chosen) must be configured at purchase except for PCIe x1 cards.

	<u>DM</u>	<u>SFF</u>	<u>MT</u>
HP DisplayPort™ Port	Х	Х	Х
HP Type-C Port	Х	Х	Х
HP HDMI Port	Х	Х	Х
HP VGA Port	Х	Х	Х
HP Internal Serial Port		X*	Х*
HP Internal Serial/PS/2 Ports		X*	Х*
HP PCIe x1 Parallel Port Card		Х	Х
HP PCIe x1 SuperSpeed USB 3.1 Gen 2 Type-C Card		Х	Х

DUST FILTERS

	<u>DM</u>	<u>SFF</u>	<u>MT</u>
HP ProDesk 600 G3 Microtower Dust Filter			X
HP ProDesk 600/400 G3 SFF Dust Filter		Х	
HP G3 Mini Dust Filter	Х		

^{*} Internal Serial Port and HP Internal Serial/PS/2 Ports can both be selected for MT and SFF

DESKTOP MINI ACCESSORIES (optional)

	<u>DM</u>	<u>SFF</u>	<u>MT</u>
HP Desktop Mini DVD-Writer ODD Expansion Module	Х		
HP Desktop Mini 500GB HDD/ I/O Expansion Module	Х		
HP Desktop Mini I/O Expansion Module	Х		
HP Desktop Mini Security/Dual VESA Sleeve	Х		
HP DM VESA Power Supply Holder	Х		
HP DM VESA Quick Deploy Adhesive	Х		
HP Desktop Mini Vertical Chassis Stand	Х		
HP Desktop Mini Port Cover Kit	Х		
HP Quick Release Bracket	Х		
HP DM Antenna/Wiring WLAN Kit	Х		
HP PC Mounting Bracket for Monitors	Х		

SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

BIOS

HP BIOSphere Gen3¹
HP DriveLock | HP Automatic DriveLock
BIOS Update via Network
Master Boot Record Security
Power On Authentication
Secure Erase²



Standard Features and Configurable Components

Absolute Persistence Module³ Pre-boot Authentication HP LAN-WLAN Protection HP Wireless Wakeup

Multi Media

CyberLink Power Media Player (select models only)
CyberLink Power2Go (select models only)

Communication / Connectivity

Native Miracast Support⁴

HP Value Add Software

HP ePrint Driver + JetAdvantage⁵

HP Hotkey Support - CMIT

HP Recovery Manager

HP Recovery Disc Creator (Windows 7 only)

HP Jumpstart

HP Support Assistant

HP Noise Cancellation Software

HP Velocity

HP Notifications

3rd Party

Foxit PhantomPDF Express for HP (Windows 7 only)

Microsoft Products

Buy Office Bing Search Skype⁶

Manageability

HP Driver Packs7

HP SoftPaq Download Manager (SDM)

HP System Software Manager (SSM)7

HP BIOS Config Utility (BCU)⁷

HP Client Catalog⁸

HP Manageability & Integration Kit (MIK)7

LANDESK Management⁸

For more information on HP Client Management Solutions refer to: http://www.hp.com/go/clientmanagement

Client Security Software

HP Client Security

- HP Security Manager (including Credential Manager and Password Manager)
- HP Drive Lock
- HP Password Manager
- · Absolute Persistence Module
- Power On Authentication

Microsoft Security Essentials9 (Windows 7 only)

Microsoft Defender

HP WorkWise (requires Bluetooth®)10



Standard Features and Configurable Components

Standard

Trusted Platform Module (TPM) 2.0 (Infineon SLB9670). Common Criteria EAL4+ Certified.

Downgradeable to TPM 1.2. Convertible to FIPS 140-2 Certified mode. (TPM 2.0 is not available for Win 7 32-bit.) Restrictions apply; contact your account manager for more details.

For more information on HP Client Security Software Suite, refer to http://www.hp.com/go/clientsecurity.

- 1 HP BIOSphere Gen 3 requires Intel® or AMD 7th generation processors.
- 2 For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88.
- 3 Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit: http://www.absolute.com/company/legal/agreements/ computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.
- 4 Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming media players that also support Miracast. You can use Miracast to share what you're doing on your PC and present a slide show. For more information: http://windows.microsoft.com/en-us/windows-8/project-wireless-screen-miracast
- 5 Requires an Internet connection to HP web-enabled printer and HP ePrint account registration (for a list of eligible printers, supported documents and image types and other HP ePrint details, see www.hp.com/go/eprintcenter). Requires optional broadband module. Broadband use requires separately purchased service contract. Check with service provider for coverage and availability in your area. Separately purchased data plans or usage fees may apply. Print times and connection speeds may vary.
- 6 Skype is not offered in China.
- 6 Not preinstalled, however available for download at http://www.hp.com/go/clientmanagement
- 7 Subscription required.
- 9 Opt in and internet connection required for updates.
- 10 HP WorkWise smartphone app will soon be available as a free download on the App Store and Google Play. Requires Windows 10 Build 1607 or higher).

HP BIOS

Key features of the HP BIOS include:

- Deployment and manageability HP BIOS provides several technologies that help integrate the HP Pro 600 G3
 Business PC into the enterprise, such as PXE, remote configuration, remote control, and F10 Setup support for 14
 languages.
- Update your BIOS via the cloud or standardize on a BIOS version hosted on Enterprise network.
- Stability HP BIOS supports the HP stable product roadmap by releasing only critical BIOS changes to the factory and advanced change notification.
- UEFI specification 2.5
- Absolute Persistence agent For tracking and tracing services, available in select countries, separate software and purchase of a subscription is required.
- Thermal and power management The HP BIOS provides and enables thermal and power management technologies so component temperatures are managed for high reliability and to assist in operating the HP Business Desktop computer in any enterprise environment.
- Acoustic performance Industry leading acoustic emissions across the range of operating conditions.
- Serviceability HP BIOS provides diagnostic and detailed service information.
- Upgrades and recovery HP BIOS provides numerous ways to upgrade HP Business Desktop computers, including BIOS updates from within Windows (HPBIOSUPDREC), HP Client Manager, and fail-safe recovery. In addition, the HP Business Desktop BIOS Utilities tool enables replicated BIOS setup throughout the Enterprise; it is available from within the BIOS software and from the support website.
- HP BIOS uses PKI signing of the BIOS for trusted BIOS upgrades and recovery.

Additional HP BIOS Features:

Power-On password – Helps prevent an unauthorized user from powering on the system.



Standard Features and Configurable Components

- Administrator password Also known as the setup password, this helps prevent unauthorized changes to the system
 configuration. If the administrator password is not known, the BIOS version cannot be changed and changes cannot be
 made to BIOS settings using F10 setup or under the OS.
- Advanced Configuration and Power Interface (ACPI) Represents a significant innovation in power and configuration
 management, allowing operating systems and applications to manage power based on activity and usage. HP Pro
 models use ACPI to provide power conservation features.

S5 Max Power Savings setting supports EU Lot6 requirement and allows the computer to power down below 0.5W in S5 (when turned off). When S5 Max Power Savings feature is enabled below features are turned off:

- Power to slots
- Wake events other than power buttons (such as Wake on LAN)
- USB charging ports

Core™ vPro™ Processors*

Intel® 6th & 7th Generation Core™ vPro™ Processors

All HP Pro 600 G3 Business PC models featuring this technology include processors that are part of the Intel® Stable Image Platform Program (SIPP) designed to ensure the stability promise inherent in the value proposition of the HP Pro 600 G3 Business PC, thus making these models the most stable, secure, and manageable platforms available to enterprises today.

Intel® Advanced Management Technology (AMT) v11** – An advanced set of remote management features and functionality which provides network administrators the latest and most effective tools to remotely discover, heal, and protect networked client systems regardless of the system's health or power state. AMT 11 includes the following advanced management functions:

- Support for configuration of Intel® AMT 11.0 new capabilities
- No reset after provisioning
- Support changes to BIOS table 130
- Support for Microsoft Windows Server 2012 R2
- Support for New Microsoft SQL Server Versions including Standard and Enterprise editions
- Support for Intel® SSD Prop 2500 Series
- Support for Intel® Enterprise Digital Fence
- The Platform Discovery Utility can now discover these additional Intel® products:
- Intel® SSD Pro 2500 Series; Enterprise Digital Fence
- Intel® Identity Protection Technology with One Time Password; Public Key Infrastructure; Multi Factor Authentication
- Intel® Identity Protection Technology with Intel® WiGig
- New Profile Editor and Profile Editor Plugin Interface
- New Required Permissions for Solutions Framework

*Some functionality of this technology, such as Intel Active management technology and Intel® Virtualization technology, requires additional 3rd party software in order to run. Availability of future "virtual appliances" applications for Intel vPro™ technology is dependent on 3rd party software providers. Compatibility with future "virtual appliances" is yet to be determined.

** Intel® Active Management Technology requires an Intel® AMT-enabled chipset, network hardware and software, as well as connection with a power source and a corporate network connection. Setup requires configuration by the purchaser and may require scripting with the management console or further integration into existing security frameworks to enable certain functionality. It may also require modifications of implementation of new business processes.



Standard Features and Configurable Components

HARDWARE SECURITY

SATA 0,1 port disablement (via BIOS)

Serial, USB enable/disable (via BIOS)

Solenoid Lock / Hood Sensor (MT/SFF only)

Hood Sensor for DM (integrated in the PCA, can be enabled/disabled through BIOS)

Support for chassis padlocks and cable lock devices

POWER SUPPLY

	DM	SFF	MT
Standard Efficiency	65W EPS, 89% average efficiency at 115V & 230Vac	N/A	N/A
80 PLUS Bronze	N/A	180W active PFC 82/85/82% efficient at 20/50/100% load (115V)	180W active PFC 82/85/82% efficient at 20/50/100% load (115V) 250W active PFC 82/85/82% efficient at 20/50/100% load (115V)
80 PLUS Gold	N/A	N/A	N/A
80 PLUS Platinum	N/A	180W active PFC 90/92/89% efficient at 20/50/100% load (115V) 91/93/90% efficient at 20/50/100% load (230V)	250W active PFC 90/92/89% efficient at 20/50/100% load (115V) 91/93/90% efficient at 20/50/100% load (230V)
Operating Voltage Range	90 – 264 VAC	90 – 264 VAC	90 – 264 VAC
Rated Voltage Range	100-240V AC	100-240V AC	100-240V AC
Rated Line Frequency	50/60 HZ	50/60 HZ	50/60 HZ
Operating Line Frequency	47 – 63 Hz	47 – 63 Hz	47 – 63 Hz
Rated Input Current	N/A	N/A	N/A
Rated Input Current with Energy Efficient* Power Supply		180W/2.3A	180W/2.3A 250W Bronze/3.5A 250W Platinum/3A
DC Output			



Standard Features and Configurable Components

	+19.5V	+12.1V	+12.1V		
99: 2102)	Less than 500 microamps of leakage current at 120 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1.	Less than 500 microamps of leakage current at 120 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1.			
	Less than 100 microamps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1.	Less than 100 microamps of leakage current at 120 Vac with th ground wire intact with normal polarity, as required for Non-pa Electrical Appliances and Equipment used in a patient care facil that contact patients in normal use. Per section 10.3.5.1.			
Power Supply Fan	N/A	70mm variable speed	70mm variable speed		
Power cord length	6.0 ft. (1.83 m)	6.0 ft. (1.83 m)	6.0 ft. (1.83 m)		
External Power Adapter	N/A	N/A	N/A		
Dimensions	N/A	N/A	N/A		
Total Cord Length	N/A	N/A	N/A		

WEIGHTS & DIMENSIONS

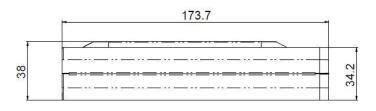
	<u>DM</u>	<u>SFF</u>	<u>MT</u>
Chassis (W x H x D) Not including bezel	6.97 x 1.35 x 6.88 in 177 x 34.2 x 174.7 mm	10.6 x 3.7 x 11.7 in 270 x 95 x 296 mm	6.69 x 13.3 x 10.79 in 170 x 338 x 274 mm
System Volume	64 cu in 1.06 L		960 cu in 15.74 L
System Weight*	2.67 lb 1.21 kg		15.77 lb 7.14 kg
Max Supported Weight (desktop orientation)	N/A		77 lb 35 kg
Packaging (H x W x D)	5.7 x 9.1 x 19.6 in 144.8 x 231.1 x 497.8 mm		19.65 x 15.35 x 11.73 in 499 x 390 x 298 mm
Shipping Weight	6.1 lb 2.8 kg	16.12 lb. 7.32 kg	22.64 lb. 10.28 kg
Palletization Profile	20-units per layer 4 layer max 80-units per pallet Footprint-39.21 x 46.61 in (996 x 1184 mm)	6-units per layer 10 layer max 60 per pallet 47.24 x 39.37 x 94.49 in (including pallet)	6-units per layer 7 layer max 42 per pallet 47.24 x 39.37 x 86.85 in (including pallet)

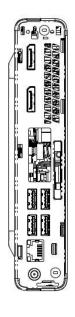


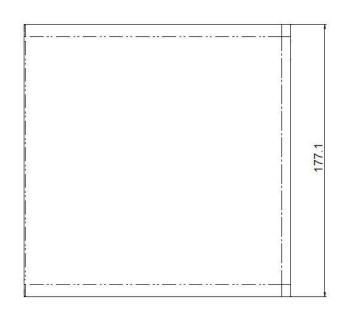
Standard Features and Configurable Components

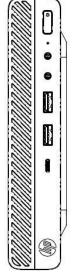
Dependent on 40-Ft Stnd. Sea Container or 40-Ft High-cube	
Sea Container is used)	

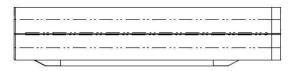
DESKTOP MINI DIMENSIONS





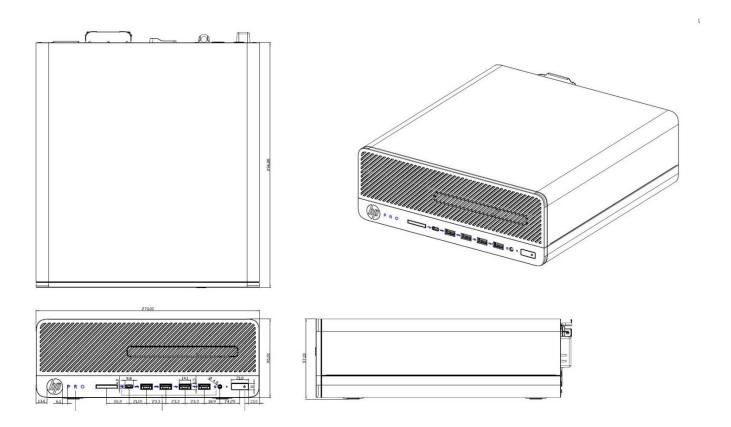






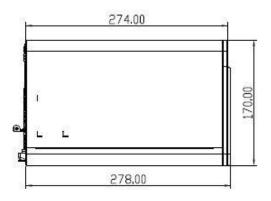
Standard Features and Configurable Components

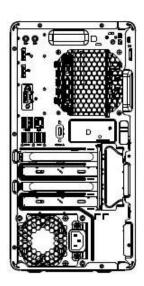
SMALL FORM FACTOR DIMENSIONS

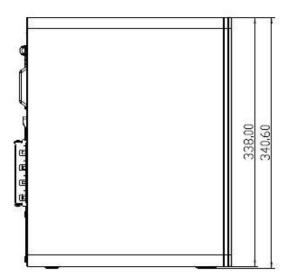


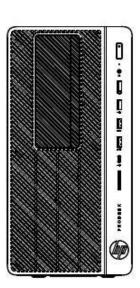
Standard Features and Configurable Components

MICROTOWER DIMENSIONS











Standard Features and Configurable Components

ENVIRONMENTAL & INDUSTRY

Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: • IT ECO declaration							
	 US ENERGY STAR® EPEAT <gold> registered in the United States. See http://www.epeat.net for registration status in your country.</gold> 							
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Desktop model is based on a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.							
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz 230VAC, 50Hz 100VAC,							
Normal Operation (Short idle)	8.22 W	9.80 W	100VAC, 50Hz 8.56 W					
Normal Operation (Long idle)	7.66 W	7.69 W	7.70 W					
Sleep	1.25 W	1.25 W	1.23 W					
Off	1.03 W	1.03 W	1.10 W					
	Environmental Protection Agency family does not offer ENERGY STA for a typically configured PC featu	(EPA) ENERGY STAR® specifications R® compliant configurations, then or Iring a hard disk drive, a high efficie	energy efficiency data listed is					
Heat Dissipation*	Environmental Protection Agency family does not offer ENERGY STA	(EPA) ENERGY STAR® specifications R® compliant configurations, then on uring a hard disk drive, a high efficient stem. 230VAC, 50Hz	s for computers. If a model energy efficiency data listed is ncy power supply, and a					
Heat Dissipation* Normal Operation (Short idle)	Environmental Protection Agency family does not offer ENERGY STA for a typically configured PC featu Microsoft Windows® operating sys	(EPA) ENERGY STAR® specifications R® compliant configurations, then or Iring a hard disk drive, a high efficie Stem.	s for computers. If a model energy efficiency data listed is ncy power supply, and a					
Normal Operation (Short	Environmental Protection Agency family does not offer ENERGY STA for a typically configured PC featu Microsoft Windows® operating sys	(EPA) ENERGY STAR® specifications R® compliant configurations, then on uring a hard disk drive, a high efficient stem. 230VAC, 50Hz	for computers. If a model energy efficiency data listed is ncy power supply, and a 100VAC, 50Hz 29 BTU/hr 26 BTU/hr					
Normal Operation (Short idle) Normal Operation (Long idle) Sleep	Environmental Protection Agency family does not offer ENERGY STA for a typically configured PC featu Microsoft Windows® operating sys 115VAC, 60Hz 28 BTU/hr 26 BTU/hr	(EPA) ENERGY STAR® specifications R® compliant configurations, then our only a hard disk drive, a high efficient of the stem. 230VAC, 50Hz 34 BTU/hr 4 BTU/hr	for computers. If a model energy efficiency data listed is ncy power supply, and a 100VAC, 50Hz 29 BTU/hr 26 BTU/hr					
Normal Operation (Short idle) Normal Operation (Long idle)	Environmental Protection Agency family does not offer ENERGY STA for a typically configured PC featu Microsoft Windows® operating sys	(EPA) ENERGY STAR® specifications R® compliant configurations, then only ring a hard disk drive, a high efficient 230VAC, 50Hz 34 BTU/hr 26 BTU/hr	for computers. If a model energy efficiency data listed is ncy power supply, and a 100VAC, 50Hz 29 BTU/hr 26 BTU/hr					
Normal Operation (Short idle) Normal Operation (Long idle) Sleep	Environmental Protection Agency family does not offer ENERGY STA for a typically configured PC featu Microsoft Windows® operating sys 115VAC, 60Hz 28 BTU/hr 26 BTU/hr 4 BTU/hr 4 BTU/hr	(EPA) ENERGY STAR® specifications R® compliant configurations, then our only a hard disk drive, a high efficient of the stem. 230VAC, 50Hz 34 BTU/hr 4 BTU/hr	for computers. If a model energy efficiency data listed is ncy power supply, and a 100VAC, 50Hz 29 BTU/hr 26 BTU/hr 4 BTU/hr 4 BTU/hr					
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Internal: PLASTIC/Polyethylene Expanded - EPE 38 g PLASTIC/Polyethylene high density - HDPE 4 g The Plastic packaging material is made from 0% recycled content. The paper packaging materials contains at least 25% recycled content. This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): Asbestos Certain Azo Colorants Certain Brominated Flame Retardants – may not be used as flame retardants in plastics Cadmium Chlorinated Hydrocarbons Chlorinated Hydrocarbons Chlorinated Paraffins Formaldehyde Halogenated Diphenyl Methanes Lead carbonates and sulfates Lead and Lead compounds Mercuric Oxide Batteries Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. Ozone Depleting Substances Polybrominated Biphenyls (PBBs) Polybrominated Biphenyl Ethers (PBBEs)		1 14	and the decorate of the									
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This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): Asbestos Certain Azo Colorants Certain Brominated Flame Retardants – may not be used as flame retardants in plastics Cadmium Chlorinated Hydrocarbons Chlorinated Paraffins Formaldehyde Halogenated Diphenyl Methanes Lead carbonates and sulfates Lead and Lead compounds Mercuric Oxide Batteries Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. Ozone Depleting Substances Polybrominated Biphenyls (PBBs) Polybrominated Biphenyl Ethers (PBBEs)												
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Polybrominated Biphenyl Oxides (PBBOs) Polychlorinated Biphenyl (DCP)		-										
 Polychlorinated Biphenyl (PCB) Polychlorinated Terphenyls (PCT) 		-										
 Polycinol retail packaging has been Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been 		_		tain retail nackaging has been								
voluntarily removed from most applications.				tani retait packaging nas been								
Radioactive Substances												
Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)				0)								
			, , , , , , , , , , , , , , , , , , , ,	-								

Standard Features and Configurable Components

Packaging Usage	 HP follows these guidelines to decrease the environmental impact of product packaging: Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. Eliminate the use of ozone-depleting substances (ODS) in packaging materials. Design packaging materials for ease of disassembly. Maximize the use of post-consumer recycled content materials in packaging materials. Use readily recyclable packaging materials such as paper and corrugated materials. Reduce size and weight of packages to improve transportation fuel efficiency. Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	Hewlett-Packard offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.
Hewlett-Packard Corporate Environmental Information	For more information about HP's commitment to the environment: Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_IS 0_14K_Certificate.pdf and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

ENERGY STAR® certified models available

EPEAT® registered where applicable/supported. See http://www.epeat.net for registration status by country. Low halogen (chassis, all internal components and modules)*

TAA compliant models available

* External power supplies, power cords, cables and peripherals are not Low Halogen. Service parts obtained after purchase may not be Low Halogen.

UNIT ENVIRONMENT AND OPERATING CONDITIONS

General Unit Operating Guidelines

• Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit is operated within the specified operating range.



Standard Features and Configurable Components

- Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow.
- Never restrict airflow into the computer by blocking any vents or air intakes.
- Do not stack computers on top of each other or place computers so near each other that they are subject to each other's re-circulated or preheated air.
- Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign matter can block the vents and limit the airflow.
- If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the enclosure, and the same operating guidelines listed above will still apply.

Temperature Range Operating: 50° to 95° F (10° to 35° C)*

Non-operating: -22° to 140° F(-30° to 60° C)

Relative Humidity Operating: 10% to 90% (non-condensing at ambient)

Non-operating: 5% to 95% (non-condensing at ambient)

Maximum Operating: 5000m

Altitude (unpressurized) Non-operating: 50000ft (15240 m)

*Operating temperature is de-rated 1.0 deg C per 300 m (1000 ft) to 3000 m (10,000 ft) above sea level, no direct sustained sunlight. Maximum rate of change is 10 deg C/Hr. The upper limit may be limited by the type and number of options installed.

SERVICE AND SUPPORT

On-site Warranty ¹: Three-year (3-3-3) limited warranty delivers three years of on-site, next business day ² service for parts and labor and complimentary limited technical support. ³ Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack. ⁴ To choose the right level of service for your HP product, visit HP Care Pack Central: www.hp.com/go/cpc

NOTE 1: Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.

NOTE 2: On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

NOTE 3: Technical telephone support applies only to HP-configured and third-party HP qualified hardware and software.

NOTE 4: Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.



Technical Specifications – Graphics

GRAPHICS

DicplayDor+TM	Multimodo capable: cupport	c UDCD Display Port Audio (2	stroams) UPD2 link rates and					
DisplayPort™	Multimode capable; supports HDCP, Display Port Audio (2 streams), HBR2 link rates and Multi-Stream Technology for a maximum of 3 displays (including the integrated panel)							
Memory	The BIOS has options for selecting the dedicated memory size of 128MB, 256MB or 512MB Additional memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an optimal balance between graphics and system memory use.							
Maximum Graphics Memory	Microsoft Windows 7	Windows 8.1	Windows 10					
	Up to 1.7GB	Up to 1.8GB	>4 GB					
	Note: the actual amount of maximum graphics memory can be less than the amounts listed above depending upon your computer's configuration.							
Maximum Color Depth	32 bits/pixel							
Graphics/Video API Support	32 bits/pixel 6th Generation Core™ processors: • Next Generation Intel® Clear Video Technology HD Support is a collection of video playback and enhancement features that improve the end user's viewing experience • Encode/transcode HD content • Playback of high definition content including Blu-ray Disc • Superior image quality with sharper, more colorful images • DirectX Video Acceleration (DXVA) support for accelerating video processing • Full AVC/VC1/MPEG2/HEVC HW Decode • Advanced Scheduler 2.0, 1.0 • Windows 7, Windows 8.1, Windows 10, Linux OS Support • DirectX 12.1 • OpenGL 4.4 • Open CL 1.2 (Intel® HD Graphics 510)							

Supported Display Resolutions and Refresh Rates

Note: other resolutions may be available but are not recommended as they may not have been tested and qualified by HP. For All in One platforms, resolutions higher than the integrated panel resolution are not supported on the integrated panel.

		VGA	DisplayPort™	нрмі	
Resolution	Refresh Rate				Standard
640 x 480	60, 75, 85	Х	Х	Χ	VESA DMT, CVT 0.31M3
720 x 400	70	Х	Х	Х	IBM VGA
800 x 600	60, 75, 85	Х	Х	Х	VESA DMT, CVT0.48M3



Technical Specifications – Graphics

1024 x 768	60, 75, 85	Х	Х	Х	VESA DMT, CVT 0.79M3
1152 x 864	60, 75, 85	Х	Х	Х	VESA DMT, CVT 0.83MA
1280 x 720	60, 75, 85	Х	Х	Х	VESA DMT, CVT 0.92M9, CEA-770.3
1280 x 768	60, 60RB, 75, 85	Х	Х	Х	VESA DMT, CVT 0.98M9/0.98M9-R
1280 x 800	60, 75, 85	Х	Х	Х	VESA DMT
1280 x 960	60, 75, 85	Х	Х	Х	VESA DMT
1280 x 1024	60, 75, 85	Х	Х	Х	VESA DMT, CVT 1.31M4
1366 x 768	60, 60RB	Х	Х	Х	VESA DMT
1440 x 900	60, 60RB	Х	Х	Х	VESA DMT
1600 x 900	60, 60RB, 75, 85	Х	Х	Х	VESA DMT
1680 x 1050	60, 60RB, 75	Х	Х	Х	VESA DMT, CVT 1.76MA/1.76MA-R
1920 x 1080	60	Х	Х	Х	VESA DMT, CVT 2.07M9, SMPTE 274M
1920 x 1200	60, 60RB, 75, 85	Х*	Х	Х	DMT, CVT 2.30MA/2.30MA-R
1600 x 1200	60, 75, 85	Х*	Х	Х	VESA DMT, 1.92M3
1920 x 1440	60, 75, 85		Х	Х	VESA DMT, CVT 2.76M3
2048 x 1536	60,75		Х	Х	CVT 3.15M3
2560 x 1440	59.951		Х	Х	CVT 3.69M9-R
2560 x 1600	60, 60RB		Х	Х	VESA DMT, CVT 4.10MA/4.10MA-R
3840 x 2160	24		Х	Х	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
3840 x 2160	25		Х	Х	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
3840 x 2160	30		Х	Х	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
3840 x 2160	50		Х	Х	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
3840 x 2160	60		Х	Х	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
4096 x 2160	24		Х	Х	CVT-RBv1/v2 (8.85M-R), SMPTE 274M
4096 x 2160	25		Х	Х	CVT-RBv1/v2 (8.85M-R), SMPTE 274M
4096 x 2160	30		Х	Х	CVT-RBv1/v2 (8.85M-R), SMPTE 274M
4096 x 2160	50		Х	Х	CVT-RBv1/v2 (8.85M-R), SMPTE 274M
4096 x 2160	60		Х	Х	CVT-RBv1/v2 (8.85M-R), SMPTE 274M
1920 x 1080	60		Х	Х	VESA (SMPTE 274M)
1920 x 1080	50		Х	Х	SMPTE 274M
1920 x 1080	30		Х	Х	SMPTE 274M
1920 x 1080	24		Х	Х	SMPTE 274M
1280 x 720	60		Х	Х	VESA (CEA-770.3)
1280 x 720	50		Х	Х	SMPTE 296M



Technical Specifications – Graphics

	60	7	Х	Χ	MHL (CEA-770.2)	
720 x 576	50	7	Х	Х	ITU-R BT.1358	
640 x 480	60	7	Х	Х	CEA (VESA DMT)	
* 60Hz refresh rate only on VGA						

AMD Radeon™ R7 450 4GB PCle x16 Graphics Card

Memory 4GB 128-bit wide frame buffer operating at 1125MHz. **Controller Clock Speed** AMD® Radeon™ R9 450 GPU operating at 925 MHz

Multi-display Support A maximum of 4 displays are supported by the card. A maximum of 2 legacy displays (Native VGA,

DVI, or displays connected with passive DisplayPort™ adapters are considered as legacy)

Graphics / API support DIRECTX 12, Open GL 4.3, Open CL1.2, UVD 3

Output Connectors 1 x Dual-Link DVI-I, 1x DisplayPort™; 1x HDMI; Includes DVI to VGA adapter

Supported Display Resolutions and Refresh Rates

Note: other resolutions may be available but are not recommended as they may not have been tested and qualified by HP

		ρε \Φ)	0	Displ		
		VGA (DVI-VGA	DVI-D	DisplayPort™	HDMI	
Resolution	Refresh Rate*					Standard
640 x 480	60, 75, 85	Х	Χ	Х	X	VESA DMT, CVT 0.31M3
720 x 400	70	Χ	Χ	Х	Х	IBM VGA
800 x 600	60, 75, 85	Х	Х	Х	Х	VESA DMT, CVT0.48M3
1024 x 768	60, 75, 85	Х	Х	Х	Х	VESA DMT, CVT 0.79M3
1152 x 864	60, 75, 85	Х	Х	Х	Х	VESA DMT, CVT 0.83MA
1280 x 720	60, 75, 85	Х	Х	Х	Х	VESA DMT, CVT 0.92M9, CEA-770.3
1280 x 768	60, 60RB, 75, 85	Х	Х	Х	Х	VESA DMT, CVT 0.98M9/0.98M9-R
1280 x 800	60, 75, 85	Х	Х	Х	Х	VESA DMT
1280 x 960	60, 75, 85	Х	Х	Х	Х	VESA DMT
1280 x 1024	60, 75, 85	Х	Х	Х	Х	VESA DMT, CVT 1.31M4
1366 x 768	60, 60RB	Х	Х	Х	Х	VESA DMT
1440 x 900	60, 60RB	Х	Х	Х	Х	VESA DMT
1600 x 900	60, 60RB, 75, 85	Х	Х	Х	Х	VESA DMT
1680 x 1050	60, 60RB, 75	Х	Х	Х	Х	VESA DMT, CVT 1.76MA/1.76MA-R
1920 x 1080	60	Х	Х	Х	Х	VESA DMT, CVT 2.07M9, SMPTE 274M
1920 x 1200	60, 60RB, 75, 85	Х	Х	Х	Х	DMT, CVT 2.30MA/2.30MA-R
1600 x 1200	60, 75, 85	Х	Х	Х	Х	VESA DMT, 1.92M3
1920 x 1440	60, 75, 85	Х	Х	Х	Х	VESA DMT, CVT 2.76M3

Technical Specifications – Graphics

2048 x 1536	60,75	Х	Х	Х	Х	CVT 3.15M3
2560 x 1440	59.951		Х	Х	Х	CVT 3.69M9-R
2560 x 1600	60, 60RB		Х	Х	Х	VESA DMT, CVT 4.10MA/4.10MA-R
3840 x 2160	24			Х	Х	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
3840 x 2160	25			Х	Х	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
3840 x 2160	30		Х	Х	Х	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
3840 x 2160	50			Х		CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
3840 x 2160	60			Х		CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
4096 x 2160	24			Х	Х	CVT-RBv1/v2 (8.85M-R), SMPTE 274M
4096 x 2160	25			Х	Х	CVT-RBv1/v2 (8.85M-R), SMPTE 274M
4096 x 2160	30			Х	Х	CVT-RBv1/v2 (8.85M-R), SMPTE 274M
4096 x 2160	50			Х		CVT-RBv1/v2 (8.85M-R), SMPTE 274M
4096 x 2160	60			Х		CVT-RBv1/v2 (8.85M-R), SMPTE 274M
1920 x 1080	60		Х	Х	Х	VESA (SMPTE 274M)
1920 x 1080	50		Х	Х	Х	SMPTE 274M
1920 x 1080	30		Х	Х	Х	SMPTE 274M
1920 x 1080	24		Х	Х	Х	SMPTE 274M
1280 x 720	60		Х	Х	Х	VESA (CEA-770.3)
1280 x 720	50		Х	Х	Х	SMPTE 296M
720 x 480	60		Х	Х	Х	MHL (CEA-770.2)
	•	•	•	•		

^{* &}gt;60 refresh rates only for analog (VGA) signaling

AMD Radeon™ RX 460 4GB FH PCIe x16 Graphics Card

Memory2GB 128-bit wide frame buffer operating at 1750MHz.Controller Clock SpeedAMD® Radeon™ RX 460 GPU operating at up to 1.2GHzMulti-display SupportA maximum of 4 displays are supported by the card.

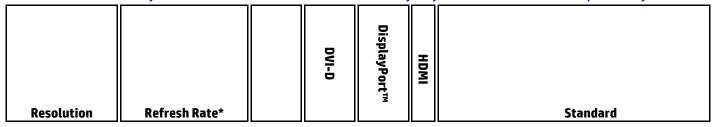
Graphics / API support DIRECTX 12, Open GL 4.5, Open CL 2.0, AMD Video Coding Engine (VCE) 3.4 and AMD Universal

Video Decoder(UVD)

Output Connectors 1 x Dual-Link DVI-D, 1x DisplayPort™; 1x HDMI

Supported Display Resolutions and Refresh Rates

Note: other resolutions may be available but are not recommended as they may not have been tested and qualified by HP





Technical Specifications – Graphics

640 x 480	60, 75, 85	Х	Х	х	VESA DMT, CVT 0.31M3
720 x 400	70	Х	Х	Х	IBM VGA
800 x 600	60, 75, 85	Х	Х	Х	VESA DMT, CVT0.48M3
1024 x 768	60, 75, 85	Х	Х	Х	VESA DMT, CVT 0.79M3
1152 x 864	60, 75, 85	Х	Х	Х	VESA DMT, CVT 0.83MA
1280 x 720	60, 75, 85	Х	Х	Х	VESA DMT, CVT 0.92M9, CEA-770.3
1280 x 768	60, 60RB, 75, 85	Х	Х	Х	VESA DMT, CVT 0.98M9/0.98M9-R
1280 x 800	60, 75, 85	Х	Х	Х	VESA DMT
1280 x 960	60, 75, 85	Х	Х	Х	VESA DMT
1280 x 1024	60, 75, 85	Х	Х	Х	VESA DMT, CVT 1.31M4
1366 x 768	60, 60RB	Х	Х	Х	VESA DMT
1440 x 900	60, 60RB	Х	Х	Х	VESA DMT
1600 x 900	60, 60RB, 75, 85	Х	Х	Х	VESA DMT
1680 x 1050	60, 60RB, 75	Х	Х	Х	VESA DMT, CVT 1.76MA/1.76MA-R
1920 x 1080	60	Х	Х	Х	VESA DMT, CVT 2.07M9, SMPTE 274M
1920 x 1200	60, 60RB, 75, 85	Х	Х	Х	DMT, CVT 2.30MA/2.30MA-R
1600 x 1200	60, 75, 85	Х	Х	Х	VESA DMT, 1.92M3
1920 x 1440	60, 75, 85	Х	Х	Х	VESA DMT, CVT 2.76M3
2048 x 1536	60, 75	Х	Х	Х	CVT 3.15M3
2560 x 1440	59.951	Х	Х	Х	CVT 3.69M9-R
2560 x 1600	60, 60 RB	Х	Х	Х	VESA DMT, CVT 4.10MA/4.10MA-R
3840 x 2160	24		Х	Х	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
3840 x 2160	25		Х	Х	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
3840 x 2160	30	Х	Х	Х	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
3840 x 2160	50		Х	Х	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
3840 x 2160	60		Х	Х	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
4096 x 2160	24		Х	Х	CVT-RBv1/v2 (8.85M-R), SMPTE 274M
4096 x 2160	25		Х	Х	CVT-RBv1/v2 (8.85M-R), SMPTE 274M
4096 x 2160	30		Х	Х	CVT-RBv1/v2 (8.85M-R), SMPTE 274M
4096 x 2160	50		Х	х	CVT-RBv1/v2 (8.85M-R), SMPTE 274M



Technical Specifications – Graphics

4096 x 2160	60		Х	Х	CVT-RBv1/v2 (8.85M-R), SMPTE 274M
1920 x 1080	60	Х	Х	Х	VESA (SMPTE 274M)
1920 x 1080	50	Х	Х	Х	SMPTE 274M
1920 x 1080	30	Х	Х	Х	SMPTE 274M
1920 x 1080	24	Х	Х	Х	SMPTE 274M
1280 x 720	60	Х	Х	Х	VESA (CEA-770.3)
1280 x 720	50	Х	Х	Х	SMPTE 296M
720 x 480	60	Х	Х	Х	MHL (CEA-770.2)

NVIDIA® GeForce® GT 730 1GB PCIe x8 HDMI Graphics Card

1GB GDDR5 64-bit wide frame buffer operating at 2.5GHz. Memory

Controller Clock Speed NVIDIA® Kepler™ GPU operating at 901 MHz

Multi-display Support A maximum of 2 displays are supported by the card

Supports Microsoft DirectX 12, OpenGL 4.4 and OpenCL 2 API, Shade Model 5 and DirectCompute **Graphics / API support**

Output Connectors 1 x Dual-Link DVI-I; 1x HDMI; Includes DVI to VGA adapter

Supported Display Resolutions and Refresh Rates

Note: other resolutions may be available but are not recommended as they may not have been tested and qualified by HP

Resolution	Refresh Rate*	VGA (DVI-VGA) adanter)	DVI-D	HDMI	Standard
640 x 480	60, 75, 85	Х	Х	Х	VESA DMT, CVT 0.31M3
720 x 400	70	Х	Х	Х	IBM VGA
800 x 600	60, 75, 85	Х	Х	Х	VESA DMT, CVT0.48M3
1024 x 768	60, 75, 85	Х	X	Х	VESA DMT, CVT 0.79M3
1152 x 864	60, 75, 85	Х	Х	Х	VESA DMT, CVT 0.83MA
1280 x 720	60, 75, 85	Х	Х	Х	VESA DMT, CVT 0.92M9, CEA-770.3
1280 x 768	60, 60RB, 75, 85	Х	Х	Х	VESA DMT, CVT 0.98M9/0.98M9-R
1280 x 800	60, 75, 85	Х	Х	Х	VESA DMT
1280 x 960	60, 75, 85	Х	Х	Х	VESA DMT

Technical Specifications – Graphics

1280 x 1024	60, 75, 85	Χ	Х	Х	VESA DMT, CVT 1.31M4
1366 x 768	60, 60RB	Х	Х	Х	VESA DMT
1440 x 900	60, 60RB	Х	Х	Х	VESA DMT
1600 x 900	60, 60RB, 75, 85	Х	Х	Х	VESA DMT
1680 x 1050	60, 60RB, 75	Х	Х	Х	VESA DMT, CVT 1.76MA/1.76MA-R
1920 x 1080	60	Х	Х	Х	VESA DMT, CVT 2.07M9, SMPTE 274M
1920 x 1200	60, 60RB, 75, 85	Х	Х	Х	DMT, CVT 2.30MA/2.30MA-R
1600 x 1200	60, 75, 85	Х	Х	Х	VESA DMT, 1.92M3
1920 x 1440	60, 75, 85	Х	Х	Х	VESA DMT, CVT 2.76M3
2048 x 1536	60,75	Х	Х	Х	CVT 3.15M3
2560 x 1440	59.951		Х	Х	CVT 3.69M9-R
2560 x 1600	60, 60RB		Х	Х	VESA DMT, CVT 4.10MA/4.10MA-R
3840 x 2160	24			Х	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
3840 x 2160	25			Х	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
3840 x 2160	30		Х	Х	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
3840 x 2160	50				CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
3840 x 2160	60				CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
4096 x 2160	24			Х	CVT-RBv1/v2 (8.85M-R), SMPTE 274M
4096 x 2160	25			Х	CVT-RBv1/v2 (8.85M-R), SMPTE 274M
4096 x 2160	30			Х	CVT-RBv1/v2 (8.85M-R), SMPTE 274M
4096 x 2160	50				CVT-RBv1/v2 (8.85M-R), SMPTE 274M
4096 x 2160	60				CVT-RBv1/v2 (8.85M-R), SMPTE 274M
1920 x 1080	60		Х	Х	VESA (SMPTE 274M)
1920 x 1080	50		Х	Х	SMPTE 274M
1920 x 1080	30		Х	Х	SMPTE 274M
1920 x 1080	24		Х	Х	SMPTE 274M
1280 x 720	60		Х	Х	VESA (CEA-770.3)
1280 x 720	50		Х	Х	SMPTE 296M
720 x 480	60		Х	Х	MHL (CEA-770.2)

^{* &}gt;60 refresh rates only for analog (VGA) signaling

NVIDIA® GeForce® GT 730 2GB DP PCIe x8 Graphics Card



Technical Specifications – Graphics

Introduction		Expres	s x8 graph	nics add-i	n card bas	esolution dual-display performance in a low profile, PCI sed on the NVIDIA® Kepler™ Graphics Processor. Inferencing, and video or photo editing.
Memory		2GB GD	DR5 64-b	it wide fr	ame buffe	er operating at 900 MHz
Controller Clock S	Speed	NVIDIA	® Kepler™	GPU ope	rating at 9	902 MHz
Multi-display Sup	port	A maxii	mum of 4	displays	are suppo	orted by the card.
Graphics /API sup	port		ts Microso d DirectCo			nGL 4.4 and OpenCL 2 APIs, Shade Model 5, UVD 4.2, VCE
Output Connector	rs					™; Includes DVI to VGA adapter capable, support Audio, HBR2 and MST
Resolution	Refresh	kate*	VGA (DVI-VGA adanter)	DVI-D	DisplayPort™	Standard
640 x 480	60, 75		Х	Х	Х	VESA DMT, CVT 0.31M3
720 x 400	70		Х	Х	Х	IBM VGA
800 x 600	60, 75	, 85	Х	Х	Х	VESA DMT, CVT0.48M3
1024 x 768	60, 75	, 85	Х	Х	Х	VESA DMT, CVT 0.79M3
1152 x 864	60, 75	, 85	Х	Х	Х	VESA DMT, CVT 0.83MA
1280 x 720	60, 75	, 85	Х	Х	Х	VESA DMT, CVT 0.92M9, CEA-770.3
1280 x 768	60, 60RB,	75, 85	Х	Х	Х	VESA DMT, CVT 0.98M9/0.98M9-R
1280 x 800	60, 75	, 85	Х	Χ	Х	VESA DMT
1280 x 960	60, 75	, 85	Χ	Χ	Х	VESA DMT
1280 x 1024	60, 75	, 85	Х	Х	Х	VESA DMT, CVT 1.31M4
1366 x 768	60, 60)RB	Х	Х	Х	VESA DMT
1440 x 900	60, 60	RB	Х	Х	Х	VESA DMT
1600 x 900	60, 60RB,	75, 85	Х	Х	Х	VESA DMT
1680 x 1050	60, 60R	B, 75	Х	Х	Х	VESA DMT, CVT 1.76MA/1.76MA-R
1920 x 1080	60		Х	Х	Х	VESA DMT, CVT 2.07M9, SMPTE 274M
1920 x 1200	60, 60RB,	75, 85	Х	Х	Х	DMT, CVT 2.30MA/2.30MA-R
1600 x 1200	60, 75	, 85	Х	Х	Х	VESA DMT, 1.92M3
1920 x 1440	60, 75	, 85	Х	Х	Х	VESA DMT, CVT 2.76M3



Technical Specifications – Graphics

2048 x 1536	60,75	Х	Х	Х	CVT 3.15M3
2560 x 1440	59.951		Х	Х	CVT 3.69M9-R
2560 x 1600	60, 60RB		Х	Х	VESA DMT, CVT 4.10MA/4.10MA-R
3840 x 2160	24			Х	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
3840 x 2160	25			Х	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
3840 x 2160	30		Х	Х	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
3840 x 2160	60			Х	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
4096 x 2160	24			Х	CVT-RBv1/v2 (8.85M-R), SMPTE 274M
4096 x 2160	25			Х	CVT-RBv1/v2 (8.85M-R), SMPTE 274M
4096 x 2160	30			Х	CVT-RBv1/v2 (8.85M-R), SMPTE 274M
4096 x 2160	60			Х	CVT-RBv1/v2 (8.85M-R), SMPTE 274M
1920 x 1080	60		Х	Х	VESA (SMPTE 274M)
1920 x 1080	50		Х	Х	SMPTE 274M
1920 x 1080	30		Х	Х	SMPTE 274M
1920 x 1080	24		Х	Х	SMPTE 274M
1280 x 720	60		Х	Х	VESA (CEA-770.3)
1280 x 720	50		Х	Х	SMPTE 296M
720 x 480	60		Х	Х	MHL (CEA-770.2)
720 x 576	50		Х	Х	ITU-R BT.1358
640 x 480	60		Х	Х	CEA (VESA DMT)

Technical Specifications – Hard Disk and Solid State Storage

HARD DISK AND SOLID STATE STORAGE

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 16 GB (for Windows 7) and 36 GB (for Windows 8.1/10) of system disk is reserved for the system recovery software.

HP 1 TB 7.2K SATA 6.0Gb/s 2.5" Hard Disk Drive				
Capacity	1,000,204,886,016 b	ytes		
Rotational Speed	7,200 rpm			
Interface	SATA 6 Gb/s			
Buffer Size	32 MB			
Logical Blocks	1,953,525,168			
	Single Track:	2.0 ms		
Seek Time (typical reads, includes controller overhead, including and the controller overhead, including a controller overhead, including a controller overhead, including a controller overhead, including a controller over	Average:	12 ms		
including settling)	Full-Stroke:	25 ms		
Height (nominal)	0.374 in/9.5 mm			
Intidate (operation)	Media diameter: 2.5	Media diameter: 2.5 in/63.5 mm		
Width (nominal)	Physical size: 2.75 in/70 mm			
Operating Temperature	41° to 131° F (5° to	55° C)		

HP 500 GB 7.2K SATA 6.0Gb/s 2.5" Hard Disk Drive*				
Capacity	500,107,862,016 bytes			
Rotational Speed	7,200 rpm			
Interface	SATA 6 Gb/s			
Buffer Size	16 MB			
Logical Blocks	976,773,168			
Seek Time (typical reads,	Single Track:	2.0 ms		
includes controller overhead, including settling)	Average:	12 ms		



Technical Specifications – Hard Disk and Solid State Storage

	Full-Stroke:	25 ms		
Height (nominal)	0.267 in/6.8 mm			
Width (naminal)	Media diameter: 2.5 in/63.5 mm			
Width (nominal)	Physical size: 2.75 in/70 mm			
Operating Temperature	41° to 131° F (5° to 55° C)			

*NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

500GB* 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive					
Formatted Capacity	500,107,862,016 bytes	S			
Spindle Speed	7,200 rpm				
Interface	Serial ATA 3.0 (6.0 Gb/s	5)			
Buffer Size	16 MB	16 MB			
Logical Blocks	976,773,168				
	Single Track:	2.0 ms			
Seek Time (average)	Average:	11 ms			
	Full-Stroke:	21 ms			
Height (nominal)	1 in/2.54 cm				
Width (naminal)	Media diameter: 3.5 in/	/8.89 cm			
Width (nominal)	Physical size: 4 in/10.2	Physical size: 4 in/10.2 cm			
Operating Temperature	41° to 131° F (5° to 55°	C)			

HP 1 TB* 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive*		
Formatted Capacity	1,000,204,886,016 bytes	
Rotational Speed	7,200 rpm	
Interface	Serial ATA 3.0 (6.0 Gb/s)	
Buffer Size	32 MB	



Technical Specifications – Hard Disk and Solid State Storage

Logical Blocks	1,953,525,168		
	Single Track:	2.0 ms	
Seek Time (average)	Average:	11 ms	
	Full-Stroke:	21 ms	
Height (nominal)	1 in/2.54 cm		
Midth (nominal)	Media diameter: 3.5 in/8.89 cm		
Width (nominal)	Physical size: 4 in/10.2 cm		
Operating Temperature	41° to 131° F (5° to 55° C)		

^{*} For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

HP 2 TB* 7.2K r _l	HP 2 TB* 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive*				
Formatted Capacity	2 TB				
Rotational Speed	7,200 rpm				
Interface	SATA 6Gb/s NCQ				
Cache, Multisegmented (MB)	64 MB				
Seek Time (average)	Read	<8.5 ms			
Seek Time (average)	Write	<9.5 ms			
Height	1.028 in/26.11 mm				
Width	4.0 in/101.6 mm				
Depth	5.787 in/146.99 mm				
Weight	1.38 lb/626 g				
Operating Temperature	32° to 140° F (0° to 60° C)				

HP 1 TB* SATA 6G 2.5" 8GB Solid State Hybrid Drive (SSHD)*		
Formatted Capacity 1 TB		
Spindle Speed	pindle Speed 5,400 rpm +/- 0.2%	
Drive Type Solid State Hybrid Drive (SSHD) technology with NAND Flash		



Interface	SATA 6 Gb/s		
interrace	3ATA 0 d0/3		
Cache Buffer	64 MB		
NAND Flash Commercial Multilevel Cell (cMLC)	8 GB		
Number of Sectors	976,773,168		
Seek Time (typical reads)	Single Track:	2.0 ms	
Seek Time (typicat reaus)	Average:	12 ms	
Height	0.374 +/008 in (9.5 +/- 0.2 mm)		
Width	2.750 +/- 0.010 in (69.85 +/- 0.25 mm)		
Length	3.951 +0.008 / -0.010 in (100.35 +0.20 / -0.25 mm)		
Weight	0.254 lb/115 g (max)		
Operating Temperature	32° to 140° F (0° to 60° C)		

^{*} For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 16 GB (for Windows 7) and 36 GB (for Windows 8.1/10) of system disk is reserved for the system recovery software.

HP 500 GB SATA 6G 2.5" 8GB Solid State Hybrid Drive (SSHD)*				
Formatted Capacity	500 GB	500 GB		
Spindle Speed	5,400 rpm +/- 0.2%			
Drive Type	Solid State Hybrid Drive	(SSHD) technology with NAND Flash		
Interface	SATA 6 Gb/s			
Cache Buffer	64 MB			
NAND Flash Commercial Multilevel Cell (cMLC)	8 GB			
Number of Sectors	976,773,168			
	Single Track:	2.0 ms		
Seek Time (typical reads)	Average:	12 ms		
Height	0.268 +/008 in (6.8 +/- 0.2 mm)			
Width	2.750 +/- 0.010 in (69.85 +/- 0.25 mm)			
Length	3.951 +0.008 / -0.010 in (100.35 +0.20 / -0.25 mm)			



Technical Specifications – Hard Disk and Solid State Storage

Weight	0.209 lb/95 g (max)
Operating Temperature	41° to 131° F (5° to 55° C)

*NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 16 GB (for Windows 7) and 36 GB (for Windows 8.1/10) of system disk is reserved for the system recovery software.

HP 1-TB SATA 6G 3.5" 8GB Solid State Hybrid Drive (SSHD)*				
Formatted Capacity	1 TB	1 TB		
Spindle Speed	7,200 rpm			
Drive Type	Solid State Hybrid D	rive (SSHD) technology with NAND Flash		
Interface	Serial ATA (SATA)			
Cache Buffer	64 MB	64 MB		
NAND Flash Multilevel Cell (MLC)	8 GB	8 GB		
Number of Sectors	1,953,525,168	1,953,525,168		
	Single Track:	2.0 ms		
Seek Time (typical reads)	Average:	11 ms		
Height	0.783 in / 2.01 cm	0.783 in / 2.01 cm		
Width	4 in / 10.2 cm	4 in / 10.2 cm		
Length	5.79 in / 14.7 cm	5.79 in / 14.7 cm		
Weight	0.88 lb/400 g	0.88 lb/400 g		
Operating Temperature	41° to 131° F (5° to 55° C)			

500GB* 2.5" FIPS 140-2 SED Solid State Drive*		
Formatted Capacity	500 GB	
Architecture	Self-Encrypting (SED) Solid State Drive with SATA interface.	



Technical Specifications – Hard Disk and Solid State Storage

	Relative Humidity: Shock:		5% to 95% Maximum 400 G/2 ms	
Environmental (all conditions, non-condensing)	Operating Temperature:		32° to 140° F (0° to 60° C)	
Power	Spinup (max): 1.00A Power consumption: Idle, active: 0.70W Sleep 0.18W			
	I/O data-transfer rate	600 MB/s max		
Bandwidth Performance	Sustained data transfer rate OD	100 MB/s max		
Weight (typical)	<95 g (0.209 lb)			
Length	100.35 mm ± 0.25/0.20			
Width	69.85 mm ± 0.25			
Height	6.80 mm ± 0.20			
Form Factor	2.5 inch	2.5 inch		
Interface	Serial ATA (6.0 Gb/s)			

256GB* TLC SED SSD 2.5" FIPS Drive*		
Unformatted Capacity	256 GB	
Architecture	Self-Encrypting (SED) Solid State Drive with SATA interface.	
Interface	Serial ATA (6.0 Gb/s)	
Form Factor	2.5 inch	
Height	7 mm	
Width	69.85 mm	
Length	100.45 mm	



Technical Specifications – Hard Disk and Solid State Storage

Weight (typical)	10 g (0.022 lb) max		
Bandwidth Performance	Sequential read (128KB transfer)	530	
	Sequential write (128KB transfer)	500	
	Random read (4KB transfer)	55,000	
	Random write (4KB transfer)	83,000	
Power	SATA Power consumption	Sleep Typical: 2m Idle, average: 55m Active, average: 7 Active maximum	nw
Environmental (all conditions, non-condensing)	Operating Temperature		32° to 158° F (0° to 70° C)
	Relative Humidity		5% to 95%
	Non-operating Shock		1500 G/0.5ms
	Non-operating Vibrat	tion	5-800Hz @ 3.10G

512GB* TLC SED SSD 2.5" FIPS Drive*		
Unformatted Capacity 512 GB		
Architecture	Self-Encrypting (SED) Solid State Drive with SATA interface.	
Interface	Serial ATA (6.0 Gb/s)	
Form Factor	2.5 inch	



Technical Specifications – Hard Disk and Solid State Storage

Height	7 mm		
Width	69.85 mm		
Length	100.45 mm		
Weight (typical)	10 g (0.022 lb) max		
Bandwidth Performance	Sequential read (128KB transfer)	530	
	Sequential write (128KB transfer)	500	
	Random read (4KB transfer)	92,000	
	Random write (4KB transfer)	83,000	
Power	SATA Power consumption	Sleep Typical: 2m Idle, average: 55m Active, average: 7 Active maximum	nw
Environmental	Operating Temperature		32° to 158° F (0° to 70° C)
(all conditions, non-condensing)	Relative Humidity		5% to 95%
	Non-operating Shock		1500 G/0.5ms
	Non-operating Vibra	tion	5-800Hz @ 3.10G

500 GB* SATA 2.5" Self-Encrypting (SED) Opal 2 Solid State Drive*	
Unformatted Capacity	500GB



Technical Specifications – Hard Disk and Solid State Storage

Architecture	Self-Encrypting (SED) Solid State Drive with 25nm MLC NAND Flash and SATA interface		
Interface	Serial ATA 2.0 (3.0 Gb/s)		
NAND Flash	25nm MLC NAND Flash		
Height	.275 in/7mm		
Width	2.75 in/69.85 mm		
Length	3.95 in/100.5 mm		
Weight	0.161 lb (73 g)		
Bandwidth Performance	Sustained Sequential 128k		
	Sustained Sequential 128k Write:	Up to 260 MB/s	
	Random 4k Read:	Up to 46K IOPs	
	Random 4k Write:	Up to 56K IOPs	
Latency	Read:	55 µs	
	Write:	55 µs	
Power	SATA power consumption:	160 mW (active average); <85 mW (idle average)	
Useful Drive Life	72TB written, up to 40GB/day for 5 years		
	Operating Temperature:	32° to 158° F (0° to 70° C)	
Environmental (all conditions, non-condensing)	Relative Humidity:	5% to 95%	
	Shock:	1,500 G/1 ms	



Technical Specifications – Hard Disk and Solid State Storage

	1			
Unformatted Capacity	256 GB 500,118,192 (User Addressable Sectors)			
Architecture	Self-Encrypting (SED) Solid State Drive with NAND Flash and SATA interface. Trusted Computing Group (TCG) OPAL 2.0 compliant encrypted solid state drive			
Interface	Serial ATA (6.0 Gb/s)			
Form Factor	2.5 inch			
Height	6.80 mm ± 0.20			
Width	69.85 mm ± 0.25	69.85 mm ± 0.25		
Length	100.20 mm ± 0.25			
Typical Weight	37.4 g			
Bandwidth Performance	Sustained Sequential Read:	υρ to 320 MB/S		
	Sustained Sequential Write:			
Power	Power consumption: Active: 3.891W; Idle		: 0.085W	
Mean Time Between Failure (MTBF)	1,500,000 hours			
Environmental (all conditions, non-condensing)	Operating Temperature:	;	32° to 158° F (0° to 70° C)	
(all conditions, non-condensing)	Relative Humidity:		5% to 95%	
	Shock:		1,500 G/0.5 ms	

512 GB SATA 2.5" TLC SED SSD Opal 2 Drive*	
Unformatted Capacity	512 GB 1,000,215,216 (User Addressable Sectors)



Technical Specifications – Hard Disk and Solid State Storage

Architecture	Self-Encrypting (SED) Solid State Drive with NAND Flash and SATA interface. Trusted Computing Group (TCG) OPAL 2.0 compliant encrypted solid state drive			
Interface	Serial ATA (6.0 Gb/s)			
Form Factor	2.5 inch			
Height	7 mm ± 0.20			
Width	69.85 mm ± 0.25			
Length	100.20 mm ± 0.25	100.20 mm ± 0.25		
Typical Weight	37.4 g			
Bandwidth Performance	Sustained Sequential Read:	Up to 515 MB/S		
	Sustained Sequential Write:			
Power	Maximum active power: ≤4,400mW Power consumption: Average power: 70mW Slumber low power mode: 42mW – 52mW		mW	
Mean Time Between Failure (MTBF)	Up to 1,750,000 hours			
Environmental	Operating Temperature:		0°C to 70°C (32°F to 158°F)	
(all conditions, non-condensing)	Non-operating temperature and storage		-55°C to +85°C (-67°F to 185°F)	
	Operating and non-operating shock		1,500 G/0.5 ms	

256GB Turbo Drive G2 TLC Solid State Drive		
Unformatted Capacity	256 GB	
Architecture	Solid State Drive with TLC NAND Flash and PCIE interface. Complies with NVMe Standard Power Saving Modes: L1 substates support Multi Queue support	



Interface	PCI-E Gen3 x 4			
Form Factor	M.2 2280			
Height	3.73 mm	3.73 mm		
Width	22.00 ± 0.15 mm	22.00 ± 0.15 mm		
Length	80.00 ± 0.15 mm	80.00 ± 0.15 mm		
Weight	Up to 8 g			
Bandwidth Performance	Sustained Sequential Read:	Up to 2600 MB/s		
	Sustained Sequential Write: Up to 1		Up to 1000 MB/s	
Power	Active: Typical 6.1W; Power consumption: Idle: Typical 80mW L1.2: Typical 5mW		;	
Mean Time Between Failure (MTBF)	1,500,000 hours			
Environmental	Operating Temperature:		32° to 158° F (0° to 70° C)	
(all conditions, non-condensing)	Relative Humidity:		5% to 95%	
	Shock: 1,500 G/0.5 ms		1,500 G/0.5 ms	

512GB Turbo Drive G2 TLC Solid State Drive			
Unformatted Capacity	512 GB		
Architecture	Solid State Drive with TLC NAND Flash and PCIE interface. Complies with NVMe Standard Power Saving Modes: L1 substates support Multi Queue support		
Interface	PCI-E Gen3 x 4		
Form Factor	M.2 2280		



Height	3.73 mm			
Width	22.00 ± 0.15 mm			
Length	80.00 ± 0.15 mm	80.00 ± 0.15 mm		
Weight	Up to 8 g	Up to 8 g		
Bandwidth Performance	Sustained Sequential Read: Up to 2600 MB/s			
	Sustained Sequential Write:	Up to 1200 MB/s		
Power	Power consumption:	Active: Typical 6.1W Idle: Typical 80mW L1.2: Typical 5mW	;	
Mean Time Between Failure (MTBF)	1,500,000 hours			
Environmental	Operating Temperature: 32° to 158° F (0° to 7		32° to 158° F (0° to 70° C)	
(all conditions, non-condensing)	Relative Humidity:		5% to 95%	
	Shock:		1,500 G/0.5 ms	

1TB Turbo Drive G2 TLC Solid State Drive		
Unformatted Capacity	1 TB	
Architecture	Solid State Drive with TLC NAND Flash and PCIE interface. Complies with NVMe Standard Power Saving Modes: L1 substates support Multi Queue support	
Interface	PCI-E Gen3 x 4	
Form Factor	M.2 2280	
Height	3.73 mm	



Width	22.00 ± 0.15 mm		
Length	80.00 ± 0.15 mm		
Weight	Up to 8 g		
Bandwidth Performance	Sustained Sequential Read: Up to 2600 MB/s		
	Sustained Sequential Write: Up to 1400 MB/s		
Power	Active: Typical 6.1W; Power consumption: Idle: Typical 80mW L1.2: Typical 5mW		;
Mean Time Between Failure (MTBF)	1,500,000 hours		
Environmental	Operating Temperature: 32° to 158° F (0° to 70° C)		32° to 158° F (0° to 70° C)
(all conditions, non-condensing)	Relative Humidity:		5% to 95%
	Shock:		1,500 G/0.5 ms



Technical Specifications – Hard Disk and Solid State Storage

HP 1 TB 7.2K SATA 6.0Gb/s 2.5" Hard Disk Drive			
Capacity	1,000,204,886,016 byt	1,000,204,886,016 bytes	
Rotational Speed	7,200 rpm		
Interface	SATA 6 Gb/s		
Buffer Size	32 MB	32 MB	
Logical Blocks	1,953,525,168		
	Single Track:	2.0 ms	
Seek Time (typical reads, includes controller overhead, including cottling)	Average:	12 ms	
including settling)	Full-Stroke:	25 ms	
Height (nominal)	0.374 in/9.5 mm		
Width (nominal)	Media diameter: 2.5 ir	Media diameter: 2.5 in/63.5 mm	
wiutii (nominal)	Physical size: 2.75 in/70 mm		
Operating Temperature	41° to 131° F (5° to 55° C)		

HP 500 GB 7.2K SATA 6.0Gb/s 2.5" Hard Disk Drive*			
Capacity	500,107,862,016 by	500,107,862,016 bytes	
Rotational Speed	7,200 rpm	7,200 rpm	
Interface	SATA 6 Gb/s	SATA 6 Gb/s	
Buffer Size	16 MB		
Logical Blocks	976,773,168		
Seek Time (tupical yeards	Single Track:	2.0 ms	
Seek Time (typical reads, includes controller overhead,	Average:	12 ms	
including settling)	Full-Stroke:	25 ms	
Height (nominal)	0.267 in/6.8 mm		



Technical Specifications – Hard Disk and Solid State Storage

Width (nominal)	Media diameter: 2.5 in/63.5 mm	
width (normal)	Physical size: 2.75 in/70 mm	
Operating Temperature	41° to 131° F (5° to 55° C)	

*NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

500GB* 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive				
Formatted Capacity	500,107,862,016 bytes			
Spindle Speed	7,200 rpm			
Interface	Serial ATA 3.0 (6.0	Serial ATA 3.0 (6.0 Gb/s)		
Buffer Size	16 MB			
Logical Blocks	976,773,168			
Seek Time (average)	Single Track:	2.0 ms		
	Average:	11 ms		
	Full-Stroke:	21 ms		
Height (nominal)	1 in/2.54 cm			
Width (nominal)	Media diameter: 3.5 in/8.89 cm			
wiutii (1101111111at)	Physical size: 4 in/	Physical size: 4 in/10.2 cm		
Operating Temperature	41° to 131° F (5° to 55° C)			

HP 1 TB* 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive*				
Formatted Capacity	1,000,204,886,016 bytes			
Rotational Speed	7,200 rpm	7,200 rpm		
Interface	Serial ATA 3.0 (6.0 Gb/s)	Serial ATA 3.0 (6.0 Gb/s)		
Buffer Size	32 MB	32 MB		
Logical Blocks	1,953,525,168			
Seek Time (average)	Single Track: 2.0 ms			



Technical Specifications – Hard Disk and Solid State Storage

	Average:	11 ms	
	Full-Stroke:	21 ms	
Height (nominal)	1 in/2.54 cm	1 in/2.54 cm	
Width (nominal)	Media diameter: 3.5 in/8.89 cm		
Width (nominal) Physical size: 4 in/10.2 cm			
Operating Temperature	41° to 131° F (5° to 55° C)		

^{*} For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

HP 2 TB* 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive*				
Formatted Capacity	2 TB			
Rotational Speed	7,200 rpm			
Interface	SATA 6Gb/s NCQ	SATA 6Gb/s NCQ		
Cache, Multisegmented (MB)	64 MB			
Sock Time (augrage)	Read	<8.5 ms		
Seek Time (average)	Write	Write <9.5 ms		
Height	1.028 in/26.11 mm			
Width	4.0 in/101.6 mm			
Depth	5.787 in/146.99 mm			
Weight	1.38 lb/626 g			
Operating Temperature	32° to 140° F (0° to 60° C)			

HP 500 GB SATA 6G 2.5" 8GB Solid State Hybrid Drive (SSHD)*			
Formatted Capacity	500 GB		
Spindle Speed	5,400 rpm +/- 0.2%		
Drive Type	Solid State Hybrid Drive (SSHD) technology with NAND Flash		
Interface	SATA 6 Gb/s		



Cache Buffer	64 MB		
NAND Flash Commercial Multilevel Cell (cMLC)	8 GB		
Number of Sectors	976,773,168		
Seek Time (typical reads)	Single Track:	2.0 ms	
	Average: 12 ms		
Height	0.268 +/008 in (6.8 +/- 0.2 mm)		
Width	2.750 +/- 0.010 in (69.85 +/- 0.25 mm)		
Length	3.951 +0.008 / -0.010 in (100.35 +0.20 / -0.25 mm)		
Weight	0.209 lb/95 g (max)		
Operating Temperature	41° to 131° F (5° to 55° C)		

^{*}NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 16 GB (for Windows 7) and 36 GB (for Windows 8.1/10) of system disk is reserved for the system recovery software.

HP 1 TB* SATA 6G 2.5" 8GB Solid State Hybrid Drive (SSHD)*				
Formatted Capacity	1 TB	1 TB		
Spindle Speed	5,400 rpm +/- 0.2%			
Drive Type	Solid State Hybrid Dri	Solid State Hybrid Drive (SSHD) technology with NAND Flash		
Interface	SATA 6 Gb/s	SATA 6 Gb/s		
Cache Buffer	64 MB			
NAND Flash Commercial Multilevel Cell (cMLC)	8 GB			
Number of Sectors	976,773,168			
Cook Theory (Associated to a de)	Single Track: 2.0 ms			
Seek Time (typical reads)	Average: 12 ms			
Height	0.374 +/008 in (9.5 +/- 0.2 mm)			
Width	2.750 +/- 0.010 in (69	2.750 +/- 0.010 in (69.85 +/- 0.25 mm)		
Length	3.951 +0.008 / -0.010 in (100.35 +0.20 / -0.25 mm)			



Technical Specifications – Hard Disk and Solid State Storage

0.254 lb/115 g (max)	
32° to 140° F (0° to 60° C)	
)	

^{*} For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 16 GB (for Windows 7) and 36 GB (for Windows 8.1/10) of system disk is reserved for the system recovery software.

HP 1-TB SATA 6G 3.5" 8GB Solid State Hybrid Drive (SSHD)*				
Formatted Capacity	1 TB			
Spindle Speed	7,200 rpm			
Drive Type	Solid State Hybrid D	Orive (SSHD) technology with NAND Flash		
Interface	Serial ATA (SATA)	Serial ATA (SATA)		
Cache Buffer	64 MB	64 MB		
NAND Flash Multilevel Cell (MLC)	8 GB			
Number of Sectors	1,953,525,168			
.	Single Track:	2.0 ms		
Seek Time (typical reads)	Average:	Average: 11 ms		
Height	0.783 in / 2.01 cm	0.783 in / 2.01 cm		
Width	4 in / 10.2 cm			
Length	5.79 in / 14.7 cm			
Weight	0.88 lb/400 g			
Operating Temperature	41° to 131° F (5° to 55° C)			

500GB* 2.5" FIPS 140-2 SED Solid State Drive*			
Formatted Capacity	500 GB		
Architecture	Self-Encrypting (SED) Solid State Drive with SATA interface.		
Interface	Serial ATA (6.0 Gb/s)		



Technical Specifications – Hard Disk and Solid State Storage

Form Factor	2.5 inch		
Height	6.80 mm ± 0.20		
Width	69.85 mm ± 0.25		
Length	100.35 mm ± 0.25/0.20		
Weight (typical)	<95 g (0.209 lb)		
Bandwidth Performance	Sustained data transfer rate OD	100 MB/s max	
	I/O data-transfer rate 600 MB/s max		
Power	Spinup (max): 1.00A Power consumption: Idle, active: 0.70W Sleep 0.18W		
Environmental	Operating Temperature:		32° to 140° F (0° to 60° C)
(all conditions, non-condensing)	Relative Humidity:		5% to 95%
	Shock:		Maximum 400 G/2 ms

256GB* TLC SED SSD 2.5" FIPS Drive*		
Unformatted Capacity	256 GB	
Architecture	Self-Encrypting (SED) Solid State Drive with SATA interface.	
Interface	Serial ATA (6.0 Gb/s)	
Form Factor	2.5 inch	
Height	7 mm	
Width	69.85 mm	
Length	100.45 mm	

Technical Specifications – Hard Disk and Solid State Storage

Weight (typical)	10 g (0.022 lb) max			
Bandwidth Performance	Sequential read (128KB transfer) 530			
	Sequential write (128KB transfer)	500	500	
	Random read (4KB transfer)	55,000		
	Random write (4KB transfer)	83,000		
Power	SATA Power Sleep Typical: 2mv Idle, average: 55m Active, average: 7		าพ	
Environmental (all conditions, non-condensing)	Operating Temperatu	ıre	32° to 158° F (0° to 70° C)	
(all conditions, non-condensing)	Relative Humidity		5% to 95%	
	Non-operating Shock		1500 G/0.5ms	
	Non-operating Vibration		5-800Hz @ 3.10G	

512GB* TLC SED SSD 2.5" FIPS Drive*	
Unformatted Capacity	512 GB
Architecture	Self-Encrypting (SED) Solid State Drive with SATA interface.
Interface	Serial ATA (6.0 Gb/s)
Form Factor	2.5 inch

Technical Specifications – Hard Disk and Solid State Storage

Height	7 mm		
Width	69.85 mm		
Length	100.45 mm		
Weight (typical)	10 g (0.022 lb) max		
Bandwidth Performance	Sequential read (128KB transfer)	530	
	Sequential write (128KB transfer)	500	
	Random read (4KB transfer)	92,000	
	Random write (4KB transfer) 83,000		
Power	SATA Power consumption Sleep Typical: 2mv Idle, average: 55m Active, average: 7 Active maximum		าพ
Environmental (all conditions, non-condensing)	Operating Temperature		32° to 158° F (0° to 70° C)
(all conditions, non-condensing)	Relative Humidity		5% to 95%
	Non-operating Shock		1500 G/0.5ms
	Non-operating Vibration		5-800Hz @ 3.10G

500 GB* SATA 2.5" Self-Encrypting (SED) Opal 2 Solid State Drive*	
Unformatted Capacity	500GB



Technical Specifications – Hard Disk and Solid State Storage

Architecture	Self-Encrypting (SED) Solid State Drive with 25nm MLC NAND Flash and SATA interface		
Interface	Serial ATA 2.0 (3.0 Gb/s)		
NAND Flash	25nm MLC NAND Flash		
Height	.275 in/7mm		
Width	2.75 in/69.85 mm		
Length	3.95 in/100.5 mm		
Weight	0.161 lb (73 g)		
Bandwidth Performance	Sustained Sequential 128k Read:	Up to 450 MB/s	
	Sustained Sequential 128k Write:	Up to 260 MB/s	
	Random 4k Read:	Up to 46K IOPs	
	Random 4k Write:	Up to 56K IOPs	
Latency	Read:	55 µs	
	Write:	55 μs	
Power	SATA power consumption:	160 mW (active average); <85 mW (idle average)	
Useful Drive Life	72TB written, up to 40GB/day for 5 years		
	Operating Temperature:	32° to 158° F (0° to 70° C)	
Environmental (all conditions, non-condensing)	Relative Humidity:	5% to 95%	
	Shock:	1,500 G/1 ms	



Technical Specifications – Hard Disk and Solid State Storage

11f	256 GB			
Unformatted Capacity	500,118,192 (User Addr	essable Sectors)		
Architecture	Self-Encrypting (SED) Sc	olid State Drive with NA	ND Flash and SATA interface.	
Architecture	Trusted Computing Grou	up(TCG) OPAL compliant	encrypted solid state drive	
Interface	Serial ATA (6.0 Gb/s)			
Form Factor	2.5 inch			
Height	6.80 mm ± 0.20			
Width	69.85 mm ± 0.25			
Length	100.20 mm ± 0.25	100.20 mm ± 0.25		
Weight	Up to 73 g			
Bandwidth Performance	Sustained Sequential Read:	d Sequential Up to 520 MB/s		
	Sustained Sequential Write:	Juential Up to 460 MB/s		
Power	Power consumption: Active: 3.891W; Idle: 0.085W			
Mean Time Between Failure (MTBF)	1,500,000 hours			
Environmental	Operating Temperature:		32° to 158° F (0° to 70° C)	
(all conditions, non-condensing)	Relative Humidity:		5% to 95%	
	Shock:		1,500 G/0.5 ms	

256GB Turbo Drive G2 TLC OPAL2.0 SED Solid State Drive	
Unformatted Capacity	256 GB



Architecture	Solid State Drive with TLC NAND Flash and PCIE interface. Complies with NVMe Standard Power Saving Modes: L1 substates support Multi Queue support TCG OPAL2.0 compliance		
Interface	PCI-E Gen3 x 4		
Form Factor	M.2 2280		
Height	3.73 mm		
Width	22.00 ± 0.15 mm		
Length	80.00 ± 0.15 mm		
Weight	Up to 8 g		
Bandwidth Performance	Sustained Sequential Read:	Up to 2200 MB/s	
	Sustained Sequential Write:	Up to 1000 MB/s	
Power	Power consumption:	Active: Typical 6.1W Idle: Typical 40mW L1.2: Typical 5mW	<i>J</i> ;
Mean Time Between Failure (MTBF)	1,500,000 hours		
Environmental (all conditions, non-condensing)	Operating Temperature:		32° to 158° F (0° to 70° C)
(att conditions, non-condensing)	Relative Humidity:		5% to 95%
	Shock:		1,500 G/0.5 ms

512GB Turbo Drive G2 TLC OPAL2.0 SED Solid State Drive	
Unformatted Capacity	512 GB



Architecture	Solid State Drive with TLC NAND Flash and PCIE interface. Complies with NVMe Standard Power Saving Modes: L1 substates support Multi Queue support TCG OPAL2.0 compliance		
Interface	PCI-E Gen3 x 4		
Form Factor	M.2 2280		
Height	3.73 mm		
Width	22.00 ± 0.15 mm		
Length	80.00 ± 0.15 mm		
Weight	Up to 8 g		
Bandwidth Performance	Sustained Sequential Read:	Up to 2200 MB/s	
	Sustained Sequential Write:	Up to 1000 MB/s	
Power	Power consumption:	Active: Typical 6.1W Idle: Typical 40mW L1.2: Typical 5mW	J;
Mean Time Between Failure (MTBF)	1,500,000 hours		
Environmental (all conditions, non-condensing)	Operating Temperature:		32° to 158° F (0° to 70° C)
(att conditions, non-condensing)	Relative Humidity:		5% to 95%
	Shock:		1,500 G/0.5 ms

128GB SATA 2.5" Value (Non-SED) Solid State Drive	
Unformatted Capacity	128 GB
Architecture	TLC NAND Flash
Interface	SATA 3.2 (6.0 Gb/s)



Technical Specifications – Hard Disk and Solid State Storage

Form Factor	2.5 inch		
Dimensions (W x H x D)	6.98 x 0.7 x 10.05 cm		
Weight	31g		
Bandwidth Performance	Sustained Sequential Read: Up to 510 MB/s Sustained Sequential Write: Up to 330 MB/s Random Read: Up to 38K IOPs Random Write: Up to 70K IOPs		
Power	DC power requirement: 5 VDC 5%-100 mV ripple p-p		pple p-p
	Total power 50mW (active); 20 consumption:		W (idle)
Useful Drive Life	72TB written, up to 40GB/day for 5 years		
Environmental	Operating Temperature: 32° to 158° F (0° to 70° C)		32° to 158° F (0° to 70° C)
(all conditions, non-condensing)	Relative Humidity:		5% to 95%
	Shock:		1,500 G/0.5 ms

256GB SATA 2.5" Value (Non-SED) Solid State Drive		
Unformatted Capacity 256 GB		
Architecture	TLC NAND Flash	
Interface	SATA 3.2 (6.0 Gb/s)	
Form Factor	2.5 inch	
Dimensions (W x H x D)	6.98 x 0.7 x 10.05 cm 31g	
Weight		



Technical Specifications – Hard Disk and Solid State Storage

Bandwidth Performance	Sustained Sequential Read:	Up to 510 MB/s	
	Sustained Sequential Write:	Up to 330 MB/s	
	Random Read:	Up to 38K IOPs	
	Random Write:	Up to 70K IOPs	
Power	DC power requirement:	5 VDC 5%-100 mV r	ipple p-p
	Total power consumption:	50mW (active); 20m	nW (idle)
Useful Drive Life	72TB written, up to 40GB/day for 5 years		
Environmental	Operating Temperature:	Operating Temperature:	
(all conditions, non-condensing)	Relative Humidity:		5% to 95%
	Shock:	Shock:	

256GB SATA 2.5" TLC Solid State Drive		
Formatted Capacity	256 GB	
Architecture	Solid State Drive with SATA interface; ATA 8 Compliant and SATA 2.6 compliant	
Interface	Serial ATA 3 (6.0 Gb/s)	
Form Factor	2.5 inch	
Height	7 mm ± 0.20	
Width	69.85 mm ± 0.25	
Length	100.2 mm ± 0.25	
Weight (typical)	36.5 g (+2)	



Data Transfer Rate (128k Sequential)	Sequential Read	Up to 500 MB/s	
(120k Sequential)	Sequential Write	Up to 455 MB/s	
Power Watts	Read: 95 mW Power consumption (avg): Standby: 70 mW DEVSLP: <7 mW		
Environmental (all conditions, non-condensing)	Operating Temperature:		32° to 158° F (0° to 70° C)
(att conditions, non-condensing)	Relative Humidity:		5% to 95%
	Shock (2 m Sec half-sine):		1500 G peak 0.5ms (operating)

512 GB SATA 2.5" TLC Solid State Drive*				
Formatted Capacity	512 GB	512 GB		
Architecture	Solid State Drive with S	ATA interface; ATA 8 Co	mpliant and SATA 2.6 compliant	
Interface	Serial ATA 3 (6.0 Gb/s)			
Form Factor	2.5 inch			
Height	7 mm ± 0.20			
Width	69.85 mm ± 0.25	69.85 mm ± 0.25		
Length	100.2 mm ± 0.25	100.2 mm ± 0.25		
Weight (typical)	36.5 g (+2)	36.5 g (+2)		
Data Transfer Rate (128k Sequential)	Sequential Read	Up to 500 MB/s		
(120k Sequentiat)	Sequential Write	Up to 455 MB/s		
Power Watts	Power consumption (avg):	Read: 95 mW Write: 95 mW Standby: 70 mW DEVSLP: <7 mW		
	Operating Temperature	:	32° to 158° F (0° to 70° C)	



Technical Specifications – Hard Disk and Solid State Storage

Environmental (all conditions, non-condensing)	Relative Humidity:	5% to 95%
	Shock (2 m Sec half-sine):	1500 G peak 0.5ms (operating)



Technical Specifications – Optical Drives

OPTICAL DRIVES

HP 9.5mm G3 800/600 Tower DVD-Writer HP 9.5mm G3 800/600/400 SFF G4 400 SFF/MT DVD-Writer			
Height	12.7mm height		
Orientation	Either horizontal or vertical		
Interface type	SATA/ATAPI		
Disc recording capacity	Up to 8.5 GB DL or 4.7 GB stand	ard	
Dimensions (W x H x D)	5.04 x 0.5 x 5.0 in (128 x 12.7 x	127 mm) without bezel	
Weight (max)	0.42 lb (190 g)		
	DVD-R DL	Up to 6X	
	DVD+R	Up to 8X	
	DVD+RW	Up to 8X	
West and	DVD+R DL	Up to 6X	
Write speeds	DVD-R	Up to 8X	
	DVD-RW	Up to 6X	
	CD-R	Up to 24X	
	CD-RW	Up to 24X	
	DVD-RW, DVD+RW	Up to 8X	
	DVD-R DL, DVD+R DL	Up to 8X	
	DVD+R, DVD-R	Up to 8X	
Read speeds	DVD-ROM DL, DVD-ROM	Up to 8X	
	CD-ROM, CD-R	Up to 24X	
	CD-RW	Up to 24X	
	Random	DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical)	
Access time	Full Stroke	DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical)	
(typical reads, including	Stop Time	6 seconds (typical)	
settling)	Source	Slimline SATA DC power receptacle	
	DC Power Requirement	5 VDC ± 5%-100 mV ripple p-p	
Power	DC Current	5 VDC (< 1000 mA typical, 1600 mA maximum)	
	Temperature	41° to 122° F (5° to 50° C)	
P	Relative Humidity	10% to 80%	
Environmental conditions (operating - non-condensing)	Maximum Wet Bulb Temperature	84° F (29° C)	



Technical Specifications – Optical Drives

HP 9.5mm G3 800/600 HP 9.5mm G3 800/600		AT DVD-ROM
Height	12.7mm	
Orientation	Either horizontal or vertical	
Interface type	SATA/ATAPI	
Dimensions (W x H x D)	5.04 x 0.5 x 5.0 in (128 x 12.7	x 127 mm) without bezel
Weight (max)	Up to 0.37 lb (170 g) without	bezel
	DVD+R/-R/+RW/ -RW/+R DL /-R DL	Up to 8X
Read speeds	DVD-ROM	Up to 8X
•	CD-ROM, CD-R	Up to 24X
	CD-RW	Up to 24X
Access time	Random	DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical)
(typical reads, including settling)	Full Stroke	DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical)
	Source	Slimline SATA DC power receptacle
Power	DC Power Requirement	5 VDC ± 5%-100 mV ripple p-p
	DC Current	5 VDC - <1000 mA typical, < 1600 mA maximum
	Temperature	41° to 122° F (5° to 50° C)
Environmental (all conditions	Relative Humidity	10% to 80%
non-condensing)	Maximum Wet Bulb Temperature (operating)	84° F (29° C)

Technical Specifications – Memory

SYSTEM MEMORY SUPPORT

The HP ProDesk 600 G3 Business PC supports the 6th & 7th generation Intel® Core™ processor family. Based on a new PC microarchitecture, the processor is designed for a two-chip platform consisting of a processor and Platform Controller Hub (PCH). The 6th generation Intel® Core™ processor includes an Integrated Memory Controller (IMC). The IMC supports DDR4protocols with two independent, 64-bit wide channels each accessing one or two DIMMs.

- Two channels of non-ECC DDR4 unbuffered dual in-line memory modules (UDIMM) or DDR4 unbuffered small outline dual in-line memory modules (SO-DIMM) with a maximum of two DIMMs per channel
- Single-channel and dual-channel memory organization modes
- Data burst length of eight for all memory organization modes
- Memory data transfer rates of up to 2400MT/s; actual supported data transfer rate determined by the configured processor.
- 64-bit wide channels
- DDR4 system memory I/O voltage of 1.25V
- Theoretical maximum memory bandwidth of:
 - o 34 GB/s in dual-channel mode assuming 2400 MT/s

PLATFORM MEMORY SUPPORT

- The Small Form Factor (SFF) and Microtower (MT) platforms support up to four (4) industry-standard DDR4-SDRAM DIMMs.
- The Desktop Mini (DM) supports up to two (2) industry-standard DDR4-SDRAM SO-DIMMs.

CAUTION: You must shut down the computer and disconnect the power cord before adding or removing memory modules. Regardless of the power-on state, voltage is always supplied to the memory modules as long as the computer is plugged in to an active AC outlet. Adding or removing memory modules while voltage is present may cause irreparable damage to the memory modules or system board.

NOTE: For systems configured with more than 3 GB of memory and a 32-bit operating system, all memory may not be available due to system resource requirements. Addressing memory above 4 GB requires a 64-bit operating system.



Technical Specifications – Networking and Communications

NETWORKING AND COMMUNICATIONS

	Network Connection LOM (standard)		
Connector	RJ-45		
System Interface	PCIe + SMBus		
Controller	Intel® I219LM Gigabit Ethernet Controller		
Data rates supported	Supports operation at 10/100/1000 Mb/s data rates		
IEEE Compliance	IEEE 802.3 Ethernet interface for 1000BASE-T, 100BASETX, and 10BASET applications (802.3ab, 802.3u, and 802.3i, respectively). EEE 802.3az support [Low Power Idle (LPI) mode] IEEE 802.3u auto-negotiation conformance		
Performance	Jumbo Frames (up to 9 kB) 802.1Q & 802.1p Receive Side Scaling (RSS) Two Queues (Tx & Rx)		
Power	 Ultra Low Power at cable disconnect (<1 mW) enables platform support for connected standby Reduced power consumption during normal operation and power down modes Integrated Intel® Auto Connect Battery Saver (ACBS) Single-pin LAN Disable for easier BIOS implementation Fully integrated Switching Voltage Regulator (iSVR) Low Power Link-Up (LPLU) 		
MAC/PHY Interconnect	 PCIe-based interface for active state operation (S0 state) SMBus-based interface for host and management traffic (Sx low power state) 		
Management Interface	MDC/MDIO management interface		
Security & Manageability	Intel® vPro™ support with appropriate Intel chipset components		

Intel® Ethernet I210-T1 Gigabit Network Adapter		
Connector	RJ-45	
System Interface	PCI Express x1	
Controller	Intel® I210 Gigabit Ethernet Controller	
Memory	Integrated Dual 48K configurable transmit receive FIFO Buffers	
Data rates supported	10/100/1000 Mbps	



IEEE Compliance	802.1P 802.1Q 802.2 802.3 802.3AB 802.3u 802.3x flow control		
Bus architecture	PCI-E 2.1		
Data path width	X1, 250 MB/s, Bi-directional inter	face	
Data transfer mode	Bus-master DMA		
Hardware certifications	FCC, B, CE, TUV-c, TUVus Mark Ca	nada and United States, TUV-GS Mark for European Union	
Power requirement	Aux 3.3 V, 3.0 Watts in 1000 base	-T and 1.0 Watts in 100 Base-T	
Boot ROM support	Yes 10BASE-T (half-duplex) 10 Mbps 10BASE-T (full-duplex) 20 Mbps		
	10BASE-T (half-duplex) 10 Mbps 10BASE-T (full-duplex) 20 Mbps		
Network transfer rate	100BASE-TX (half-duplex) 100 Mbps		
	100BASE-TX (full-duplex) 200 Mbps		
	1000BASE-T (full-duplex) 2000 N	1bps (actual rate limited by PCI bus)	
Environmental	Operating Temperature:	32° to 132° F (0° to 55° C)	
Environmentat	Operating Humidity:	85% at 131° F (55° C)	
Management	WOL, PXE, DMI, WFM 2.0		

Intel® 8265 802.11ac 2x2 WiFi + Bluetooth® M.2 Combo Card* (802.11AC Wave 2 supported)		
Wireless LAN Standards	IEEE 802.11a	
	IEEE 802.11b	
	IEEE 802.11g	
	IEEE 802.11n	
	IEEE 802.11ac	
Interoperability	Wi-Fi certified	
Frequency Band	802.11b/g/n	
	• 2.402 – 2.482 GHz	
	Note:	
	The FCC has declared as of January 1, 2015 products that utilize passive scanning on channel 12/13 and are capable of transmitting	



	must fully comply with requirements of 15.247 or otherwise
	disable those channels.
	802.11a/n
	• 4.9 – 4.95 GHz (Japan)
	• 5.15 – 5.25 GHz
	• 5.25 – 5.35 GHz
	• 5.47 – 5.725 GHz
	• 5.825 – 5.850 GHz
Poto Potos	Note: Indonesia no support this band)
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
	 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz,
	and 80MHz)
Modulation	Direct Sequence Spread Spectrum
	BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
Security ¹	IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g
	mode only
	AES-CCMP: 128 bit in hardware
	802.1x authentication
	WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
	WPA2 certification
	• IEEE 802.11i
	Cisco Certified Extensions, all versions through CCX4 and CCX
	Lite
	WAPI
	- 11111
Network Architecture	Ad-hoc (Peer to Peer)
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Models	Infrastructure (Access Point Required)
Models Roaming	Infrastructure (Access Point Required) IEEE 802.11 compliant roaming between access points
Models	Infrastructure (Access Point Required) IEEE 802.11 compliant roaming between access points • 802.11b: +16dBm minimum
Models Roaming	Infrastructure (Access Point Required) IEEE 802.11 compliant roaming between access points • 802.11b:+16dBm minimum • 802.11g:+14dBm minimum
Models Roaming	Infrastructure (Access Point Required) IEEE 802.11 compliant roaming between access points • 802.11b: +16dBm minimum • 802.11g: +14dBm minimum • 802.11a: +14dBm minimum
Models Roaming	Infrastructure (Access Point Required) IEEE 802.11 compliant roaming between access points • 802.11b: +16dBm minimum • 802.11g: +14dBm minimum • 802.11a: +14dBm minimum • 802.11n HT20(2.4GHz): +14dBm minimum
Models Roaming	Infrastructure (Access Point Required) IEEE 802.11 compliant roaming between access points • 802.11b: +16dBm minimum • 802.11g: +14dBm minimum • 802.11a: +14dBm minimum • 802.11n HT20(2.4GHz): +14dBm minimum • 802.11n HT40(2.4GHz): +12dBm minimum
Models Roaming	Infrastructure (Access Point Required) IEEE 802.11 compliant roaming between access points • 802.11b: +16dBm minimum • 802.11g: +14dBm minimum • 802.11a: +14dBm minimum • 802.11n HT20(2.4GHz): +14dBm minimum • 802.11n HT40(2.4GHz): +12dBm minimum • 802.11n HT20(5GHz): +14dBm minimum
Models Roaming Output Power ²	Infrastructure (Access Point Required) IEEE 802.11 compliant roaming between access points • 802.11b:+16dBm minimum • 802.11g:+14dBm minimum • 802.11a:+14dBm minimum • 802.11n HT20(2.4GHz):+14dBm minimum • 802.11n HT40(2.4GHz):+12dBm minimum • 802.11n HT20(5GHz):+14dBm minimum • 802.11n HT40(5GHz):+12dBm minimum
Models Roaming	Infrastructure (Access Point Required) IEEE 802.11 compliant roaming between access points • 802.11b:+16dBm minimum • 802.11g:+14dBm minimum • 802.11a:+14dBm minimum • 802.11n HT20(2.4GHz):+14dBm minimum • 802.11n HT40(2.4GHz):+12dBm minimum • 802.11n HT20(5GHz):+14dBm minimum • 802.11n HT40(5GHz):+12dBm minimum Transmit: 2.0 W (max)
Models Roaming Output Power ²	Infrastructure (Access Point Required) IEEE 802.11 compliant roaming between access points • 802.11b:+16dBm minimum • 802.11g:+14dBm minimum • 802.11a:+14dBm minimum • 802.11n HT20(2.4GHz):+14dBm minimum • 802.11n HT40(2.4GHz):+12dBm minimum • 802.11n HT20(5GHz):+14dBm minimum • 802.11n HT40(5GHz):+12dBm minimum Transmit: 2.0 W (max) Receive: 1.6 W (max)
Models Roaming Output Power ²	Infrastructure (Access Point Required) IEEE 802.11 compliant roaming between access points • 802.11b: +16dBm minimum • 802.11g: +14dBm minimum • 802.11a: +14dBm minimum • 802.11n HT20(2.4GHz): +14dBm minimum • 802.11n HT40(2.4GHz): +12dBm minimum • 802.11n HT20(5GHz): +12dBm minimum • 802.11n HT40(5GHz): +12dBm minimum Transmit: 2.0 W (max) Receive: 1.6 W (max) Idle mode (PSP): 180 mW (WLAN Associated)
Models Roaming Output Power ²	Infrastructure (Access Point Required) IEEE 802.11 compliant roaming between access points • 802.11b: +16dBm minimum • 802.11g: +14dBm minimum • 802.11a: +14dBm minimum • 802.11n HT20(2.4GHz): +14dBm minimum • 802.11n HT40(2.4GHz): +12dBm minimum • 802.11n HT20(5GHz): +12dBm minimum • 802.11n HT40(5GHz): +12dBm minimum Transmit: 2.0 W (max) Receive: 1.6 W (max) Idle mode (PSP): 180 mW (WLAN Associated) Idle mode: 50 mW (WLAN unassociated)
Models Roaming Output Power ²	Infrastructure (Access Point Required) IEEE 802.11 compliant roaming between access points • 802.11b:+16dBm minimum • 802.11g:+14dBm minimum • 802.11a:+14dBm minimum • 802.11n HT20(2.4GHz):+14dBm minimum • 802.11n HT40(2.4GHz):+12dBm minimum • 802.11n HT20(5GHz):+12dBm minimum • 802.11n HT40(5GHz):+12dBm minimum Transmit: 2.0 W (max) Receive: 1.6 W (max) Idle mode (PSP): 180 mW (WLAN Associated) Idle mode: 50 mW (WLAN unassociated) Connect Standby: 10 mW (WLAN+BT)
Models Roaming Output Power ² Power Consumption	Infrastructure (Access Point Required) IEEE 802.11 compliant roaming between access points • 802.11b: +16dBm minimum • 802.11g: +14dBm minimum • 802.11a: +14dBm minimum • 802.11n HT20(2.4GHz): +14dBm minimum • 802.11n HT40(2.4GHz): +12dBm minimum • 802.11n HT20(5GHz): +12dBm minimum • 802.11n HT40(5GHz): +12dBm minimum Transmit: 2.0 W (max) Receive: 1.6 W (max) Idle mode (PSP): 180 mW (WLAN Associated) Idle mode: 50 mW (WLAN unassociated) Connect Standby: 10 mW (WLAN+BT) Radio disabled: 30 mW
Models Roaming Output Power ²	Infrastructure (Access Point Required) IEEE 802.11 compliant roaming between access points • 802.11b:+16dBm minimum • 802.11g:+14dBm minimum • 802.11a:+14dBm minimum • 802.11n HT20(2.4GHz):+14dBm minimum • 802.11n HT40(2.4GHz):+12dBm minimum • 802.11n HT20(5GHz):+14dBm minimum • 802.11n HT40(5GHz):+12dBm minimum Transmit: 2.0 W (max) Receive: 1.6 W (max) Idle mode (PSP): 180 mW (WLAN Associated) Idle mode: 50 mW (WLAN unassociated) Connect Standby: 10 mW (WLAN+BT) Radio disabled: 30 mW ACPI and PCI Express compliant power management
Models Roaming Output Power ² Power Consumption Power Management	Infrastructure (Access Point Required) IEEE 802.11 compliant roaming between access points • 802.11b:+16dBm minimum • 802.11g:+14dBm minimum • 802.11a:+14dBm minimum • 802.11n HT20(2.4GHz):+14dBm minimum • 802.11n HT40(2.4GHz):+12dBm minimum • 802.11n HT20(5GHz):+14dBm minimum • 802.11n HT40(5GHz):+12dBm minimum Transmit: 2.0 W (max) Receive: 1.6 W (max) Idle mode (PSP): 180 mW (WLAN Associated) Idle mode: 50 mW (WLAN unassociated) Connect Standby: 10 mW (WLAN+BT) Radio disabled: 30 mW ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Models Roaming Output Power ² Power Consumption	Infrastructure (Access Point Required) IEEE 802.11 compliant roaming between access points • 802.11b:+16dBm minimum • 802.11g:+14dBm minimum • 802.11a:+14dBm minimum • 802.11n HT20(2.4GHz):+14dBm minimum • 802.11n HT40(2.4GHz):+12dBm minimum • 802.11n HT20(5GHz):+14dBm minimum • 802.11n HT40(5GHz):+12dBm minimum Transmit: 2.0 W (max) Receive: 1.6 W (max) Idle mode (PSP): 180 mW (WLAN Associated) Idle mode: 50 mW (WLAN unassociated) Connect Standby: 10 mW (WLAN+BT) Radio disabled: 30 mW ACPI and PCI Express compliant power management 802.11 compliant power saving mode 802.11b, 1Mbps:-94dBm maximum
Models Roaming Output Power ² Power Consumption Power Management	Infrastructure (Access Point Required) IEEE 802.11 compliant roaming between access points • 802.11b:+16dBm minimum • 802.11g:+14dBm minimum • 802.11a:+14dBm minimum • 802.11n HT20(2.4GHz):+14dBm minimum • 802.11n HT40(2.4GHz):+12dBm minimum • 802.11n HT20(5GHz):+14dBm minimum • 802.11n HT40(5GHz):+12dBm minimum Transmit: 2.0 W (max) Receive: 1.6 W (max) Idle mode (PSP): 180 mW (WLAN Associated) Idle mode: 50 mW (WLAN unassociated) Connect Standby: 10 mW (WLAN+BT) Radio disabled: 30 mW ACPI and PCI Express compliant power management 802.11 compliant power saving mode 802.11b, 1Mbps:-94dBm maximum 802.11b, 11Mbps:-86dBm maximum
Models Roaming Output Power ² Power Consumption Power Management	Infrastructure (Access Point Required) IEEE 802.11 compliant roaming between access points • 802.11b:+16dBm minimum • 802.11g:+14dBm minimum • 802.11a:+14dBm minimum • 802.11n HT20(2.4GHz):+14dBm minimum • 802.11n HT40(2.4GHz):+12dBm minimum • 802.11n HT20(5GHz):+12dBm minimum • 802.11n HT40(5GHz):+12dBm minimum Transmit: 2.0 W (max) Receive: 1.6 W (max) Idle mode (PSP): 180 mW (WLAN Associated) Idle mode: 50 mW (WLAN unassociated) Connect Standby: 10 mW (WLAN+BT) Radio disabled: 30 mW ACPI and PCI Express compliant power management 802.11 compliant power saving mode 802.11b, 1Mbps:-94dBm maximum 802.11g, 6Mbps:-88dBm maximum
Models Roaming Output Power ² Power Consumption Power Management	Infrastructure (Access Point Required) IEEE 802.11 compliant roaming between access points • 802.11b: +16dBm minimum • 802.11g: +14dBm minimum • 802.11a: +14dBm minimum • 802.11n HT20(2.4GHz): +14dBm minimum • 802.11n HT40(2.4GHz): +12dBm minimum • 802.11n HT40(5GHz): +12dBm minimum • 802.11n HT40(5GHz): +12dBm minimum Transmit: 2.0 W (max) Receive: 1.6 W (max) Idle mode (PSP): 180 mW (WLAN Associated) Idle mode: 50 mW (WLAN unassociated) Connect Standby: 10 mW (WLAN+BT) Radio disabled: 30 mW ACPI and PCI Express compliant power management 802.11 compliant power saving mode 802.11b, 1Mbps: -94dBm maximum 802.11g, 6Mbps: -86dBm maximum 802.11g, 6Mbps: -74dBm maximum 802.11g, 54Mbps: -74dBm maximum
Models Roaming Output Power ² Power Consumption Power Management	Infrastructure (Access Point Required) IEEE 802.11 compliant roaming between access points 802.11b:+16dBm minimum 802.11g:+14dBm minimum 802.11a:+14dBm minimum 802.11n HT20(2.4GHz):+14dBm minimum 802.11n HT40(2.4GHz):+12dBm minimum 802.11n HT20(5GHz):+12dBm minimum 802.11n HT40(5GHz):+12dBm minimum Transmit: 2.0 W (max) Receive: 1.6 W (max) Idle mode (PSP): 180 mW (WLAN Associated) Idle mode: 50 mW (WLAN unassociated) Connect Standby: 10 mW (WLAN+BT) Radio disabled: 30 mW ACPI and PCI Express compliant power management 802.11 compliant power saving mode 802.11b, 1Mbps:-94dBm maximum 802.11g, 6Mbps:-88dBm maximum 802.11g, 54Mbps:-74dBm maximum 802.11a, 6Mbps:-88dBm maximum
Models Roaming Output Power ² Power Consumption Power Management	Infrastructure (Access Point Required) IEEE 802.11 compliant roaming between access points • 802.11b:+16dBm minimum • 802.11g:+14dBm minimum • 802.11a:+14dBm minimum • 802.11n HT20(2.4GHz):+14dBm minimum • 802.11n HT40(2.4GHz):+12dBm minimum • 802.11n HT20(5GHz):+12dBm minimum • 802.11n HT40(5GHz):+12dBm minimum Transmit: 2.0 W (max) Receive: 1.6 W (max) Idle mode (PSP): 180 mW (WLAN Associated) Idle mode: 50 mW (WLAN unassociated) Connect Standby: 10 mW (WLAN+BT) Radio disabled: 30 mW ACPI and PCI Express compliant power management 802.11 compliant power saving mode 802.11b, 1Mbps:-94dBm maximum 802.11g, 6Mbps:-88dBm maximum 802.11g, 54Mbps:-74dBm maximum 802.11a, 54Mbps:-74dBm maximum 802.11a, 54Mbps:-74dBm maximum
Models Roaming Output Power ² Power Consumption Power Management	Infrastructure (Access Point Required) IEEE 802.11 compliant roaming between access points • 802.11b: +16dBm minimum • 802.11g: +14dBm minimum • 802.11a: +14dBm minimum • 802.11n HT20(2.4GHz): +14dBm minimum • 802.11n HT40(2.4GHz): +12dBm minimum • 802.11n HT20(5GHz): +12dBm minimum • 802.11n HT40(5GHz): +12dBm minimum Transmit: 2.0 W (max) Receive: 1.6 W (max) Idle mode (PSP): 180 mW (WLAN Associated) Idle mode: 50 mW (WLAN unassociated) Connect Standby: 10 mW (WLAN+BT) Radio disabled: 30 mW ACPI and PCI Express compliant power management 802.11 compliant power saving mode 802.11b, 1Mbps: -94dBm maximum 802.11b, 11Mbps: -86dBm maximum 802.11g, 6Mbps: -88dBm maximum 802.11a, 54Mbps: -74dBm maximum 802.11n, MCS07: -69dBm maximum
Models Roaming Output Power ² Power Consumption Power Management	Infrastructure (Access Point Required) IEEE 802.11 compliant roaming between access points • 802.11b:+16dBm minimum • 802.11g:+14dBm minimum • 802.11a:+14dBm minimum • 802.11n HT20(2.4GHz):+14dBm minimum • 802.11n HT40(2.4GHz):+12dBm minimum • 802.11n HT20(5GHz):+12dBm minimum • 802.11n HT40(5GHz):+12dBm minimum Transmit: 2.0 W (max) Receive: 1.6 W (max) Idle mode (PSP): 180 mW (WLAN Associated) Idle mode: 50 mW (WLAN unassociated) Connect Standby: 10 mW (WLAN+BT) Radio disabled: 30 mW ACPI and PCI Express compliant power management 802.11 compliant power saving mode 802.11b, 1Mbps:-94dBm maximum 802.11g, 6Mbps:-88dBm maximum 802.11g, 54Mbps:-74dBm maximum 802.11a, 54Mbps:-74dBm maximum 802.11a, 54Mbps:-74dBm maximum

	1				
	802.11ac, 1SS, MC				
	802.11ac, 2SS, MC				
		802.11ac, 2SS, MCS-9: -58dBm maximum			
Antenna type	High efficiency antenna with spatial diversity, mounted in the			he	
	display enclosure				
			z antennas are provided		
		LAN MIMO commu	inications and Bluetooth	l®	
	communications				
Form Factor	PCI-Express M.2 M				
Dimensions	Type 2230 : 2.3 x 2	22.0 x 30.0 mm			
	Or				
Int. * - I. a	Type 1630 : 2.3 x 1	16.0 X 30.0 mm			
Weight	Type 2230 : 2.8g				
	Or 1630 3-				
On custing Voltage	Type 1630 : 2g				
Operating Voltage	3.3v +/- 9%	140+-15005/	100 to 700 C)		
Temperature	Operating	14° to 158° F (–	·		
U	Non-operating	-40° to 176° F (
Humidity	Operating Non-operating	10% to 90% (no	3		
Altitude	Operating	0 to 10,000 ft (3	·		
Attitude	Non-operating	0 to 10,000 ft (3			
LED Activity	LED Amber – Radi				
1. Check latest software/driv					
2. Maximum output power n					
3. Receiver sensitivity is mea				n) and a	
packet error rate of 10% f			oz. i ib (CKK illoudiatioi	ii) aiiu a	
HP Integrated Module with Blueto					
		tess recliliology			
		ant			
Bluetooth® Specification	4.0/4.1/4.2 Compli	ant			
Bluetooth® Specification Frequency Band	4.0/4.1/4.2 Compliance 2402 to 2480 MHz				
Bluetooth® Specification	4.0/4.1/4.2 Compliance 2402 to 2480 MHz Legacy: 0~79 (1 MI)	Hz/CH)			
Bluetooth® Specification Frequency Band Number of Available Channels	4.0/4.1/4.2 Compliance 2402 to 2480 MHz	Hz/CH)			
Bluetooth® Specification Frequency Band	4.0/4.1/4.2 Compliance 2402 to 2480 MHz Legacy: 0~79 (1 MI)	Hz/CH) CH)	ut up to 2.17 Mbps		
Bluetooth® Specification Frequency Band Number of Available Channels	4.0/4.1/4.2 Complia 2402 to 2480 MHz Legacy : 0~79 (1 MI BLE : 0~39 (2 MHz/0	Hz/CH) CH) ta rate; throughpu			
Bluetooth® Specification Frequency Band Number of Available Channels	4.0/4.1/4.2 Complication 2402 to 2480 MHz Legacy: 0~79 (1 MHBLE: 0~39 (2 MHz/0 Legacy: 3 Mbps data reference to the second sec	Hz/CH) CH) ta rate; throughpu ate; throughput u	p to 0.2 Mbps	kbps,	
Bluetooth® Specification Frequency Band Number of Available Channels	4.0/4.1/4.2 Complication 2402 to 2480 MHz Legacy: 0~79 (1 MHBLE: 0~39 (2 MHz/0 Legacy: 3 Mbps data reference to the second sec	Hz/CH) CH) ta rate; throughpu ate; throughput u		kbps,	
Bluetooth® Specification Frequency Band Number of Available Channels	4.0/4.1/4.2 Complication 2402 to 2480 MHz Legacy: 0~79 (1 Missing 1985) BLE: 0~39 (2 MHz/0 Legacy: 3 Mbps data re Legacy: Synchrono voice channels	Hz/CH) CH) ta rate; throughpu ate; throughput u uus Connection Ori	p to 0.2 Mbps iented links up to 3, 64 k		
Bluetooth® Specification Frequency Band Number of Available Channels Data Rates and Throughput	4.0/4.1/4.2 Complication 2402 to 2480 MHz Legacy: 0~79 (1 MHz) Legacy: 3 Mbps data rows a superior of the su	Hz/CH) CH) ta rate; throughpu ate; throughput u ous Connection Ori	p to 0.2 Mbps iented links up to 3, 64 k erate as a Class II Blueto	oth [®]	
Bluetooth® Specification Frequency Band Number of Available Channels Data Rates and Throughput Transmit Power	4.0/4.1/4.2 Complication 2402 to 2480 MHz Legacy: 0~79 (1 MHz) Legacy: 3 Mbps data results and the second control of the second co	Hz/CH) CH) ta rate; throughpu ate; throughput u ous Connection Ori nponent shall ope num transmit pov	p to 0.2 Mbps iented links up to 3, 64 k erate as a Class II Blueto ver of +4 dBm for BR an	oth [®]	
Bluetooth® Specification Frequency Band Number of Available Channels Data Rates and Throughput	4.0/4.1/4.2 Complication 2402 to 2480 MHz Legacy: 0~79 (1 MHz) Legacy: 3 Mbps data results and the second s	Hz/CH) CH) ta rate; throughpu ate; throughput u ous Connection Ori mponent shall ope mum transmit pov 0.01% BER	p to 0.2 Mbps iented links up to 3, 64 k erate as a Class II Blueto ver of +4 dBm for BR an 0.001% BER	oth [®]	
Bluetooth® Specification Frequency Band Number of Available Channels Data Rates and Throughput Transmit Power	4.0/4.1/4.2 Complication 2402 to 2480 MHz Legacy: 0~79 (1 MHz) Legacy: 3 Mbps data results and the second s	Hz/CH) CH) ta rate; throughput unus Connection Orienter mponent shall openum transmit pover 1-80 dBm	p to 0.2 Mbps iented links up to 3, 64 kerate as a Class II Blueto ver of +4 dBm for BR an 0.001% BER -70 dBm	oth [®]	
Bluetooth® Specification Frequency Band Number of Available Channels Data Rates and Throughput Transmit Power	4.0/4.1/4.2 Complication 2402 to 2480 MHz Legacy: 0~79 (1 MHz) Legacy: 3 Mbps data rows a superior of the s	Hz/CH) CH) ta rate; throughpu ate; throughput u ous Connection Ori mponent shall ope mum transmit pov 0.01% BER -80 dBm -80 dBm	p to 0.2 Mbps iented links up to 3, 64 kerate as a Class II Blueto ver of +4 dBm for BR and 0.001% BER -70 dBm -70 dBm	oth [®]	
Bluetooth® Specification Frequency Band Number of Available Channels Data Rates and Throughput Transmit Power Receiver Sensitivity	4.0/4.1/4.2 Complice 2402 to 2480 MHz Legacy: 0~79 (1 MHz) Legacy: 3 Mbps data BLE: 1 Mbps data rate Legacy: Synchrono voice channels The Bluetooth® cordevice with a maxin Modulation GFSK π/4-DQPSK 8DPSK	Hz/CH) CH) ta rate; throughput unus Connection Orienter mponent shall openum transmit pover 1-80 dBm	p to 0.2 Mbps iented links up to 3, 64 kerate as a Class II Blueto ver of +4 dBm for BR an 0.001% BER -70 dBm	oth [®]	
Bluetooth® Specification Frequency Band Number of Available Channels Data Rates and Throughput Transmit Power	4.0/4.1/4.2 Complice 2402 to 2480 MHz Legacy: 0~79 (1 MHz) Legacy: 3 Mbps data BLE: 1 Mbps data range of the Bluetooth® corrected with a maxim Modulation GFSK π/4-DQPSK 8DPSK Peak (Tx) 330 mW	Hz/CH) CH) ta rate; throughpu ate; throughput u ous Connection Ori mponent shall ope mum transmit pov 0.01% BER -80 dBm -80 dBm	p to 0.2 Mbps iented links up to 3, 64 kerate as a Class II Blueto ver of +4 dBm for BR and 0.001% BER -70 dBm -70 dBm	oth [®]	
Bluetooth® Specification Frequency Band Number of Available Channels Data Rates and Throughput Transmit Power Receiver Sensitivity	4.0/4.1/4.2 Complication 2402 to 2480 MHz Legacy: 0~79 (1 MHz) Legacy: 3 Mbps data results and the second control of the second co	Hz/CH) CH) ta rate; throughput unus Connection Orienters shall openum transmit pover the content of the content	p to 0.2 Mbps iented links up to 3, 64 kerate as a Class II Blueto ver of +4 dBm for BR and 0.001% BER -70 dBm -70 dBm	oth [®]	
Bluetooth® Specification Frequency Band Number of Available Channels Data Rates and Throughput Transmit Power Receiver Sensitivity Power Consumption	4.0/4.1/4.2 Complice 2402 to 2480 MHz Legacy: 0~79 (1 MHz) Legacy: 3 Mbps data rown and the second and the sec	Hz/CH) CH) ta rate; throughput uses Connection Orion mponent shall open mum transmit pov O.01% BER -80 dBm -80 dBm -80 dBm -80 dBm	p to 0.2 Mbps iented links up to 3, 64 kerate as a Class II Blueto ver of +4 dBm for BR and 0.001% BER -70 dBm -70 dBm	oth [®]	
Bluetooth® Specification Frequency Band Number of Available Channels Data Rates and Throughput Transmit Power Receiver Sensitivity	4.0/4.1/4.2 Compliance 2402 to 2480 MHz Legacy: 0~79 (1 MHz Legacy: 3 Mbps data results and the second voice channels The Bluetooth® condevice with a maximal modulation GFSK π/4-DQPSK 8DPSK Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend of the second voice channels	Hz/CH) CH) ta rate; throughput us connection Orion of the connection of the connecti	p to 0.2 Mbps iented links up to 3, 64 kerate as a Class II Blueto ver of +4 dBm for BR and 0.001% BER -70 dBm -70 dBm	oth [®]	
Bluetooth® Specification Frequency Band Number of Available Channels Data Rates and Throughput Transmit Power Receiver Sensitivity Power Consumption Range	4.0/4.1/4.2 Complice 2402 to 2480 MHz Legacy: 0~79 (1 MHz) Legacy: 3 Mbps data results and results an	Hz/CH) CH) ta rate; throughput us connection Orion of the connection of the connecti	p to 0.2 Mbps iented links up to 3, 64 kerate as a Class II Blueto ver of +4 dBm for BR and 0.001% BER -70 dBm -70 dBm	oth [®]	
Bluetooth® Specification Frequency Band Number of Available Channels Data Rates and Throughput Transmit Power Receiver Sensitivity Power Consumption Range Electrical Interface	4.0/4.1/4.2 Compliant 2402 to 2480 MHz Legacy: 0~79 (1 MHz) BLE: 0~39 (2 MHz/θ Legacy: 3 Mbps data results and re	Hz/CH) CH) ta rate; throughput unus Connection Orion mponent shall openum transmit povo 0.01% BER -80 dBm -80 dBm -80 dBm -80 dBm 17 mW (10 m) m)	p to 0.2 Mbps iented links up to 3, 64 k erate as a Class II Blueto ver of +4 dBm for BR an 0.001% BER -70 dBm -70 dBm -70 dBm	oth [®]	
Bluetooth® Specification Frequency Band Number of Available Channels Data Rates and Throughput Transmit Power Receiver Sensitivity Power Consumption Range Electrical Interface Bluetooth® Software Supported	4.0/4.1/4.2 Complice 2402 to 2480 MHz Legacy: 0~79 (1 MHz) Legacy: 3 Mbps data results and results an	Hz/CH) CH) ta rate; throughput unus Connection Orion mponent shall openum transmit povo 0.01% BER -80 dBm -80 dBm -80 dBm -80 dBm 17 mW (10 m) m)	p to 0.2 Mbps iented links up to 3, 64 k erate as a Class II Blueto ver of +4 dBm for BR an 0.001% BER -70 dBm -70 dBm -70 dBm	oth [®]	
Bluetooth® Specification Frequency Band Number of Available Channels Data Rates and Throughput Transmit Power Receiver Sensitivity Power Consumption Range Electrical Interface Bluetooth® Software Supported Link Topology	4.0/4.1/4.2 Compliant 2402 to 2480 MHz Legacy: 0~79 (1 MHz) BLE: 0~39 (2 MHz/θ Legacy: 3 Mbps data results and re	Hz/CH) CH) ta rate; throughput unus Connection Orion mponent shall openum transmit povo 0.01% BER -80 dBm -80 dBm -80 dBm -80 dBm 17 mW (10 m) m)	p to 0.2 Mbps iented links up to 3, 64 k erate as a Class II Blueto ver of +4 dBm for BR an 0.001% BER -70 dBm -70 dBm -70 dBm	oth [®]	
Bluetooth® Specification Frequency Band Number of Available Channels Data Rates and Throughput Transmit Power Receiver Sensitivity Power Consumption Range Electrical Interface Bluetooth® Software Supported Link Topology Electrical Interface	4.0/4.1/4.2 Compliant 2402 to 2480 MHz Legacy: 0~79 (1 MHz) BLE: 0~39 (2 MHz/θ Legacy: 3 Mbps data results and re	Hz/CH) CH) ta rate; throughpu use; throughput uses Connection Orion ponent shall openum transmit power of the control of the c	p to 0.2 Mbps iented links up to 3, 64 kerate as a Class II Blueto ver of +4 dBm for BR and 0.001% BER -70 dBm -70 dBm -70 dBm	oth [®]	
Bluetooth® Specification Frequency Band Number of Available Channels Data Rates and Throughput Transmit Power Receiver Sensitivity Power Consumption Range Electrical Interface Bluetooth® Software Supported Link Topology	4.0/4.1/4.2 Compliant 2402 to 2480 MHz Legacy: 0~79 (1 MHz Legacy: 3 Mbps data results and results an	Hz/CH) CH) ta rate; throughput us connection Orion ponent shall openum transmit power of the content of the con	p to 0.2 Mbps iented links up to 3, 64 kerate as a Class II Blueto ver of +4 dBm for BR and 0.001% BER -70 dBm -70 dBm -70 dBm	oth [®]	

Technical Specifications – Networking and Communications

Security			
Power Management	Microsoft Windows ACPI, and USB Bus Support		
Power Management Certifications	Self-configurable to optimize power conservation in all operating modes, including Standby, Hold, Park, and Sniff		
Security	All necessary regulatory approvals for supported countries, including:		
Certifications Bluetooth® Profiles Supported	FCC (47 CFR) Part 15C, Section 15.247 & 15.249		
Power Management	ETS 300 328, ETS 300 826		
Certifications	Low Voltage Directive IEC950		
	UL, CSA, and CE Mark		
Certifications Bluetooth® Profiles Supported	UL, CSA, and CE Mark Serial Port Profile (SPP)1.2 Service Discovery Application Profile (SDAP) Dial-Up Networking (DUN)1,1 Generic Object Exchange Profile (GOEP)1,2 Object Push Profile (OPP)1,2 Hard Copy Cable Replacement (HCRP)1,2 Personal Area Networking Profile (PAN)1.0 Human Interface Device Profile (HID)1.0 Hands Free Profile (HFP) 1.5/1.6 Advanced Audio Distribution Profile (A2DP) 1.3 Audio Video Remote Control Profile (AVRCP) 1.3/1.4		
Bluetooth® V4.1/V4.2 support	V4.1: ESR5/6/7 compliant		
feature	V4.2: ESR8 compliant, LE Secure Connection – Basic		

*Wireless access point and internet access required. Availability of public wireless access points limited. The specifications for the 802.11ac WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices.

Intel® 7265 802.11ac 2x2 DualBand Combo PCIe x1 Card		
Wireless LAN Standards	IEEE 802.11a	
	IEEE 802.11b	
	IEEE 802.11g	
	IEEE 802.11n	
	IEEE 802.11ac	
Interoperability	Wi-Fi certified	
Frequency Band	802.11b/g/n	
	• 2.402 – 2.482 GHz	
	Note:	
	The FCC has declared as of January 1, 2015 products that utilize	
	passive scanning on channel 12/13 and are capable of	
	transmitting must fully comply with requirements of 15.247 or	
	otherwise disable those channels.	
	802.11a/n	
	• 4.9 – 4.95 GHz (Japan)	
	• 5.15 – 5.25 GHz	
	• 5.25 – 5.35 GHz	
	• 5.47 – 5.725 GHz	
	• 5.825 – 5.850 GHz	
	Note: Indonesia no support this band)	
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps	

recrimed specifications Tree	working and commi	
		• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
		• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
		 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
		 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz,
		and 80MHz)
Modulation		Direct Sequence Spread Spectrum
		BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
Security ¹		• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g
		mode only
		AES-CCMP: 128 bit in hardware
		802.1x authentication
		• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
		WPA2 certification
		• IEEE 802.11i
		Cisco Certified Extensions, all versions through CCX4 and CCX
		Lite
		• WAPI
Network Arc	hitecture	Ad-hoc (Peer to Peer)
Models		Infrastructure (Access Point Required)
Roaming		IEEE 802.11 compliant roaming between access points
Output Power	er ²	802.11b: +16dBm minimum
-		• 802.11g: +14dBm minimum
		• 802.11a:+14dBm minimum
		802.11n HT20(2.4GHz): +13dBm minimum
		• 802.11n HT40(2.4GHz): +13dBm minimum
		• 802.11n HT20(5GHz): +12dBm minimum
		• 802.11n HT40(5GHz): +12dBm minimum
		802.11ac 80MHz(5GHz): +11dBm minimum
Power Consu	ımntion	Transmit: 2.0 W (max)
1 ower const	·····ption	Receive: 1.6 W (max)
		Idle mode (PSP): 180 mW (WLAN Associated)
		Idle mode: 60 mW (WLAN unassociated)
		Radio disabled: 30 mW
Power Mana	gement	ACPI and PCI Express compliant power management
		802.11 compliant power saving mode
Receiver Ser	nsitivity³	802.11b, 1Mbps : -94dBm maximum
		802.11b, 11Mbps : -86dBm maximum
		802.11g, 6Mbps : -88dBm maximum
		802.11g, 54Mbps : -74dBm maximum
		802.11a, 6Mbps : -86dBm maximum
		802.11a, 54Mbps : -72dBm maximum
		802.11n, MCS07 : -69dBm maximum
		802.11n, MCS15 : -66dBm maximum
		802.11ac, 1SS, MCS-0 : -86dBm maximum
		802.11ac, 1SS, MCS-9 : -61dBm maximum
		802.11ac, 2SS, MCS-0 : -83dBm maximum
A		802.11ac, 2SS, MCS-9: -58dBm maximum
Antenna typ	e	High efficiency antenna with spatial diversity, mounted in the
		display enclosure
		Two embedded dual band 2.4/5 GHz antennas are provided to the
		card to support WLAN MIMO communications and Bluetooth®
Faum Factor		communications DCL Everyors M. 2. MiniCard
Form Factor		PCI-Express M.2 MiniCard
Dimensions		Type 2230 : 2.3 x 22.0 x 30.0 mm

	Or			
	Or Type 1630 : 2 3 v 1	6 0 v 30 0 mm		
Weight	Type 1630 : 2.3 x 16.0 x 30.0 mm Type 2230 : 2.8g			
weight	Type 2230 : 2.8g Or			
	Type 1630 : 2g			
Operating Voltage	3.3v +/- 9%			
Temperature	Operating 14° to 158° F (–10° to 70° C)			
1 Simporution C	Non-operating	-40° to 176° F (-	•	
Humidity	Operating	10% to 90% (nor		
	Non-operating			
Altitude	Operating	0 to 10,000 ft (3,		
	Non-operating	0 to 50,000 ft (1		
LED Activity	LED Amber – Radio	o OFF; LED White –	Radio ON	
4. Check latest software/drive	r release for updates	on supported sec	urity features.	
5. Maximum output power ma	y vary by country acc	cording to local reg	gulations.	
6. Receiver sensitivity is meas			2.11b (CKK modulation	on) and
a packet error rate of 10% f				
HP Integrated Module with Bluetoot	h® 4.2 Wireless Tech	nnology		
Bluetooth® Specification	4.2 Compliant			
Frequency Band	2402 to 2480 MHz			
Number of Available Channels	79 (1 MHz) available	e channels		
Data Rates and Throughput	3 Mbps data rate; th		17 Mhns	
butu Nutes unu i mougnput	-	<u> </u>	•	vico
	Synchronous Connection Oriented links up to 3, 64 kbps, voice channels			
	Asynchronous Connection Less links 2178.1 kbps/177.1 kbps			
	asymmetric or 1306.9 kbps symmetric			μs
Transmit Power	The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum transmit power of +4 dBm for BR and EDR.			ooth®
Transmit rower				
Receiver Sensitivity	Modulation Modulation	0.01% BER	0.001% BER	
Receiver Sensitivity	GFSK	-80 dBm	-70 dBm	
	π/4-DQPSK	-80 dBm	-70 dBm	
	8DPSK	-80 dBm	-70 dBm	
Power Consumption	Peak (Tx) 330 mW	OO UDIII	70 00111	
rowei Consumption	Peak (Rx) 230 mW			
	Selective Suspend 1	I7 mW		
Range	Up to 33 ft (10 m)			
Electrical Interface	USB 2.0 compliant			
Bluetooth® Software Supported	Microsoft Windows	Pluotooth® Coftuu		
Link Topology	MICIOSOIT WINDOWS	bluelooth 301tw	are	
Electrical Interface	Point to Point, Mult	ingint Dica Note un	to 7 claves	
Bluetooth® Software Supported				
Security	Full support of Blue	tootn [®] Security Pr	OVISIONS	
Power Management	Microsoft Windows ACDL and UCD Due Connect			
Power Management	Microsoft Windows ACPI, and USB Bus Support			rating
Certifications	Self-configurable to optimize power conservation in all operati modes, including Standby, Hold, Park, and Sniff		erauny	
			r supported countries	
Security	including:	atory approvats for	supported countries	,
Contifications		EC Costion 15 347	9 15 240	
Certifications	FCC (47 CFR) Part 1!	oc, section 15.24/	α 13.249	
Willotocok(#) Ducotiles Elicocuted				
Bluetooth® Profiles Supported	ETC 200 220 ETC 2	00.036		
Bluetooth® Profiles Supported Power Management Certifications	ETS 300 328, ETS 3 Low Voltage Directi			

Certifications Bluetooth® Profiles Supported	UL, CSA, and CE Mark Serial Port Profile (SPP) ¹ Service Discovery Application Profile (SDAP) Dial-Up Networking (DUN) ^{1,2} Generic Object Exchange Profile (GOEP) ^{1,2} Object Push Profile (OPP) ^{1,2} File Transfer Profile (FTP) Synchronization Profile (SYNC) Hard Copy Cable Replacement (HCRP) ^{1,2} Personal Area Networking Profile (PAN) ^{1,2} Human Interface Device Profile (HID) ^{1,2} FAX Profile (FAX) Basic Imaging Profile (BIP) ²

Intel® 3168 802.11a	c with PCle x1 V	VLAN/ Bluetooth® Combo*	
Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac		
Interoperability	Wi-Fi certification		
Frequency Bands	802.11b/g/n	2.402 – 2.482 GHz Note: The FCC has declared as of January 1, 2015 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.	
	802.11a/n	4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz Note: Indonesia only supports 5.725 - 5.825 GHz (CH149 - CH161)	
Data Rates	 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) 802.11ac: MCS0 ~ MCS7, (1SS) (20MHz, 40MHz, and 80MHz) 		
Modulation	Direct Seque	nce Spread Spectrum	



	BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM	
Security ¹	 IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification IEEE 802.11i Cisco Certified Extensions, all versions through CCX4 and CCX Lite WAPI 	
	¹ Check latest software/driver release for updates on supported security features.	
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)	
Roaming	802.11r Fast Roaming	
Output Power ²	 802.11b: +16dBm minimum 802.11g: +14dBm minimum 802.11a: +14dBm minimum 802.11n HT20(2.4GHz): +14dBm minimum 802.11n HT40(2.4GHz): +12dBm minimum 802.11n HT20(5GHz): +14dBm minimum 802.11n HT40(5GHz): +12dBm minimum 802.11ac 80MHz(5GHz): +11dBm minimum 	
	² Maximum output power may vary by country according to local regulations.	
Power Consumption	Transmit: 2.0 W (max) Receive: 1.6 W (max) Idle mode (PSP): 180 mW (WLAN Associated) Idle mode: 50 mW (WLAN unassociated) Connect Standby: 10 mW (WLAN+BT) Radio disabled: 5 mW	
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode	
Receiver Sensitivity ³	802.11b, 1Mbps: -94dBm maximum 802.11b, 11Mbps: -86dBm maximum 802.11g, 6Mbps: -88dBm maximum 802.11g, 54Mbps: -74dBm maximum 802.11a, 6Mbps: -88dBm maximum 802.11a, 54Mbps: -74dBm maximum 802.11a, 54Mbps: -74dBm maximum 802.11n, MCS07: -69dBm maximum 802.11n, MCS15: -66dBm maximum 802.11ac, 1SS, MCS-0: -86dBm maximum 802.11ac, 1SS, MCS-9: -61dBm maximum	



	802.11ac, 2SS, MCS-9 : -58dBm maximum 802.11ac, 2SS, MCS-9 : -58dBm maximum		
	³ Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).		
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth® communications		
Form Factors	PCI-Express M.2 MiniCard		
Dimensions	Type 2230 : 2.3 x 22.0 x 30.0 mm Or Type 1630 : 2.3 x 16.0 x 30.0 mm		
Weight	Type 2230 : 2.8g Or Type 1630 : 2g		
Operating Voltage	3.3v +/- 9%		
Temperature	Operating: Non-operating:	14° to 158° F (-10° to 70° C) -40° to 176° F (-40° to 80° C)	
Humidity	Operating: Non-operating:	10% to 90% (non-condensing) 5% to 95% (non-condensing)	
Altitude	Operating: Non-operating:	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)	
LED Activity	LED Amber – Radio OFF; LED White – Radio ON		
Wireless access point and Inte	rnet service required and not included. <i>I</i>	Availability of public wireless access points limited.	
HP Integrated Module with Bl	uetooth® 4.0/4.1/4.2 Wireless Technol	ogy	
Bluetooth® Specification	4.0/4.1/4.2 Compliant		
Frequency Band	2402 to 2480 MHz		
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)		
	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps		
Data Rates and Throughput			



	Legacy : Asynchrono 864 kbps symmetric		s links 2178.1 kbps/1	77.1 kbps asymmetric (3-DH5) or
Transmit Power	The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum transmit power of + 4 dBm for BR and EDR.			
Receiver Sensitivity	Modulation	0.01% BER	0.001% BER	
Legacy	GFSK	-80 dBm	-70 dBm	
	π/4-DQPSK	-80 dBm	-70 dBm	
	8DPSK	-80 dBm	-70 dBm	
Power Consumption	Peak (Tx) 330 mW			
	Peak (Rx) 230 mW Selective Suspend 1	7 mW		
 Range	Legacy Up to 33 ft (1			
	BLE Up to 99 ft (30 n			
Electrical Interface	USB 2.0 compliant			
Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth® Software			
Electrical Interface Bluetooth® Software Supported Security	Point to Point, Multipoint Pico Nets up to 7 slaves			
	Full support of Bluet	Full support of Bluetooth® Security Provisions		
Power Management Certifications	Microsoft Windows ACPI, and USB Bus Support			
	Self-configurable to optimize power conservation in all operating modes, including Standby, Hold, Park, and Sniff			
Security	All necessary regulatory approvals for supported countries, including:			
Certifications Bluetooth® Profiles Supported	FCC (47 CFR) Part 15C, Section 15.247 & 15.249			
Power Management Certifications	ETS 300 328, ETS 300 826			
	Low Voltage Directiv	ve IEC950		
Certifications	UL, CSA, and CE Mark			
Bluetooth® Profiles Supported	Serial Port Profile (SPP) ¹ Service Discovery Application Profile (SDAP) Dial-Up Networking (DUN) ^{1,2} Generic Object Exchange Profile (GOEP) ^{1,2}			



	Object Push Profile (OPP) ^{1,2} Hard Copy Cable Replacement (HCRP) ^{1,2} Personal Area Networking Profile (PAN) ^{1,2} Human Interface Device Profile (HID) ^{1,2} Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)
	Audio Video Remote Control Profile (AVRCP)
Bluetooth® V4.1/V4.2 support	V4.1: ESR5/6/7 compliant
feature	V4.2: ESR8 compliant, LE Secure Connection – Basic.



Technical Specifications - Audio

AUDIO

High Definition Audio – MT/SFF/DM

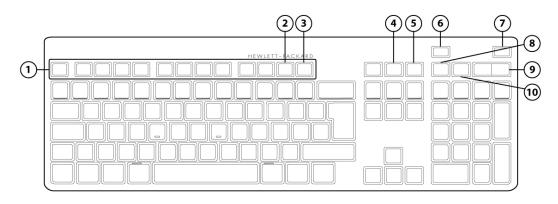
Туре	Integrated		
HD Stereo Codec	Conexant CX20632		
Audio I/O Ports	Headset connector supports a CTIA style headset and is re-taskable as a Line-in, Line-out, Microphone-in or Headphone-out port		
	Rear Line-In can be retasked to function as a microphone input		
	Rear Line-Out		
	All ports are 3.5mm and support stereo (see above tables for system configurations)		
Internal Speaker Amplifier	2W class D mono amplifier for the internal speaker only External speakers must be powered externally.		
Multi-streaming Capable	Playback multi-streaming can be enabled in the audio control panel to allow independent audio streams to be sent to/from the front and rear jacks or integrated speaker.		
Sampling	Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC		
Wavetable Syntheses	Yes – Uses OS soft wavetable		
Analog Audio	Yes		
# of Channels on Line-Out	Stereo (Left & Right channels)		
Internal Mono Speaker	Yes		



Technical Specifications - Input/Output Devices

INPUT/OUTPUT DEVICES

HP Conferencing Keyboard



1.	Function Keys		6.	End/Decline a Call
2.	F11 Lync or Skype for Business Contact list *		7.	Answer a Call
3.	F12 Lync or Skype for Business Calendar **		8.	Microphone Mute
4.	Share Screen		9.	Volume Up/Down
5.	Stop Webcam		10.	Audio Mute
*M	icrosoft Lync 2013, or Skype fo	or Business, or Microsoft Outlook 2013	Conta	ct list
**M	icrosoft Lync 2013, or Skype fo	or Business, or Microsoft Outlook 2013	Calen	dar
Dimensions (H x L x W) 0.85 x 17.34 x 6.10 in (2.16 x 44.		0.85 x 17.34 x 6.10 in (2.16 x 44.05 x	(15.50	cm)
Wei	eight 24.69 oz. (700 g)			
Con	nectivity	USB cable		
Key	s	110 (US) Layout, 111 (EU) Layout – depending upon country		ing upon country
Fea	ture Summary	Full-size ultra-quiet keyboard with numerical pad and 12 function keys One-touch simplicity for Microsoft Lync or Skype for Business calls with dedicated keys and LED light indicators		
Illui	minated keys	Incoming Call – Blinks Green Call in progress –Green Microphone Mute – Orange Audio Mute – Orange Screen Sharing – Orange Stop Webcam – Orange		
0th	er Call control keys	End/Decline Call		



	Volume up and down rocker key
Microsoft Lync/Outlook	Fn+F12 – Lync or Skype for Business Calendar will open. If Lync or Skype for Business is not available will bring Outlook Calendar * Fn+F11 – Lync or Skype for Business Contact will open. If Lync or Skype for Business is not available will bring Outlook Contact list *
	* Fn+11 and Fn+12 function keys are not supported in Microsoft Windows 8.x Metro mode
Functions Keys	Fn+F10 – System Settings Fn+F9 – Devices Fn+F8 – Search Fn+F7 – Blank Fn+F6 – Up Brightness Adjustment Fn+F5 – Down Brightness Adjustment Fn+F4 – Display Options Fn+F3 – File Explorer Fn+F2 – System Lock Fn+F1 – System Sleep
System requirements	Available USB port Windows 7, Windows 8.x, and Windows 10 Server: Microsoft Lync Server 2010 or 2013 and Skype for Business Server 2015 Client: Microsoft Lync 2013 version 15.0.46xx or newer or Skype for Business Notes: • Limited support for Microsoft Lync 2010, Microsoft Lync 2013 Basic and Microsoft Metro Mode • Screen brightness functions supported in select HP systems
Approvals EMC Product Safety	FCC; CE; ACA(C-tick); EAC UL, CE Mark

HP USB PS/2 Washable Keyboard			
Physical Characteristics	Keys	104 (US) Layout, 105 (EU) layout – depending upon country	
	Dimensions (L x W x H)	17.67x 6.62 x 1.38 in (449 x 168 x 35 mm)	
	Weight	1.7 lb (0.77 kg) minimum	
	Operating voltage	+ 5VDC ±5%	
	Power consumption	50-mA maximum (with three LEDs ON)	
Electrical	System interface	USB Type A plug connector	
Electrical	ESD	CE level 4, 15-kV air discharge	
	EMI - RFI	Conforms to FCC rules for a Class B computing device	
	Microsoft PC 99 - 2001	Functionally compliant	
Mechanical	Keycaps	Stepped -profile design	



	Switch actuation	55-g nominal peak force with tactile feedback	
	Switch life	20 million keystrokes	
	Switch type	Contamination-resistant switch membrane	
	Key-leveling mechanisms	For all double-wide and greater-length keys	
	Cable length	7 ft (2.2 m)	
	Microsoft PC 99 - 2001	Mechanically compliant	
	Acoustics	43-dBA maximum sound pressure level	
	Operating temperature	50° to 122° F (10° to 50° C)	
	Non-operating temperature	4° to 149° F (-20° to 65° C)	
	Operating humidity	10% to 95% (non-condensing at ambient)	
	Non-operating humidity	0% to 95% (non-condensing at ambient)	
	Operating shock	40 g, six surfaces	
Environmental	Non-operating shock	80 g, six surfaces	
	Operating vibration	2-g peak acceleration	
	Non-operating vibration	4-g peak acceleration	
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence	
	Drop (in box)	42 in (107 cm) on concrete, 16-drop sequence	
Operating system support	Windows® 7, Windows Vista, Windows XP Professional		
Approvals	UL, cUL, FCC, CE, TUV GS, VCCI, BSMI, C-Tick, KCC, USB-IF, WHQL, EN/IEC 60601-1, IP66/NEMA4X		
Ergonomic compliance	ANSI HFS 100, ISO 9241-4, and TUVGS		
HP USB Business Slim Sm	artcard Keyboard		
	Keys	104, 105, 109 layout	
Physical Characteristics	Dimensions	(depending upon country 17.34 x 5.68 x 0.78 in (440.6 x 14.45 x 1.98 cm)	
rnysical characteristics	(H x W x D)	17.34 X 3.00 X 0.76 III (440.0 X 14.43 X 1.36 CIII)	
	Weight	1.32 lb (0.6± 0.1 kg)	
	Operating voltage	5V	
	Power consumption	200 mA	
Electrical	System interface	USB Interface	
	ESD	Air 12.5kV / Contact 8kV	
	EMI - RFI	under 3dB	
	Microsoft PC 99 - 2001	Conforms to FCC rules for a Class B computing device	
	Keycaps	Low-profile design	
	Switch actuation	60±15g nominal peak force with tactile feedback	
Mechanical	Switch life	10 million keystrokes (Life tester)	
	Switch type	Contamination-resistant switch membrane	
	Key-leveling mechanisms	For all double-wide and greater-length keys	
	Cable length	6 ft (1.8 m)	
Environmental	Acoustics	43-dBA maximum sound pressure level	
	Operating temperature	50° to 122° F (10° to 50° C)	



	Non-operating temperature	-22° to 140° F (-30° to 6	50° C)	
	Operating humidity	10% to 90% (non-conde		
	Non-operating humidity	20% to 80% (non-condensing at ambient)		
	Operating shock	40 g, six surfaces		
	Non-operating shock	80 g, six surfaces		
	Operating vibration	2-g peak acceleration		
	Non-operating vibration	4-g peak acceleration		
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence		
	Drop (in box)	30 in (76.2 cm) on conc	rete, 16-drop sequence	
	Support	All ISO 7816 smart card	S	
	Interface	Reads from and writes to and microprocessor sm	to all IS07816-1, 2, 3, 4 memory art cards (T=0, T=1)	
	Chipset	IDENTIVE CLOUD 2190 F		
	Standard APIs supported	PC/SC, EMV2000, CT-AF	PI	
	Power	USB Port		
		Short circuit detection (protects smart card and reader)	
SmartCard Function		Power supply complian mA)	t with ISO7816 and EMV (5V, 60	
		Supports 3-V and 5-V cards		
	Power consumption	100-mA maximum draw		
	Communication	From card	9600 bps to 330,000 bps	
		From computer	12 Mbps (USB transfer speed)	
	Landing mechanism	Contact device	Friction contact	
		Card insertions rating	Up to 100,000 insertion cycles	
	Interface modes	CCID protocol		
	Reader performance interface	USB connection		
	Electro-magnetic standards	Europe	2004/108/EC	
		USA	USAFCC part 15	
Approvals	CE Marking; TUV; EAC; FCC; cULus/	/CSAus; ICES; RCM; VCCI; KCC; BSMI		
Ergonomic Compliance	ISO 9241-410, TUV GS			
Kit Contents	Keyboard, I/O Security and Docun	nentation CD, warranty card		
HP USB Business Slim	Keyboard			
	Keys	104, 105, 106, 107, 109	layout (depending upon country)	
Physical characteristics	Dimensions (L × W × H)	171.97 x 68.35 x 8.27 in (436.8± 1.5 x 137.6± 1.0 x 21.0± 1.0 cm)		
	Weight	1.32 lb (0.6± 0.08 kg)		
	Operating voltage	+ 4.4 – 5.25VDC		
Electrical	Power consumption	50-mA maximum (with 5 VDC power supplied and three LEDs ON)		



	System interface	USB Type A plug connector	
	rcp	Contact Discharge: 2, 4,6,8KV	
	ESD	Air Discharge: 2, 4, 8,10,12.5KV	
	EMI - RFI	Conforms to FCC rules for a Class B computing device	
	Microsoft® PC 99 - 2001	Functionally compliant	
	Keycaps	Low-profile design	
	Switch actuation	60±12.5g nominal peak force with tactile feedback	
	Switch life	10 million keystrokes (Life tester)	
Mechanical	Switch type	Contamination-resistant switch membrane	
	Key-leveling mechanisms	For all double-wide and greater-length keys	
	Cable length	6 ft (1.8 m)	
	Microsoft PC 99 - 2001	Mechanically compliant	
	Acoustics	43-dBA maximum sound pressure level	
	Operating temperature	50° to 122° F (10° to 50° C)	
	Non-operating temperature	-22° to 140° F (-30° to 60° C)	
	Operating humidity	10% to 90% (non-condensing at ambient)	
	Non-operating humidity	20% to 80% (non-condensing at ambient)	
Environmental	Operating shock	40 g, six surfaces	
	Non-operating shock	80 g, six surfaces	
	Operating vibration	2-g peak acceleration	
	Non-operating vibration	4-g peak acceleration	
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence	
	Drop (in box)	30 in (76.2 cm) on concrete, 16-drop sequence	
Approvals	UL, FCC, CE Mark, TUV, TUV GS, VCCI, BSMI, C-Tick, KC		
Ergonomic compliance	ANSI HFS 100, ISO 9241-4, and TUVGS		



Kit contents	Keyboard	Installation Guide	
	Warranty Card	Safety and Comfort Guide	
HP PS/2 Business Slim Keyboard			
	Keys	104, 105, 106, 107, 109 layout (depending upon country)	
Physical Characteristics	Dimensions (L x W x H)	171.97 x 68.35 x 8.27 in (436.8± 1.5 x 137.6± 1.0 x 21.0± 1.0 cm)	
	Weight	1.32 lb (600± 80 g)	
	Operating voltage	+ 4.4 – 5.25VDC	
	Power consumption	50-mA maximum (with 5 VDC power supplied and three LEDs ON)	
	System interface	PS/2 6-pin mini din connector	
	ESD	Contact Discharge: 2, 4,6,8KV	
	E30	Air Discharge: 2, 4, 8,10,12.5KV	
	EMI - RFI	Conforms to FCC rules for a Class B computing device	
Electrical	Microsoft PC 99 - 2001	Functionally compliant	
	Keycaps	Low-profile design	
	Switch actuation	60±12.5g nominal peak force with tactile feedback	
	Switch life	10 million keystrokes (Life tester)	
	Switch type	Contamination-resistant switch membrane	
	Key-leveling mechanisms	For all double-wide and greater-length keys	
	Cable length	6 ft (1.8 m)	
	Microsoft PC 99 - 2001	Mechanically compliant	
	Acoustics	43-dBA maximum sound pressure level	
Former	Operating temperature	50° to 122° F (10° to 50° C)	
Environmental	Non-operating temperature	-22° to 140° F (-30° to 60° C)	
	Operating humidity	10% to 90% (non-condensing at ambient)	

Technical Specifications - Input/Output Devices

	Non-operating humidity	20% to 80% (non-condensing at ambient)
	Operating shock	N/A
	Non-operating shock	65 inch 2.9 ms, six surface; 30g 266 inch/second; 50g 266 inch/second six surface
	Operating vibration	2-g peak acceleration
	Non-operating vibration	Starting at 5 Hz, vary the frequency of vibration from 5 to 500 Hz and back to 5 Hz at a Logarithmic sweep rate of 1 octave per minute.
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence
	Drop (in box)	29.93 in (76 cm) on concrete, 16-drop sequence
Approvals	UL, FCC, CE Mark, TUV, TUV GS, VCCI, BSMI, C-Tick, KC	
Ergonomic compliance	ANSI HFS 100, ISO 9241-4, and TUVGS	

HP USB (Grey) Business Slim Keyboard

Physical characteristics	Keys	104, 105, 106, 107, 109 layout (depending upon country)
	Dimensions (L x W x H)	17.19 x 5.41 x 0.82 in (43.68±1.5 x 13.76±1.0 x 2.1 ±1.0 cm)
	Weight	1.32 lb (0.6± 0.08 kg)
Electrical	Operating voltage	+ 4.4 – 5.25VDC
	Power consumption	100-mA maximum (with 5 VDC power supplied and three LEDs ON)
	System interface	USB Type A plug connector
	ESD	Contact Discharge: 4, 6, 8 KV
	EMI – RFI	Air Discharge: 8, 10, 12 KV / 15 KV
	Microsoft PC 99 – 2001	Conforms to FCC rules for a Class B computing device; Functionally compliant
Mechanical	Keycaps	Low-profile design
	Switch actuation	Rubber dome + membrane
	Switch life	10 million
	Switch type	Rubber dome
	Key-leveling mechanisms	Link bar
	Cable length	For all double-wide and greater-length keys
	Microsoft PC 99 – 2001	Yes
Environmental	Acoustics	55-dBA maximum sound pressure level
	Operating temperature	10°C to 50°
	Non-operating temperature	-30°C to 90°
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	60% to 80% (non-condensing at ambient)
	Operating shock	40 g, six surfaces



	Non-operating shock	80 g, six surfaces
	Operating vibration	2-g peak acceleration
	Non-operating vibration 4-g peak acceleration	
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence
	Drop (in box)	30 in (76.2 cm) on concrete, 16-drop sequence
Approvals	FCC; CE; VCCI; BSMI; KC; EAC; RCM; TUV-GS; UL; RoHS; WEEE	
Ergonomic compliance	ANSI HFS 100; ISO 9241-4; and TUVGS	

HP Wireless Business Slim Keyboard and Mouse			
Keyboard	Dimensions (L x W x H)	171.97 x 68.35 x 8.27 in (436.8± 1.5 x 137.6± 1.0 x 21.0± 1.0 cm)	
Reyboard	Weight – Without Two AA Alkaline Batteries	1.23 lb (560± 80 g)	
	Dimensions (H x L x W)	1.46 x 4.53 x 2.47 in (37 x 115 x 62.9 mm)	
Mouse	Weight – Without Two AA Alkaline Batteries	0.15 lb (67 g)	
	Dimensions (H x L x W)	0.33x 1.79 x 0.72 in (8.4 x 45.5 x 18.4 mm)	
Receiver	Weight	0.21 oz (5.9 g)	
Receiver	Cable Length – Minimum	6 ft (1.8 m)	
	Range	32.8 ft (10 m)	
System Requirements	Available USB port for the receiver CD-ROM Drive *This system may require upgraded and/or separately purchased hardware and/or a DVD drive to install the Windows 7 software and take full advantage of Windows 7 functionality. See http://www.microsoft.com/windows/windows-7/ for details.		
	Product Safety	UL; CSA /TUV (Europe only); CE Mark; CB Report	
	Ergonomics	ANSI; ISO (Europe only); GS Mark (Germany only)	
	EMC	FCC; CE; ACA (-tick); BSMI; KC ; VCCI	
	CE Mark	EN 55022:2010; EN 55024; EN 301489-1; EN 61000	
Approvals	Design Guidelines for PCs	PC 99 – connector overmold colors; PC 2001 – full functionality	
	Telecom	All local telecom requirements and approvals for intended markets	
	USA	FCC Title 47 CFR, Par 15, Subpart C; other local requirements	



	Country Support	US, Belgium, Switzerland, Spain, Denmark, Netherlands, France, Germany, Italy, Portugal, Sweden, Norway, Finland, UK, Poland, Czech Republic, Turkey, Greece, Austria, Bulgaria, Cyprus, Estonia, Hungary, Ireland, Latvia, Lithuania, Luxemburg, Malta, Romania, Slovakia, Slovenia, Vietnam, HK, Australia, NZ, Malaysia, Singapore, Indonesia, Philippines, Thailand, Canada, China, Japan, Korea, Taiwan, India, Venezuela, Ecuador, Russia, Ukraine, Israel, Croatia, United Arab Emirates, Peru, Brazil, Chile, Argentina, Mexico, South Africa, and up to 193 countries worldwide.
Environmental	Keyboard contains 25% post-consumer recycled plastic material.	

HP PS/2 Mouse				
Dimensions (H x L x W)	1.46 x 2.48 x 4.53 in (3.70 x 6.	1.46 x 2.48 x 4.53 in (3.70 x 6.29 x 11.50 cm)		
Weight	3.53 oz (100g; +10g/- 5 g)			
	Operating temperature	-32° to 104°F (0° to 40° C)		
	Non-operating temperature	-4° to 140°F (-20° to 60° C)		
	Operating humidity	10% to 90% (non condensing at ambient)		
	Non-operating humidity	10% to 90% (non condensing at ambient)		
Environmental	Operating shock	40 g, 6 surfaces		
	Non-operating shock	80 g, 6 surfaces		
	Operating vibration	2 g peak acceleration		
	Non-operating vibration	4 g peak acceleration		
	Drop (out of box)	80 cm height onto asphalt tile over concrete or equivalent, 5-drop in 5 direction except the cable face		
	Operating voltage	5 VDC ± 10%		
	Power consumption	100mA		
Electrical	System consumption	PS/2 mini-din connector		
Electricat	ESD	CE level 4, 15 kV air discharge		
	EMI-RFI	Conforms to FCC rules for a Class B computing device		
	Microsoft PC99 - 2001	Functionally compliant		
	Resolution	800 DPI		
	Tracking speed	10 in/s (25.4 cm/s) maximum		
Mechanical	Acceleration	±15%		
	Switch actuation	65±20 gf		
	Switch life	3,000,000 operations (using Hasco modified tester)		



	Switch type		Low force micro-switches	
	Tracking mechanisr	n life	80 km	
	Cable length		6 ft (1.8 m)	
	Microsoft PC99 - 20	01	Mechanically compliant	
	Width		6 mm	
	Diameter		22.5 ± 0.2 mm	
C. II beel	Maximum rotation	orce	50 gf-cm	
Scroll wheel	Switch type		Light force micro-switch	
	Switch life		1 million operations	
	Mechanical life		Minimum 200,000 revolutions	
Regulatory Approvals	UL/cUL, FCC, CE Mar	k, TUV/GS, V	CCI, KCC, BSMI, C-Tick	
HP USB 1000dpi La	ser Mouse			
Dimensions (H x L x W)	1.47 x 4.53 x 2.47 ir	า (37.3 x 114	.97 x 62.86 mm)	
Weight	3.360 oz (102g)			
Cable length	70.9 in (180 cm)			
System requirements	Available USB port			
Environmental Operating Tempera		ture	re 32° to 104° F (0° to 40° C)	
	Non-operating Tem	perature	-4° to 140° F (-20° to 60° C)	
Operating Humidity			10% to 90% (non-condensing at ambient)	
Mechanical	Resolution		1000dpi	
	Tracking Speed		45 cm/sec	
	Cable Length		70.9 in (180 cm)	
HP USB PS/2 Washa	able Mouse			
Dimensions (H x L x W)	1.56 x 2.44 x 4.61 in (3.95	5 x 6.21 x 11.	.7 cm)	
Weight	4.44 oz (126 g)	T		
Environmental	Environmental Operating temperature		-32° to 104°F (0° to 40° C) -4° to 140°F (-20° to 60° C)	
	Non-operating temperature	-4° t0 140	FF (-20° t0 60° C)	
	Operating humidity		% (non-condensing at ambient)	
	Non-operating humidity	10% to 90% (non condensing at ambient)		
Operating shock			40 g, 6 surfaces	
	Non-operating shock Operating vibration Non-operating vibration		faces	
			cceleration	
			cceleration	



	Drop (out of box)	80 cm height onto asphalt tile over concrete or equivalent, 5-drop in 5 direction except the cable face
Electrical	Operating voltage	5 VDC ± 10%
	Power consumption	100mA
	System consumption	PS/2 mini-din connector
	ESD	CE level 4, 15 kV air discharge
	EMI-RFI	Conforms to FCC rules for a Class B computing device
	Microsoft® PC99 – 2001	Functionally compliant
Mechanical	Resolution	400 ± 20% DPI
	Tracking speed	10 in/s (25.4 cm/s) maximum
	Acceleration	100 in/s/s (2.54 m/s/s)
	Switch actuation	61 g nominal peak force
	Switch life	3,000,000 operations (using Hasco modified tester)
	Switch type	Low force micro-switches
	Tracking mechanism life	155 mi (250 km) at average speed of 10 in/s
	Cable length	6 ft (1.8 m)
	Microsoft PC99 – 2001	Mechanically compliant
Scroll wheel	Width	8 mm
	Diameter	1.01 in (25.6 mm)
	Maximum rotation speed	48 rats/sec
	Switch type	Light force micro-switch
	Switch life	1 million operations
	Mechanical life	Minimum 200,000 revolutions
Regulatory approvals	Compliant	UL, CSA, FCC, CE Mark, TUV, TUV GS, VCCI, BSMI, C-Tick, MIC

HP USB Hardei	HP USB Hardened Mouse		
Mouse Type	Wired optical mouse		
Interface	USB 2.0		
Dimensions (H x L x W)	114.97 x 62.92 x 37.3 (11.49 x 6.29 x 1.46 i		
Weight	92 g (+/-10 g) (3.2 oz)		
Cable length	1.8 M		
Tracking	X-Y Positioning	X-Y Wheel Resolution	1000 DPI
		Tracking Speed	Up to 30 in/sec in either X or Y direction



	Z Axis Wheel	Z Wheel Revolution	24 counts per revolution	
		Tracking Speed	0 ~ 120 rpm	
Environmental	Operating temperature	0° - 40°C		
	Non-operating temperature	-40° - 65°C		
	Operating humidity	90%		
	Agency Approvals	CE FCC RCM VCCI EMC EAC BSMI UL ICES-003 Cla KCC TUV/GS		
Electrical	Input Voltage & Current	4.4 ~ 5.25 VDC / 100 mA		
	Power Consumption		nal 5 VDC power supplied, max current consumption is 100mAg speed up to 30 in/sec	
Color	Black			
System requirements	Windows 10, Windows 8.	1 32/64bit, Wi	ndows 7 32/64bit	

HP Grey V2 Mouse			
Dimensions (H x L x W)	1.46 x 4.53 x 2.48 in (3.72 x 11	1.46 x 4.53 x 2.48 in (3.72 x 11.5 x 6.29 cm) ±1 mm	
Weight	3.53 oz (100g; +10g/- 5 g)	3.53 oz (100g; +10g/- 5 g)	
	Operating temperature	50° to 122°F (10° to 50° C)	
	Non-operating temperature	-22° to 140°F (-30° to 60° C)	
Environmental	Operating humidity	10% to 90% (non condensing at ambient)	
	Non-operating humidity	20% to 80% (non condensing at ambient)	
	Operating shock	40 g, 6 surfaces	
	Non-operating shock	80 g, 6 surfaces	
	Operating vibration	2 g peak acceleration	
	Non-operating vibration	4 g peak acceleration	
	Operating voltage	4.75~5.25 Vdc	
Electrical	Power consumption (typical)	10mA	
Mechanical	Connector	USB 2.0	



	Туре	3D mouse (3 keys and wheel)	
	Resolution	800 DPI	
	Sensor	PixArt vendor Optical USB mouse sensor. DIP	
	Tracking speed	30 inch/sec (max)	
	Tracking acceleration	8G(max), 1G=9.8m/s2	
	Cable length	6 ft (1.8 m)	
Color	Grey	Grey	
Regulatory Approvals	FCC, CE, ICES, C-TICK, VCCI, KCC, BSMI, IS09241, Part 4, Computer Work Station Ergonomics compliance, IEC 801-2, IEC 1000-4-2, EN 55024:1998 + A1:2001 + A2:2003, European Standard EN 55022: 2006 Class B, CE Mark		

HP USB Mouse				
Dimensions (H x L x W)	2.5 x 4.5 x 1.5 in (63.5	2.5 x 4.5 x 1.5 in (63.5 x 114.3 x 38.1 mm)		
Weight	0.22 lb (99.79 g)	0.22 lb (99.79 g)		
Color	Black	Black		
Connector	USB	USB		
Mechanical	Resolution	800 DPI sensitivity		
	Buttons	Two primary buttons and clickable scroll wheel		

Technical Specifications – Miscellaneous Features

MISCELLANEOUS FEATURES

Management Features

- Advanced Configuration and Power Management Interface (ACPI). Allows the system to wake from a low power mode.
 Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system.
- Intel® Wired for Management support; industry wide initiative to make Intel® architecture based PCs, servers and mobile computers more inherently manageable out-of-the-box and over the network
- Dual State Power Button; acts as both an on/off button and a suspend-to-sleep button

Serviceability Features

- Dual colored power LED on front of computer to indicate either normal or fault condition
- Diagnostic LED Explanation Table:
 - Power LED will blink red 2 to 5 times, then blink white 2 or more times, then repeat (with beep tones for each blink initially):
 - 2 red + 2 white User must provide file for BIOS recovery (USB storage, typically)
 - 2 red + 3 white User must enter a key sequence to proceed with recovery by policy
 - 2 red + 4 white BIOS recovery is in progress
 - 3 red + 2 white Memory could not be initialized
 - 3 red + 3 white Graphics adapter could not be found
 - 3 red + 4 white Power supply failure / not connected
 - 3 red + 5 white Processor not installed
 - 3 red + 6 white Current processor does not support an enabled feature
 - 4 red + 2 white Processor has exceeded its temperature threshold / system thermal shutdown
 - 4 red + 3 white System internal temperature has exceeded its threshold
 - 5 red + 2 white System controller firmware is not valid
 - 5 red + 3 white System controller detected BIOS is not executing
 - 5 red + 4 white BIOS could not complete initialization / PCA failure
 - 5 red + 5 white System controller rebooted the system after a health or recovery timer triggered
- HP PC Hardware Diagnostics UEFI:
 - This utility enables hardware level testing outside the operating system on many components. The diagnostics can be invoked by pressing F2 at POST, and is available as a download from HP Support
- System/Emergency ROM
- Flash ROM
- CMOS Battery Holder for easy replacement
- BIOS recovery files are maintained on the local OS drive when updating with HP BIOS Update and Recovery utility (HPBIOSUPDREC) 5 Aux Power LED on System PCA
- Processor ZIF Socket for easy Upgrade
- Over-Temp Warning on Screen (Requires IM Agents)
- Clear Password Jumper
- DIMM Connectors for easy Upgrade
- Clear CMOS Button
- NIC LEDs (integrated) (Green & Amber)
- Dual Color Power and HD LED To Indicate Normal Operations and Fault Conditions
- Color coordinated cables and connectors
- Tool-less Hood Removal
- Front power switch
- System memory can be upgraded without removing the system board or any internal components
- Tool-less Hard Drive, CD & Diskette Removal
- Green Pull Tabs, and Quick Release Latches for easy Identification



Technical Specifications – Environmental

Δd	diti	nnal	Fea	tures
MU	ulli	viial	гса	LUI ES

Description

Towerable Orientation

Product can be oriented as either a desktop (horizontal) or a tower (vertical)

Drive Lock

Implementation of the industry standard ATA Security feature set. When enabled, it prevents software access to user data on the drive until one or two user-defined

passwords are provided.

Boot Sectors Protection

Drive Protection System

MBR or GPT boot sectors of the hard drive are critical to securely starting the operating system. By saving the MBR or GPT data (depending on the how the OS was installed), the BIOS will be able to monitor for changes and allow the user to override them with the backup copy at boot-up.

DPS Access through F10 Setup during Boot

A diagnostic hard drive self-test. It scans critical physical components and every sector of the hard drive for physical faults and then reports any faults to the user Running independently of the operating system, it can be accessed through a Windows-based diagnostics utility or through the computer's setup procedure. It produces an evaluation on whether the hard drive is the source of the problem and

needs to be replaced

The system expands on the Self-Monitoring, Analysis, and Reporting Technology (SMART), a continuously running systems diagnostic that alerts the user to certain

types of failures

SMART Technology (Self-Monitoring, Analysis and Reporting Technology) Allows hard drives to monitor their own health and to raise flags if imminent failures were predicted

Predicts failures before they occur. Tracks fault prediction and failure indication parameters such as re-allocated sector count, spin retry count, calibration retry count

SMART II - Off-Line Data Collection

SMART I - Drive Failure Prediction

By avoiding actual hard drive failures, SMART hard drives act as "insurance" against unplanned user downtime and potential data loss from hard drive failure

SMART III - Off-Line Read Scanning with

Defect Position

Defect Reallocation

IOEDC: I/O Error Detection Circuitry

Detects errors in Read/Write buffers on HDD cache RAM

SMART IV - End-to-End CRC for hard

drives

Interface in F10 setup provides confirmation of SMART IV support.



After-Market Options (availability may vary by region)

After Market Options

Business Monitors (sample list)*	SFF/MT	<u>DM</u>	Part Number
HP ProDisplay P240va 23.8-inch Monitor	Х	Х	N3H14AA
HP ProDisplay P232 23-inch Monitor	Х	Х	K7X31AA
HP ProDisplay P222c 21.5-inch Video Conferencing Monitor	Х	Х	L4J08AA
*Additional models are available.			
Communication Devices	SFF/MT	<u>DM</u>	Part Number
Intel® Ethernet I210 - T1 Gbe NIC	Х		E0X95AA
Intel® 7265 802.11ac 2x2 DualBand Combo PCIe x1 Card	X		N4G85AA
Graphics Solutions	SFF/MT	<u>DM</u>	Part Number
NVIDIA® GeForce® GT 730 2GB DP PCIe x8 Card	X		Z9H51AA
NVIDIA® GeForce® GT 730 1GB HDMI PCIe x8 Card	X		
AMD® Radeon™ R7 450 4GB PCIe x16 Card	MT Only		Z9H52AA
HP UHD USB Graphics Adapter	Х	Х	N2U81AA
HP DisplayPort™ Cable Kit	Х	Х	VN567AA
HP DisplayPort™ To DVI-D Adapter	Х	Х	FH973AA
HP DisplayPort™ To VGA Adapter	Х	Х	AS615AA
HP DisplayPort™ To HDMI 4k Adapter	Х	Х	K2K92AA
HP DVI to DVI Cable	Х	Х	DC198A
HP (Bulk) 700mm DisplayPort™ Cable Kit		Х	V8Y77A6
HP USB-C to VGA Adapter (when Type-C Port is installed)	Х	Х	N9K76AA
HP USB-C to HDMI Adapter (when Type-C Port is installed)	Х	Х	N9K77AA
HP USB-C to DisplayPort™ Adapter (when Type-C Port is installed)	X	Х	N9K78AA
Data Storage Drives	SFF/MT	<u>DM</u>	Part Number
HP 500GB 7200PRM SATA 6.0Gb/s 3.5" Hard Drive	Х		QK554AA
HP 1TB 7200rpm SATA 6Gb/s 3.5" Hard Drive	Х		QK555AA
HP 256GB SATA TLC Solid State Drive	Х	Х	P1N68AA
HP 512GB Turbo Drive G2 TLC M.2 SSD Drive	Х	Х	X8U75AA
HP 9.5mm Slim Removable SATA 500GB	Х		T7G14AA
HP 256GB SATA Non-SED Solid State Drive	Х	Х	W0U55AA
HP 9.5mm G3 800/600 Tower DVD Writer	MT Only		1CA52AA
HP 9.5mm G3 8/4 SFF G4 400 SFF/MT DVD Writer	SFF Only		1CA53AA
Input Devices	SFF/MT	DM	Part Number
•			K8P74AA
HP Conferencing Keyboard HP USB Business Slim Keyboard	X	X	N3R87AA



After-Market Options (availability may vary by region)

HP PS/2 Business Slim Keyboard	Х		N3R86AA
HP Wireless Business Slim Keyboard and Mouse**	Х	Х	QY449AA
HP USB Business Slim Grey Keyboard (EMEA only)	Х	Х	Z9H49AA
HP USB Business Slim Smart Card CCID Keyboard	Х	Х	Z9H48AA
HP USB PS/2 Washable Keyboard and Mouse Kit**	Х	Х	BU207AA
HP USB Grey V2 Mouse (EMEA only)	Х	Х	Z9H74AA
HP USB Business Slim Keyboard and Mouse (China Only)	Х	Х	Z9H50AA
HP USB Hardened Mouse	Х	Х	P1N77AA
HP PS/2 Mouse	Х		QY775AA
HP USB Mouse	X	Х	QY777AA
HP USB 1000dpi Laser Mouse	X	Х	QY778AA
** Keyboard contains 25% post-consumer recycled plastic material			
Desktop Mini Accessories	SFF/MT	<u>DM</u>	Part Number
HP Desktop Mini DVD Super Multi-Writer ODD Expansion Module		Х	K9Q83AA
HP Desktop Mini 500GB HDD/ I/O Expansion Module		Х	K9Q82AA
HP Desktop Mini Rack Mount Tray Kit		Х	G1K21AA
HP Desktop Mini Security/Dual VESA Sleeve		Х	G1K22AA
HP Desktop Mini 65W Power Supply Kit		Х	L2X04AA
HP Desktop Mini 90W Power Supply Kit		Х	L4R65AA
HP Desktop Mini Vertical Chassis Stand		Х	G1K23AA
HP Desktop Mini Lock Box		Х	P1N78AA
HP Desktop Mini Port Cover Kit		Х	P3R65AA
HP Desktop Mini I/O Expansion Module		Х	K9Q84AA
HP Integrated Work Center Desktop Mini/Thin Clients		Х	G1V61AA
HP Single Monitor Arm		Х	BT861AA
HP Quick Release Bracket		Х	EM870AA
Constant Maria and	SFF/MT	DM	Part Number
System Memory		<u> </u>	
HP 4GB DDR4-2400 DIMM	X		Z9H59AA
HP 8GB DDR4-2400 DIMM	X		Z9H60AA
HP 16GB DDR4-2400 DIMM	X		Z9H57AA
HP 4GB DDR4-2400 SODIMM		Х	Z9H55AA
HP 8GB DDR4-2400 SODIMM		Х	Z9H56AA
HP 16GB DDR4-2400 SODIMM		Х	Z9H53AA



After-Market Options (availability may vary by region)

Multimedia Devices	SFF/MT	<u>DM</u>	Part Number
HP Business Headset v2	Х	Х	T4E61AA
HP USB Business Speakers v2	X	Х	N3R89AA
Security Devices	SFF/MT	<u>DM</u>	Part Number
HP 600 G3 SFF Solenoid Lock and Hood Sensor	SFF only		1CA50AA
HP 600 G3 MT Solenoid Lock and Hood Sensor	MT only		J6L42AA
HP Business PC Security Lock v2 Kit	X		N3R93AA
HP Keyed Cable Lock 10mm Kit	X	Х	T1A62AA
HP Dual Head Keyed Cable Lock Kit	X	Х	T1A64AA
Stands and Accessories	SFF/MT	DM	Part Number
HP (10 Set) 600/800 G3 Tower Bezel Support Kit	Tower only		Z9H63A6
HP (10) 400 G4 600/800 G3 SFF G4 MT Bezel Support Kit	SFF only		Z9H64A6
HP Single Monitor Arm	X	Х	BT861AA
LANDESK Software (e-delivery)	SFF/MT	<u>DM</u>	Part Number
Contact your HP representative for available options.			N/A

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Change Log

Date of change:	Version History:		Description of change:
January 25,	Version 1 to 2	Launch	QS launched
2017			
February 8,	Version 2 to 3	Update	Weights & Dimensions Section: Chassis (W x H x D) Not including bezel MT
2017			inches value
February 13,	Version 3 to 4	Update	Graphics Section updated
2017			
February 27,	Version 4 to 5	Update	Bays section updated (5.25" Half Height text updated, footnote added)
2017			
March 2, 2017	Version 5	Update	Accessories section updated (accessory added), Environmental section
			updated

